SLAS626C – OCTOBER 2008 – REVISED MARCH 2011

- **Low Supply-Voltage Range: 1.8 V to 3.6 V**
- **Ultralow Power Consumption**
  - **Active Mode: 350 μA at 1 MHz, 2.2 V**
  - **Standby Mode: 1.1 μA**
  - **Off Mode (RAM Retention): 0.2 μA**
- **Five Power-Saving Modes**
- **Wake-Up From Standby Mode in Less Than 6 μs**
- **16-Bit RISC Architecture, 62.5-ns Instruction Cycle Time**
- **Three-Channel Internal DMA**
- **Three, Six or Seven 16-Bit Sigma-Delta Analog-to-Digital (A/D) Converters With Differential PGA Inputs**
- **16-Bit Timer_B With Three Capture/Compare-With-Shadow Registers**
- **16-Bit Timer_A With Three Capture/Compare Registers**
- **On-Chip Comparator**
- **Four Universal Serial Communication Interface (USCI) Modules**
  - **USCI_A0 and USCI_A1**
    - **Enhanced UART Supporting Auto-Baudrate Detection**
    - **IrDA Encoder and Decoder**
    - **Synchronous SPI**
  - **USCI_B0 and USCI_B1**
    - **I2C**
    - **Synchronous SPI**
- **Integrated LCD Driver With Contrast Control for Up to 160 Segments**
- **Basic Timer With Real-Time Clock Feature**
- **32-Bit Hardware Multiplier**
- **Brownout Detector**
- **Supply Voltage Supervisor/Monitor With Programmable Level Detection**
- **Serial Onboard Programming, No External Programming Voltage Needed Programmable Code Protection by Security Fuse**
- **Bootstrap Loader**
- **On-Chip Emulation Module**
- **Family Members Include**
  - **MSP430F47163: 92KB Flash, 4KB RAM, 3 Sigma-Delta ADCs**
  - **MSP430F47173: 92KB Flash, 8KB RAM, 3 Sigma-Delta ADCs**
  - **MSP430F47183: 116KB Flash, 8KB RAM, 3 Sigma-Delta ADCs**
  - **MSP430F47193: 120KB Flash, 4KB RAM, 3 Sigma-Delta ADCs**
  - **MSP430F47126: 56KB Flash, 4KB RAM, 6 Sigma-Delta ADCs**
  - **MSP430F47166: 92KB Flash, 4KB RAM, 6 Sigma-Delta ADCs**
  - **MSP430F47176: 92KB Flash, 8KB RAM, 6 Sigma-Delta ADCs**
  - **MSP430F47186: 116KB Flash, 8KB RAM, 6 Sigma-Delta ADCs**
  - **MSP430F47196: 120KB Flash, 4KB RAM, 6 Sigma-Delta ADCs**
  - **MSP430F47127: 56KB Flash, 4KB RAM, 7 Sigma-Delta ADCs**
  - **MSP430F47167: 92KB Flash, 4KB RAM, 7 Sigma-Delta ADCs**
  - **MSP430F47177: 92KB Flash, 8KB RAM, 7 Sigma-Delta ADCs**
  - **MSP430F47187: 116KB Flash, 8KB RAM, 7 Sigma-Delta ADCs**
  - **MSP430F47197: 120KB Flash, 4KB RAM, 7 Sigma-Delta ADCs**
- **Available in a 100-Pin Plastic Quad Flatpack (QFP) Package**
- **For Complete Module Descriptions, See the *MSP430x4xx Family User's Guide*, Literature Number SLAU056**
- **For E-Meter Reference Design and Software, See *Implementation of a Three-Phase Electronic Watt-Hour Meter using the MSP430F471xx*, Literature Number SLAA409**

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications. These devices have limited built-in ESD protection.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

description

The Texas Instruments MSP430 family of ultralow-power microcontrollers consists of several devices featuring different sets of peripherals targeted for various applications. The architecture, combined with five low-power modes, is optimized to achieve extended battery life in portable measurement applications. The devices feature a powerful 16-bit RISC CPU, 16-bit registers, and constant generators that contribute to maximum code efficiency. The digitally controlled oscillator (DCO) allows wake-up from low-power modes to active mode in less than 6μs.

The MSP430F471xx series are microcontroller configurations targeted to single-phase and poly-phase electricity meters with three, six, or seven 16-bit sigma-delta A/D converters. Each channel has a differential input pair and programmable input gain. Also integrated are two 16-bit timers, four universal serial communication interfaces (USCI), DMA, 68 I/O pins, and a liquid crystal driver (LCD) with integrated contrast control.

AVAILABLE OPTIONS[†]

T_A	PACKAGED DEVICES[‡]
	PLASTIC 100-PIN QFP (PZ)
–40°C to 85°C	MSP430F47127IPZ MSP430F47167IPZ MSP430F47177IPZ MSP430F47187IPZ MSP430F47197IPZ
	MSP430F47126IPZ MSP430F47166IPZ MSP430F47176IPZ MSP430F47186IPZ MSP430F47196IPZ
	MSP430F47163IPZ MSP430F47173IPZ MSP430F47183IPZ MSP430F47193IPZ

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

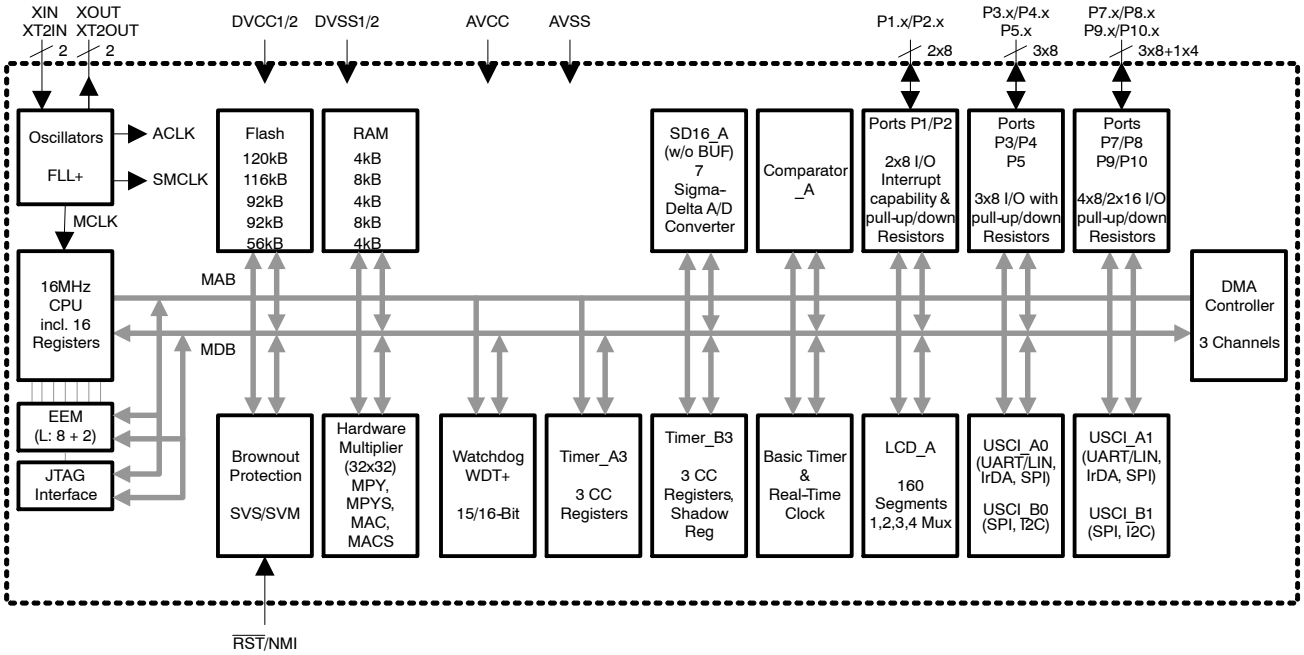
‡ Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

DEVELOPMENT TOOL SUPPORT

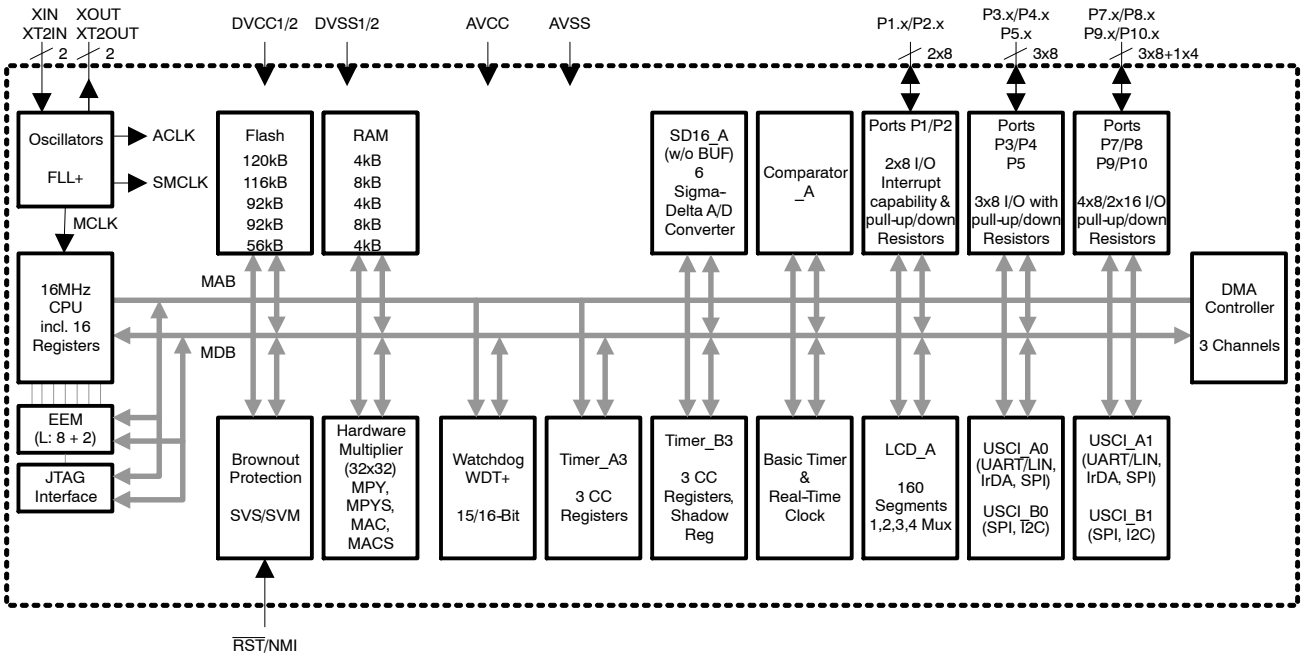
All MSP430 microcontrollers include an Embedded Emulation Module (EEM) allowing advanced debugging and programming through easy to use development tools. Recommended hardware options include the following:

- Debugging and Programming Interface
  - MSP-FET430UIF (USB)
  - MSP-FET430PIF (Parallel Port)
- Debugging and Programming Interface with Target Board
  - MSP-FET430U100
- Stand-Alone Target Board
  - MSP-TS430PZ100
- Production Programmer
  - MSP-GANG430

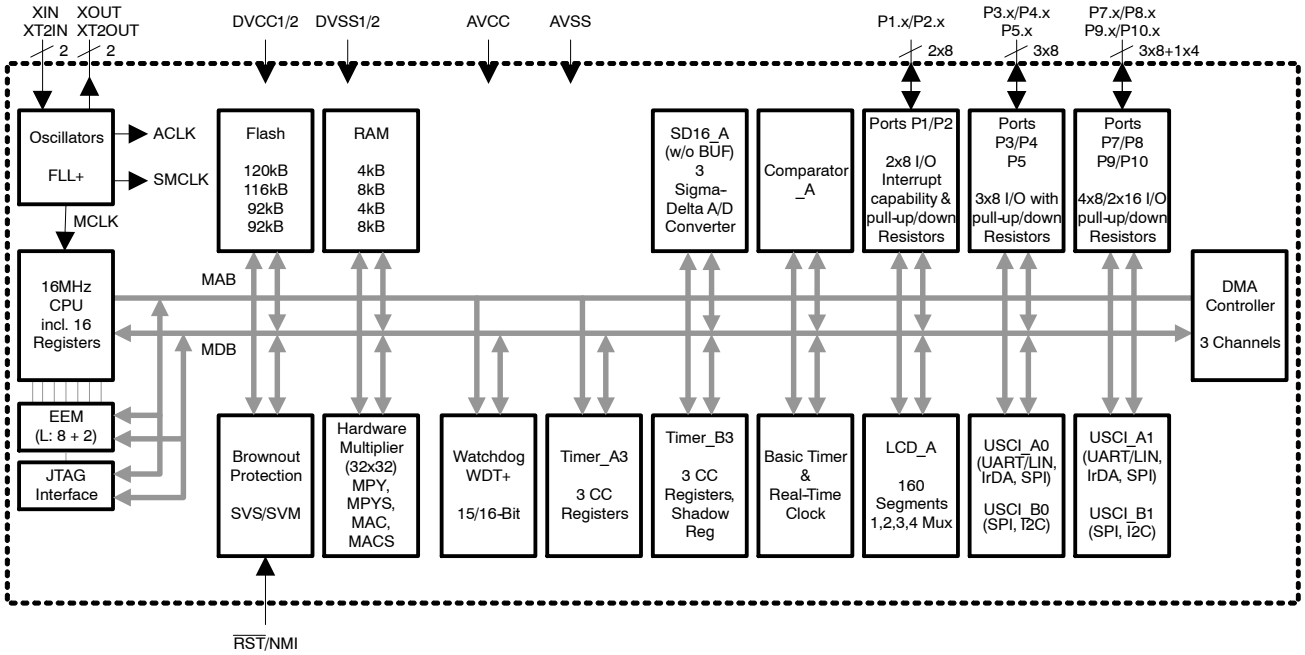
functional block diagram, MSP430F471x7



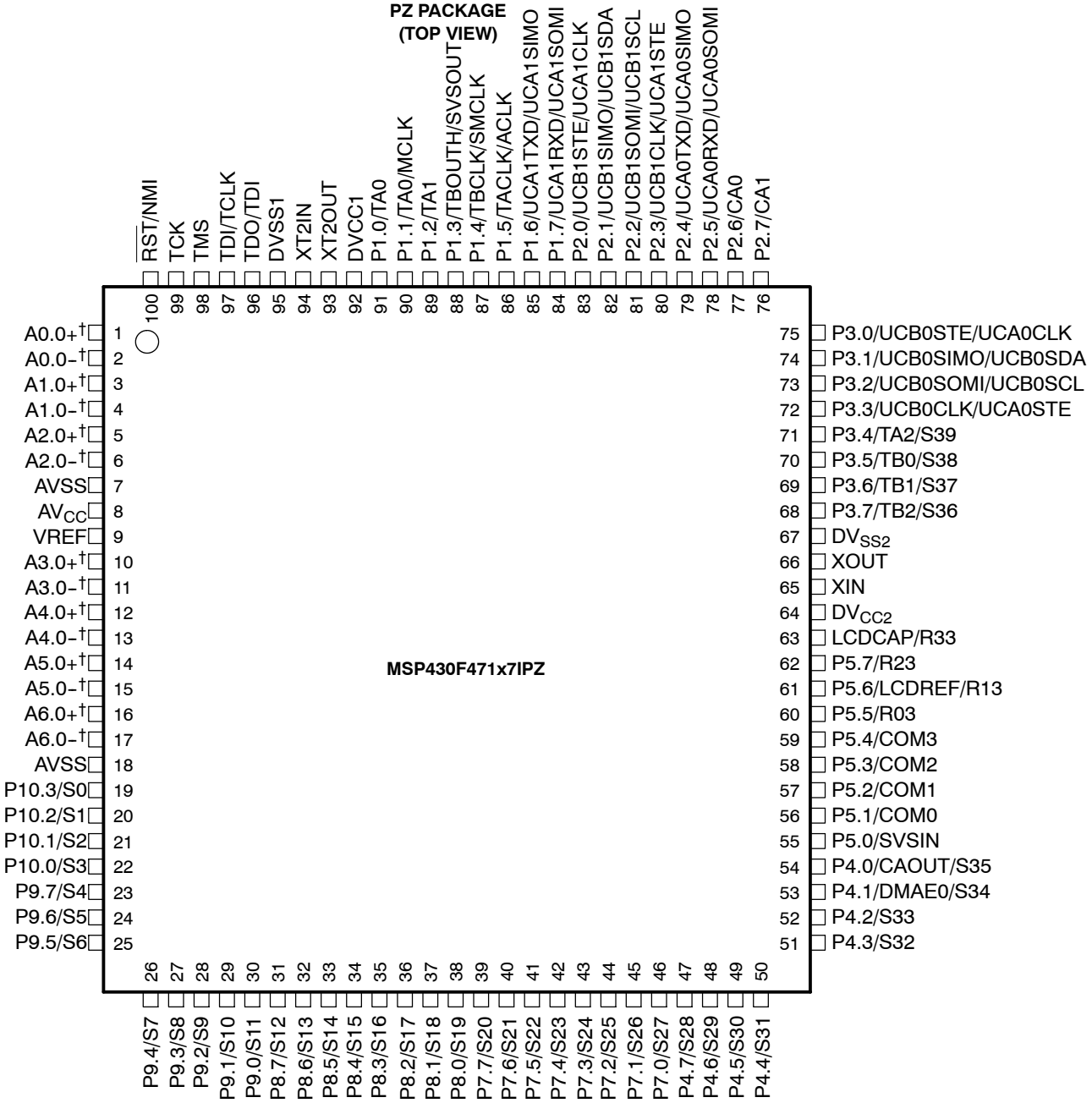
functional block diagram, MSP430F471x6



functional block diagram, MSP430F471x3

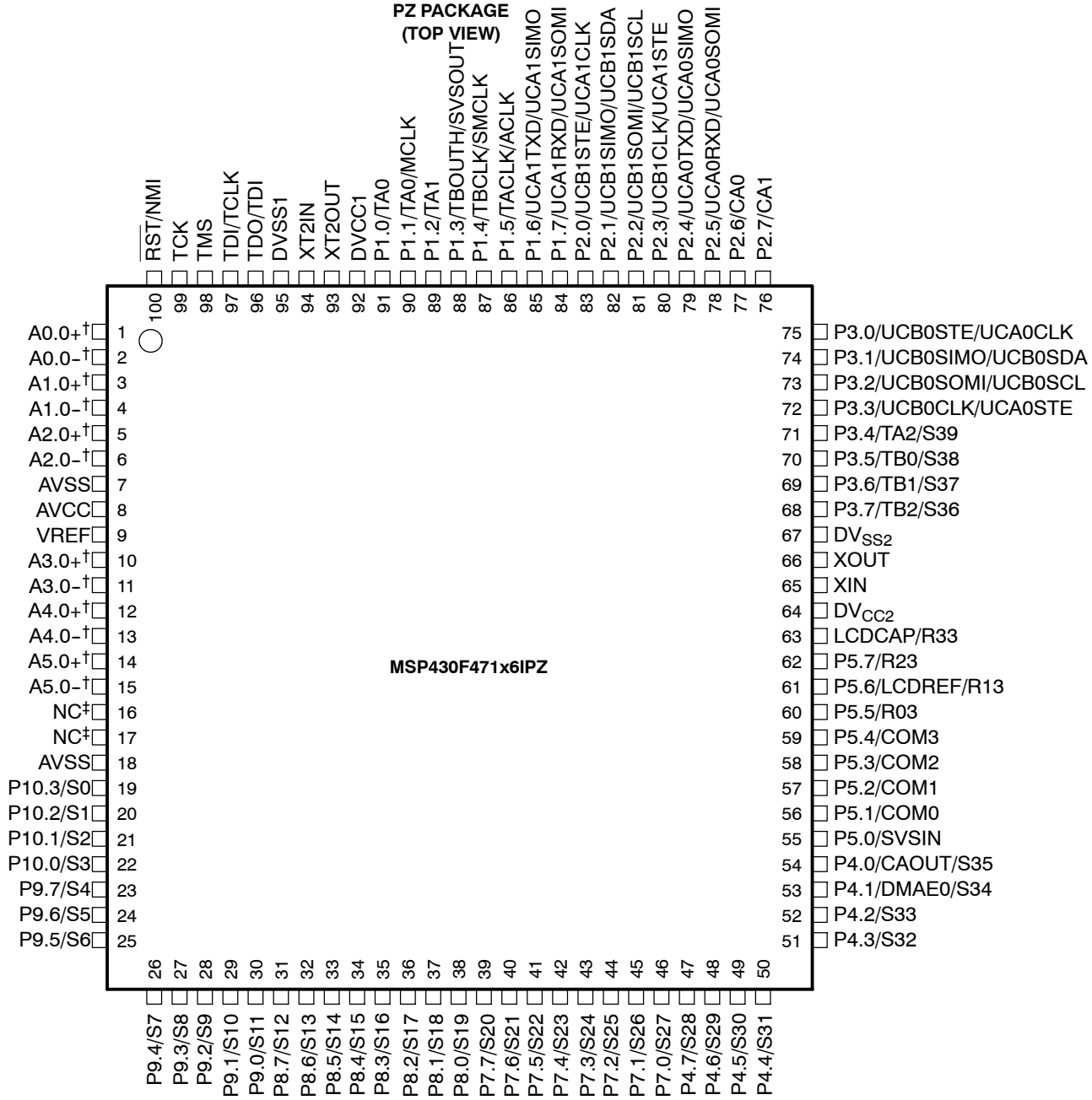


pin designation, MSP430F471x7IPZ



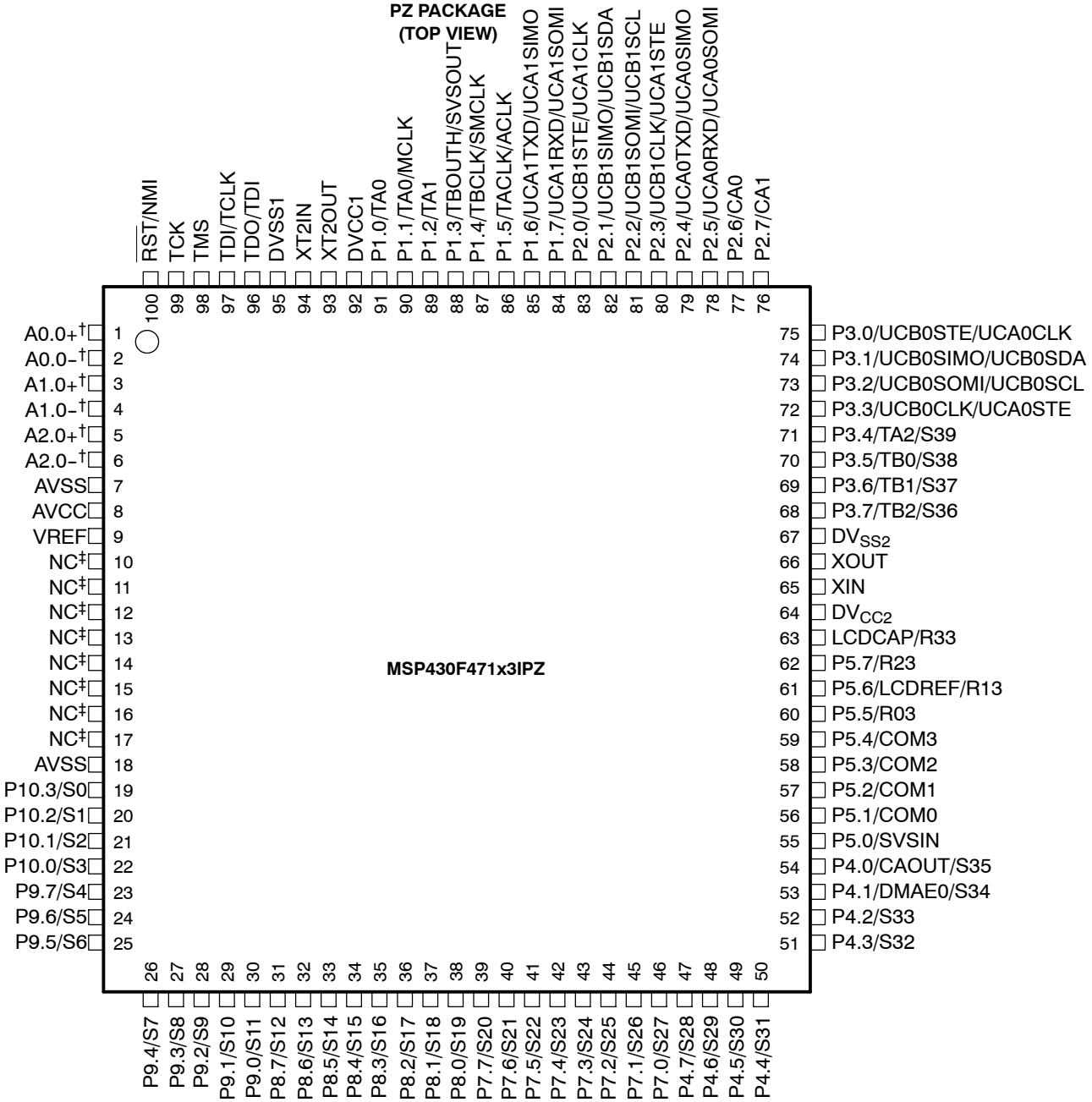
† It is recommended to short unused analog input pairs and connect them to analog ground (AVSS).

pin designation, MSP430F471x6IPZ



† It is recommended to short unused analog input pairs and connect them to analog ground (AVSS).
‡ Connect pin to analog ground (AVSS).

pin designation, MSP430F471x3IPZ



† It is recommended to short unused analog input pairs and connect them to analog ground (AVSS).
‡ Connect pin to analog ground (AVSS).

Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
A0.0+	1	I	SD16_A positive analog input A0.0 (see Note 1)
A0.0–	2	I	SD16_A negative analog input A0.0 (see Note 1)
A1.0+	3	I	SD16_A positive analog input A1.0 (see Note 1)
A1.0–	4	I	SD16_A negative analog input A1.0 (see Note 1)
A2.0+	5	I	SD16_A positive analog input A2.0 (see Note 1)
A2.0–	6	I	SD16_A negative analog input A2.0 (see Note 1)
AV_{SS}	7		Analog supply voltage, negative terminal.
AV_{CC}	8		Analog supply voltage, positive terminal. Must not power up prior to DV_{CC1}/DV_{CC2}.
V_{REF}	9	I/O	Input for an external reference voltage / internal reference voltage output (can be used as mid-voltage)
A3.0+ (MSP430F471x6/7 only)	10	I	SD16_A positive analog input A3.0 (see Note 1) – Not connected in MSP430F471x3, connect pin to analog ground (AVSS).
A3.0– (MSP430F471x6/7 only)	11	I	SD16_A negative analog input A3.0 (see Note 1) – Not connected in MSP430F471x3, connect pin to analog ground (AVSS).
A4.0+ (MSP430F471x6/7 only)	12	I	SD16_A positive analog input A4.0 (see Note 1) – Not connected in MSP430F471x3, connect pin to analog ground (AVSS).
A4.0– (MSP430F471x6/7 only)	13	I	SD16_A negative analog input A4.0 (see Note 1) – Not connected in MSP430F471x3, connect pin to analog ground (AVSS).
A5.0+ (MSP430F471x6/7 only)	14	I	SD16_A positive analog input A5.0 (see Note 1) – Not connected in MSP430F471x3, connect pin to analog ground (AVSS).
A5.0– (MSP430F471x6/7 only)	15	I	SD16_A negative analog input A5.0 (see Note 1) – Not connected in MSP430F471x3, connect pin to analog ground (AVSS).
A6.0+ (MSP430F471x7 only)	16	I	SD16_A positive analog input A6.0 (see Note 1) – Not connected in MSP430F471x6, connect pin to analog ground (AVSS).
A6.0– (MSP430F471x7 only)	17	I	SD16_A negative analog input A6.0 (see Note 1) – Not connected in MSP430F471x6, connect pin to analog ground (AVSS).
AV_{SS}	18		Analog supply voltage, negative terminal.
P10.3/S0	19	I/O	General-purpose digital I/O / LCD segment output 0
P10.2/S1	20	I/O	General-purpose digital I/O / LCD segment output 1
P10.1/S2	21	I/O	General-purpose digital I/O / LCD segment output 2
P10.0/S3	22	I/O	General-purpose digital I/O / LCD segment output 3
P9.7/S4	23	I/O	General-purpose digital I/O / LCD segment output 4
P9.6/S5	24	I/O	General-purpose digital I/O / LCD segment output 5
P9.5/S6	25	I/O	General-purpose digital I/O / LCD segment output 6
P9.4/S7	26	I/O	General-purpose digital I/O / LCD segment output 7
P9.3/S8	27	I/O	General-purpose digital I/O / LCD segment output 8
P9.2/S9	28	I/O	General-purpose digital I/O / LCD segment output 9
P9.1/S10	29	I/O	General-purpose digital I/O / LCD segment output 10
P9.0/S11	30	I/O	General-purpose digital I/O / LCD segment output 11
P8.7/S12	31	I/O	General-purpose digital I/O / LCD segment output 12
P8.6/S13	32	I/O	General-purpose digital I/O / LCD segment output 13
P8.5/S14	33	I/O	General-purpose digital I/O / LCD segment output 14
P8.4/S15	34	I/O	General-purpose digital I/O / LCD segment output 15
P8.3/S16	35	I/O	General-purpose digital I/O / LCD segment output 16
P8.2/S17	36	I/O	General-purpose digital I/O / LCD segment output 17
P8.1/S18	37	I/O	General-purpose digital I/O / LCD segment output 18

NOTES: 1. It is recommended to short unused analog input pairs and connect them to analog ground.

Terminal Functions (continued)

TERMINAL NAME	TERMINAL NO.	I/O	DESCRIPTION
P8.0/S19	38	I/O	General-purpose digital I/O / LCD segment output 19
P7.7/S20	39	I/O	General-purpose digital I/O / LCD segment output 20
P7.6/S21	40	I/O	General-purpose digital I/O / LCD segment output 21
P7.5/S22	41	I/O	General-purpose digital I/O / LCD segment output 22
P7.4/S23	42	I/O	General-purpose digital I/O / LCD segment output 23
P7.3/S24	43	I/O	General-purpose digital I/O / LCD segment output 24
P7.2/S25	44	I/O	General-purpose digital I/O / LCD segment output 25
P7.1/S26	45	I/O	General-purpose digital I/O / LCD segment output 26
P7.0/S27	46	I/O	General-purpose digital I/O / LCD segment output 27
P4.7/S28	47	I/O	General-purpose digital I/O / LCD segment output 28
P4.6/S29	48	I/O	General-purpose digital I/O / LCD segment output 29
P4.5/S30	49	I/O	General-purpose digital I/O / LCD segment output 30
P4.4/S31	50	I/O	General-purpose digital I/O / LCD segment output 31
P4.3/S32	51	I/O	General-purpose digital I/O / LCD segment output 32
P4.2/S33	52	I/O	General-purpose digital I/O / LCD segment output 33
P4.1/DMAE0/S34	53	I/O	General-purpose digital I/O / DMA Channel 0 external trigger / LCD segment output 34
P4.0/CAOUT/S35	54	I/O	General-purpose digital I/O / Comparator_A output / LCD segment output 35
P5.0/SVSIN	55	I/O	General-purpose digital I/O / analog input to supply voltage supervisor
P5.1/COM0	56	I/O	General-purpose digital I/O / common output, COM0–3 are used for LCD backplanes.
P5.2/COM1	57	I/O	General-purpose digital I/O / common output, COM0–3 are used for LCD backplanes.
P5.3/COM2	58	I/O	General-purpose digital I/O / common output, COM0–3 are used for LCD backplanes.
P5.4/COM3	59	I/O	General-purpose digital I/O / common output, COM0–3 are used for LCD backplanes.
P5.5/R03	60	I/O	General-purpose digital I/O / Input port of lowest analog LCD level (V5)
P5.6/LCDREF/R13	61	I/O	General-purpose digital I/O / External reference voltage input for regulated LCD voltage / Input port of third most positive analog LCD level (V4 or V3)
P5.7/R23	62	I/O	General-purpose digital I/O / Input port of second most positive analog LCD level (V2)
LCDCAP/R33	63	I	LCD Capacitor connection / Input/output port of most positive analog LCD level (V1)
DV_{CC2}	64		Digital supply voltage, positive terminal.
XIN	65	I	Input port for crystal oscillator XT1. Standard or watch crystals can be connected.
XOUT	66	O	Output terminal of crystal oscillator XT1
DV_{SS2}	67		Digital supply voltage, negative terminal.
P3.7/TB2/S36	68	I/O	General-purpose digital I/O / Timer_B3 CCR2. Capture: CCI2A/CCI2B input, compare: Out2 output / LCD segment output 36
P3.6/TB1/S37	69	I/O	General-purpose digital I/O / Timer_B3 CCR1. Capture: CCI1A/CCI1B input, compare: Out1 output / LCD segment output 37
P3.5/TB0/S38	70	I/O	General-purpose digital I/O / Timer_B3 CCR0. Capture: CCI0A/CCI0B input, compare: Out0 output / LCD segment output 38
P3.4/TA2/S39	71	I/O	General-purpose digital I/O / Timer_A Capture: CCI2A input, compare: Out2 output / LCD segment output 39
P3.3/ UCB0CLK/UCA0STE	72	I/O	General-purpose digital I/O / USCI_B0 clock input/output / USCI_A0 slave transmit enable
P3.2/ UCB0SOMI/UCB0SCL	73	I/O	General-purpose digital I/O / USCI_B0 slave out/master in in SPI mode, SCL I^2C clock in I^2C mode
P3.1/ UCB0SIMO/UCB0SDA	74	I/O	General-purpose digital I/O / USCI_B0 slave in/master out in SPI mode, SDA I^2C data in I^2C mode

Terminal Functions (continued)

TERMINAL NAME	TERMINAL NO.	I/O	DESCRIPTION
P3.0/ UCB0STE/UCA0CLK	75	I/O	General-purpose digital I/O / USCI_B0 slave transmit enable / USCI_A0 clock input/output
P2.7/CA1	76	I/O	General-purpose digital I/O / Comparator_A input
P2.6/CA0	77	I/O	General-purpose digital I/O / Comparator_A input
P2.5/ UCA0RXD/UCA0SOMI	78	I/O	General-purpose digital I/O / USCI_A0 receive data input in UART mode, slave out/master in in SPI mode
P2.4/ UCA0TXD/UCA0SIMO	79	I/O	General-purpose digital I/O / USCI_A0 transmit data output in UART mode, slave in/master out in SPI mode
P2.3/ UCB1CLK/UCA1STE	80	I/O	General-purpose digital I/O / USCI_B1 clock input/output / USCI_A1 slave transmit enable
P2.2/ UCB1SOMI/UCB1SCL	81	I/O	General-purpose digital I/O / USCI_B1 slave out/master in in SPI mode, SCL I^2C clock in I^2C mode
P2.1/ UCB1SIMO/UCB1SDA	82	I/O	General-purpose digital I/O / USCI_B1 slave in/master out in SPI mode, SDA I^2C data in I^2C mode
P2.0/ UCB1STE/UCA1CLK	83	I/O	General-purpose digital I/O / USCI_B1 slave transmit enable / USCI_A1 clock input/output
P1.7/ UCA1RXD/UCA1SOMI	84	I/O	General-purpose digital I/O / USCI_A1 receive data input in UART mode, slave out/master in in SPI mode
P1.6/ UCA1TXD/UCA1SIMO	85	I/O	General-purpose digital I/O / USCI_A1 transmit data output in UART mode, slave in/master out in SPI mode
P1.5/TACLK/ACLK	86	I/O	General-purpose digital I/O / Timer_A, clock signal TACLK input / ACLK output (divided by 1, 2, 4, or 8)
P1.4/TBCLK/SMCLK	87	I/O	General-purpose digital I/O / input clock TBCLK—Timer_B3 / submain system clock SMCLK output
P1.3/TBOUTH/SVSOUT	88	I/O	General-purpose digital I/O / switch all PWM digital output ports to high impedance—Timer_B3 TB0 to TB2 / SVS: output of SVS comparator
P1.2/TA1	89	I/O	General-purpose digital I/O / Timer_A, Capture: CCI1A input, compare: Out1 output
P1.1/TA0/MCLK	90	I/O	General-purpose digital I/O / Timer_A. Capture: CCI0B input / MCLK output. Note: TA0 is only an input on this pin / BSL receive
P1.0/TA0	91	I/O	General-purpose digital I/O / Timer_A. Capture: CCI0A input, compare: Out0 output / BSL transmit
DV_{CC1}	92		Digital supply voltage, positive terminal.
XT2OUT	93	O	Output terminal of crystal oscillator XT2
XT2IN	94	I	Input port for crystal oscillator XT2. Only standard crystals can be connected.
DV_{SS1}	95		Digital supply voltage, negative terminal.
TDO/TDI	96	I/O	Test data output port. TDO/TDI data output or programming data input terminal
TDI/TCLK	97	I	Test data input or test clock input. The device protection fuse is connected to TDI/TCLK.
TMS	98	I	Test mode select. TMS is used as an input port for device programming and test.
TCK	99	I	Test clock. TCK is the clock input port for device programming and test.
$\overline{RST}$/NMI	100	I	Reset input or nonmaskable interrupt input port

short-form description

CPU

The MSP430 CPU has a 16-bit RISC architecture that is highly transparent to the application. All operations, other than program-flow instructions, are performed as register operations in conjunction with seven addressing modes for source operand and four addressing modes for destination operand.

The CPU is integrated with 16 registers that provide reduced instruction execution time. The register-to-register operation execution time is one cycle of the CPU clock.

Four of the registers, R0 to R3, are dedicated as program counter, stack pointer, status register, and constant generator, respectively. The remaining registers are general-purpose registers.

Peripherals are connected to the CPU using data, address, and control buses and can be handled with all instructions.

instruction set

The instruction set consists of 51 instructions with three formats and seven address modes. Each instruction can operate on word and byte data. Table 1 shows examples of the three types of instruction formats; Table 2 shows the address modes.

Table 1. Instruction Word Formats

Dual operands, source-destination	e.g., ADD R4,R5	R4 + R5 ---> R5
Single operands, destination only	e.g., CALL R8	PC -->(TOS), R8--> PC
Relative jump, un/conditional	e.g., JNE	Jump-on-equal bit = 0

Table 2. Address Mode Descriptions

ADDRESS MODE	S	D	SYNTAX	EXAMPLE	OPERATION
Register	●	●	MOV Rs,Rd	MOV R10,R11	R10 --> R11
Indexed	●	●	MOV X(Rn),Y(Rm)	MOV 2(R5),6(R6)	M(2+R5)--> M(6+R6)
Symbolic (PC relative)	●	●	MOV EDE,TONI		M(EDE) --> M(TONI)
Absolute	●	●	MOV &MEM,&TCDAT		M(MEM) --> M(TCDAT)
Indirect	●		MOV @Rn,Y(Rm)	MOV @R10,Tab(R6)	M(R10) --> M(Tab+R6)
Indirect autoincrement	●		MOV @Rn+,Rm	MOV @R10+,R11	M(R10) --> R11 R10 + 2--> R10
Immediate	●		MOV #X,TONI	MOV #45,TONI	#45 --> M(TONI)

NOTE: S = source, D = destination

operating modes

The MSP430 has one active mode and five software-selectable low-power modes of operation. An interrupt event can wake up the device from any of the five low-power modes, service the request, and restore back to the low-power mode on return from the interrupt program.

The following six operating modes can be configured by software:

- Active mode AM
  - All clocks are active
- Low-power mode 0 (LPM0)
  - CPU is disabled
  - ACLK and SMCLK remain active. MCLK is disabled.
  - FLL+ loop control remains active
- Low-power mode 1 (LPM1)
  - CPU is disabled
  - FLL+ loop control is disabled
  - ACLK and SMCLK remain active. MCLK is disabled.
- Low-power mode 2 (LPM2)
  - CPU is disabled
  - MCLK and FLL+ loop control and DCOCLK are disabled
  - DCO's dc generator remains enabled
  - ACLK remains active
- Low-power mode 3 (LPM3)
  - CPU is disabled
  - MCLK, FLL+ loop control, and DCOCLK are disabled
  - DCO's dc generator is disabled
  - ACLK remains active
- Low-power mode 4 (LPM4)
  - CPU is disabled
  - ACLK is disabled
  - MCLK, FLL+ loop control, and DCOCLK are disabled
  - DCO's dc generator is disabled
  - Crystal oscillator is stopped

interrupt vector addresses

The interrupt vectors and the power-up starting address are located in the address range 0FFFFh to 0FFC0h. The vector contains the 16-bit address of the appropriate interrupt-handler instruction sequence. If the reset vector (at 0FFFEh) contains 0FFFFh (e.g., flash is not programmed) the CPU enters LPM4 after power-up.

INTERRUPT SOURCE	INTERRUPT FLAG	SYSTEM INTERRUPT	WORD ADDRESS	PRIORITY
Power-Up External Reset Watchdog Flash Memory PC Out-of-Range (see Note 4)	PORIFG RSTIFG WDTIFG KEYV (see Note 1)	Reset	0FFFEh	31, highest
NMI Oscillator Fault Flash Memory Access Violation	NMIIFG (see Notes 1 and 3) OFIFG (see Notes 1 and 3) ACCVIFG (see Notes 1 and 3)	(Non)maskable (Non)maskable (Non)maskable	0FFFCh	30
Timer_B3	TBCCR0 CCIFG (see Note 2)	Maskable	0FFFAh	29
Timer_B3	TBCCR1 to TBCCR2 CCIFGs TBIFG (see Notes 1 and 2)	Maskable	0FFF8h	28
Comparator_A	CAIFG	Maskable	0FFF6h	27
Watchdog Timer	WDTIFG	Maskable	0FFF4h	26
USCI_A0/B0 Receive USCI_B0 I2C Status	UCA0RXIFG, UCB0RXIFG (see Notes 1 and 5)	Maskable	0FFF2h	25
USCI_A0/B0 Transmit USCI_B0 I2C Receive/Transmit	UCA0TXIFG, UCB0TXIFG (see Notes 1 and 6)	Maskable	0FFF0h	24
SD16_A	SD16CCTLx SD16OVIFG, SD16CCTLx SD16IFG (see Notes 1 and 2)	Maskable	0FFEEh	23
Timer_A3	TACCR0 CCIFG (see Note 2)	Maskable	0FFECh	22
Timer_A3	TACCR1 and TACCR2 CCIFGs, TAIFG (see Notes 1 and 2)	Maskable	0FFEAh	21
I/O Port P1 (Eight Flags)	P1IFG.0 to P1IFG.7 (see Notes 1 and 2)	Maskable	0FFE8h	20
USCI_A1/B1 Receive USCI_B1 I2C Status	UCA1RXIFG, UCB1RXIFG (see Notes 1 and 5)	Maskable	0FFE6h	19
USCI_A1/B1 Transmit USCI_B1 I2C Receive/Transmit	UCA1TXIFG, UCB1TXIFG (see Notes 1 and 6)	Maskable	0FFE4h	18
I/O Port P2 (Eight Flags)	P2IFG.0 to P2IFG.7 (see Notes 1 and 2)	Maskable	0FFE2h	17
Basic Timer1/RTC	BTIFG	Maskable	0FFE0h	16
DMA	DMA0IFG, DMA1IFG, DMA2IFG (see Notes 1 and 2)	Maskable	0FFDEh	15
Reserved	Reserved (see Note 8)		0FFDCh to 0FFC0h	14 to 0, lowest

NOTES:
1. Multiple source flags
2. Interrupt flags are located in the module.
3. (Non)maskable: the individual interrupt-enable bit can disable an interrupt event, but the general-interrupt enable can not disable it.
4. A reset is generated if the CPU tries to fetch instructions from within the module register memory address range (0h to 01FFh) or from within unused address ranges.
5. USCI_B in SPI mode: UCBxRXIFG. USCI_B in I2C mode: UCALIFG, UCNACKIFG, ICSTTIFG, UCSTPIFG
6. USCI_B in SPI mode: UCBxTXIFG. USCI_B in I2C mode: UCBxRXIFG, UCBxTXIFG
7. The address 0x0FFBE is used as bootstrap loader security key (BSLSKEY).
   A 0x0AA55 at this location disables the BSL completely.
   A zero disables the erasure of the flash if an invalid password is supplied.
8. The interrupt vectors at addresses 0FFDCh to 0FFC0h are not used in this device and can be used for regular program code if necessary.

special function registers

The MSP430 special function registers (SFR) are located in the lowest address space and are organized as byte mode registers. SFRs should be accessed with byte instructions.

interrupt enable 1 and 2

Address	7	6	5	4	3	2	1	0
00h			ACCVIE	NMIIE			OFIE	WDTIE
			rw-0	rw-0			rw-0	rw-0

WDTIE Watchdog timer interrupt enable. Inactive if watchdog mode is selected. Active if watchdog timer is configured in interval timer mode.

OFIE Oscillator fault enable

NMIIE (Non)maskable interrupt enable

ACCVIE Flash access violation interrupt enable

Address	7	6	5	4	3	2	1	0
01h	BTIE				UCB0TXIE	UCB0RXIE	UCA0TXIE	UCA0RXIE
	rw-0				rw-0	rw-0	rw-0	rw-0

UCA0RXIE USCI_A0 receive interrupt enable

UCA0TXIE USCI_A0 transmit interrupt enable

UCB0RXIE USCI_B0 receive interrupt enable

UCB0TXIE USCI_B0 transmit interrupt enable

BTIE Basic timer interrupt enable

interrupt flag register 1 and 2

Address	7	6	5	4	3	2	1	0
02h				NMIIFG	RSTIFG	PORIFG	OFIFG	WDTIFG
				rw-0	rw-(0)	rw-(1)	rw-1	rw-(0)

WDTIFG Set on watchdog timer overflow or security key violation.
Reset on V_{CC} power-up or a reset condition at $\overline{RST}$/NMI pin in reset mode.

OFIFG Flag set on oscillator fault

RSTIFG External reset interrupt flag. Set on a reset condition at $\overline{RST}$/NMI pin in reset mode. Reset on V_{CC} power-up

PORIFG Power-on interrupt flag. Set on V_{CC} power-up.

NMIIFG Set via $\overline{RST}$/NMI-pin

Address	7	6	5	4	3	2	1	0
03h	BTIFG				UCB0 TXIFG	UCB0 RXIFG	UCA0 TXIFG	UCA0 RXIFG
	rw-0				rw-1	rw-0	rw-1	rw-0

UCA0RXIFG USCI_A0 receive interrupt flag

UCA0TXIFG USCI_A0 transmit interrupt flag

UCB0RXIFG USCI_B0 receive interrupt flag

UCB0TXIFG USCI_B0 transmit interrupt flag

BTIFG Basic Timer1 interrupt flag

Legend		
	rw:	Bit can be read and written.
	rw-0,1:	Bit can be read and written. It is Reset or Set by PUC.
	rw-(0,1):	Bit can be read and written. It is Reset or Set by POR.
		SFR bit is not present in device

memory organization

		MSP430F47126/ MSP430F47127	MSP430F47163/ MSP430F47166/ MSP430F47167	MSP430F47173/ MSP430F47176/ MSP430F47177	MSP430F47183/ MSP430F47186/ MSP430F47187	MSP430F47193/ MSP430F47196/ MSP430F47197
Memory Main: interrupt vector Main: code memory	Size Flash Flash	56KB 0FFFFh – 0FFC0h 0FFFFh–002100h	92KB 0FFFFh – 0FFC0h 018FFFh–002100h	92KB 0FFFFh – 0FFC0h 019FFFh–003100h	116KB 0FFFFh – 0FFC0h 01FFFFh–003100h	120KB 0FFFFh – 0FFC0h 01FFFFh–002100h
RAM (Total)	Size	4KB 020FFh–01100h	4KB 020FFh–01100h	8KB 030FFh–01100h	8KB 030FFh–01100h	4KB 020FFh–01100h
Extended	Size	2KB 020FFh–01900h	2KB 020FFh–01900h	6KB 030FFh–01900h	6KB 030FFh–01900h	2KB 020FFh–01900h
Mirrored	Size	2KB 018FFh–01100h	2KB 018FFh–01100h	2KB 018FFh–01100h	2KB 018FFh–01100h	2KB 018FFh–01100h
Information memory	Size Flash	256 Byte 010FFh–01000h	256 Byte 010FFh–01000h	256 Byte 010FFh–01000h	256 Byte 010FFh–01000h	256 Byte 010FFh–01000h
Boot memory	Size ROM	1KB 0FFFh–0C00h	1KB 0FFFh–0C00h	1KB 0FFFh – 0C00h	1KB 0FFFh–0C00h	1KB 0FFFh–0C00h
RAM (mirrored at 018FFh – 01100h)	Size	2KB 09FFh–0200h	2KB 09FFh–0200h	2KB 09FFh–0200h	2KB 09FFh–0200h	2KB 09FFh–0200h
Peripherals	16-bit 8-bit 8-bit SFR	01FFh–0100h 0FFh–010h 0Fh–00h	01FFh–0100h 0FFh–010h 0Fh–00h	01FFh–0100h 0FFh–010h 0Fh–00h	01FFh–0100h 0FFh–010h 0Fh–00h	01FFh–0100h 0FFh–010h 0Fh–00h

bootstrap loader (BSL)

The MSP430 bootstrap loader (BSL) enables users to program the flash memory or RAM using a UART serial interface. Access to the MSP430 memory via the BSL is protected by user-defined password. For complete description of the features of the BSL and its implementation, see the *MSP430 Memory Programming User's Guide,* literature number SLAU265.

BSL FUNCTION	PZ PACKAGE PINS
Data Transmit	91 - P1.0
Data Receive	90 - P1.1

flash memory

The flash memory can be programmed via the JTAG port, the bootstrap loader, or in-system by the CPU. The CPU can perform single-byte and single-word writes to the flash memory. Features of the flash memory include:

- Flash memory has n segments of main memory and four segments of information memory (A to D) of 64 bytes each. Each segment in main memory is 512 bytes in size.
- Segments 0 to n may be erased in one step, or each segment may be individually erased.
- Segments A to D can be erased individually, or as a group with segments 0 to n.
  Segments A to D are also called *information memory.*
- Segment A might contain calibration data. After reset segment A is protected against programming or erasing. It can be unlocked but care should be taken not to erase this segment if the calibration data is required.
- Flash content integrity check with marginal read modes.

peripherals

Peripherals are connected to the CPU through data, address, and control buses and can be handled using all instructions. For complete module descriptions, see the *MSP430x4xx Family User's Guide*, literature number SLAU056.

oscillator and system clock

The clock system is supported by the FLL+ module that includes support for a 32768-Hz watch crystal oscillator, an internal digitally-controlled oscillator (DCO) and an 8-MHz high-frequency crystal oscillator (XT1) plus a 16-MHz high-frequency crystal oscillator (XT2). The FLL+ clock module is designed to meet the requirements of both low system cost and low power consumption. The FLL+ features a digital frequency locked loop (FLL) hardware that, in conjunction with a digital modulator, stabilizes the DCO frequency to a programmable multiple of the watch crystal frequency. The internal DCO provides a fast turn-on clock source and stabilizes in less than 6 μs. The FLL+ module provides the following clock signals:

- Auxiliary clock (ACLK), sourced from a 32768-Hz watch crystal or a high-frequency crystal
- Main clock (MCLK), the system clock used by the CPU
- Sub-Main clock (SMCLK), the sub-system clock used by the peripheral modules
- ACLK/n, the buffered output of ACLK, ACLK/2, ACLK/4, or ACLK/8

brownout, supply voltage supervisor (SVS)

The brownout circuit is implemented to provide the proper internal reset signal to the device during power on and power off. The SVS circuitry detects if the supply voltage drops below a user selectable level and supports both supply voltage supervision (the device is automatically reset) and supply voltage monitoring (SVM, the device is not automatically reset).

The CPU begins code execution after the brownout circuit releases the device reset. However, V_{CC} may not have ramped to $V_{CC(min)}$ at that time. The user must insure the default FLL+ settings are not changed until V_{CC} reaches $V_{CC(min)}$. If desired, the SVS circuit can be used to determine when V_{CC} reaches $V_{CC(min)}$.

digital I/O

There are nine 8-bit I/O ports implemented—ports P1 through P5 and P7 through P10.

- All individual I/O bits are independently programmable.
- Any combination of input, output, and interrupt conditions is possible.
- Edge-selectable interrupt input capability for all the eight bits of ports P1 and P2.
- Read/write access to port-control registers is supported by all instructions.
- Ports P7/P8 and P9/P10 can be accessed word-wise as ports PA and PB respectively.
- Each I/O has an individually programmable pullup/pulldown resistor.

Note: Only four bits of port P10 (P10.0 to P10.3) are available on external pins, but all control and data bits for port P10 are implemented.

DMA controller

The DMA controller allows movement of data from one memory address to another without CPU intervention. For example, the DMA controller can be used to move data from a USCI module to RAM. Using the DMA controller can increase the throughput of peripheral modules. The DMA controller reduces system power consumption by allowing the CPU to remain in sleep mode without having to awaken to move data to or from a peripheral.

DMA TRIGGER SELECT DMAXTSELX	DESCRIPTION
0000	DMAREQ bit (software trigger)
0001	TACCR2 CCIFG bit
0010	TBCCR2 CCIFG bit
0011	UCA0RXIFG bit
0100	UCA0TXIFG bit
0101	N/A
0110	SD16IFG bit
0111	TACCR0 CCIFG bit
1000	TBCCR0 CCIFG bit
1001	UCA1RXIFG bit
1010	UCA1TXIFG bit
1011	Multiplier ready
1100	UCB0RXIFG bit
1101	UCB0TXIFG bit
1110	DMA0IFG bit triggers DMA channel 1 DMA1IFG bit triggers DMA channel 2 DMA2IFG bit triggers DMA channel 0
1111	External trigger DMAE0

hardware multiplier

The multiplication operation is supported by a dedicated peripheral module. The module performs operations with 32-bit, 24-bit, 16-bit and 8-bit operands. The module is capable of supporting signed and unsigned multiplication as well as signed and unsigned multiply and accumulate operations.

watchdog timer (WDT+)

The primary function of the WDT+ module is to perform a controlled system restart after a software problem occurs. If the selected time interval expires, a system reset is generated. If the watchdog function is not needed in an application, the module can be configured as an interval timer and can generate interrupts at selected time intervals.

Basic Timer1 and Real-Time Clock (RTC)

The Basic Timer1 has two independent 8-bit timers that can be cascaded to form a 16-bit timer/counter. Both timers can be read and written by software. The Basic Timer1 is extended to provide an integrated real-time clock (RTC). An internal calendar compensates for months with less than 31 days and includes leap year correction.

universal serial communication interfaces (USCIs) (USCI_A0, USCI_B0, USCI_A1, USCI_B1)

The USCI module is used for serial data communication. The USCI module supports synchronous communication protocols such as SPI (3-pin or 4-pin) and I2C and asynchronous communication protocols such as UART, enhanced UART with automatic baudrate detection (LIN), and IrDA.

USCI_A0 and USCI_A1 provides support for SPI (3-pin or 4-pin), UART, enhanced UART, and IrDA.

USCI_B0 and USCI_B1 provides support for SPI (3-pin or 4-pin) and I2C.

Timer_A3

Timer_A3 is a 16-bit timer/counter with three capture/compare registers. Timer_A3 can support multiple capture/compares, PWM outputs, and interval timing. Timer_A3 also has extensive interrupt capabilities. Interrupts may be generated from the counter on overflow conditions and from each of the capture/compare registers.

TIMER_A3 SIGNAL CONNECTIONS

INPUT PIN NUMBER	DEVICE INPUT SIGNAL	MODULE INPUT NAME	MODULE BLOCK	MODULE OUTPUT SIGNAL	OUTPUT PIN NUMBER
86 - P1.5	TACLK	TACLK	Timer	NA	
	ACLK	ACLK			
	SMCLK	SMCLK			
86 - P1.5	$\overline{\text{TACLK}}$	INCLK			
91 - P1.0	TA0	CCI0A	CCR0	TA0	91 - P1.0
90 - P1.1	TA0	CCI0B			
	DV_{SS}	GND			
	DV_{CC}	V_{CC}			
89 - P1.2	TA1	CCI1A	CCR1	TA1	89 - P1.2
	CAOUT (internal)	CCI1B			
	DV_{SS}	GND			
	DV_{CC}	V_{CC}			
71 - P3.4	TA2	CCI2A	CCR2	TA2	71 - P3.4
	ACLK (internal)	CCI2B			
	DV_{SS}	GND			
	DV_{CC}	V_{CC}			

Timer_B3

Timer_B3 is a 16-bit timer/counter with three capture/compare registers. Timer_B3 can support multiple capture/compares, PWM outputs, and interval timing. Timer_B3 also has extensive interrupt capabilities. Interrupts may be generated from the counter on overflow conditions and from each of the capture/compare registers.

TIMER_B3 SIGNAL CONNECTIONS					
INPUT PIN NUMBER	DEVICE INPUT SIGNAL	MODULE INPUT NAME	MODULE BLOCK	MODULE OUTPUT SIGNAL	OUTPUT PIN NUMBER
87 - P1.4	TBCLK	TBCLK	Timer	NA	
	ACLK	ACLK			
	SMCLK	SMCLK			
87 - P1.4	$\overline{\text{TBCLK}}$	INCLK			
70 – P3.5	TB0	CCI0A	CCR0	TB0	70 - P3.5
70 – P3.5	TB0	CCI0B			
	DV_{SS}	GND			
	DV_{CC}	V_{CC}			
69 - P3.6	TB1	CCI1A	CCR1	TB1	69 - P3.6
69 - P3.6	TB1	CCI1B			
	DV_{SS}	GND			
	DV_{CC}	V_{CC}			
68 - P3.7	TB2	CCI2A	CCR2	TB2	68 - P3.7
68 - P3.7	TB2	CCI2B			
	DV_{SS}	GND			
	DV_{CC}	V_{CC}			

Comparator_A

The primary function of the comparator_A module is to support precision slope analog-to-digital conversions, battery-voltage supervision, and monitoring of external analog signals.

SD16_A

The SD16_A module integrates three (MSP430F471x3), six (MSP430F471x6) or seven (MSP430F471x7) independent 16-bit sigma-delta A/D converters. Each channel is designed with a fully differential analog input pair and programmable gain amplifier input stage. In addition to external analog inputs, an internal V_{CC} sense and temperature sensor are also available.

LCD driver with regulated charge pump

The LCD_A driver generates the segment and common signals required to drive an LCD display. The LCD_A controller has dedicated data memory to hold segment drive information. Common and segment signals are generated as defined by the mode. Static, 2-MUX, 3-MUX, and 4-MUX LCDs are supported by this peripheral. The module can provide a LCD voltage independent of the supply voltage via an integrated charge pump. Furthermore it is possible to control the level of the LCD voltage and thus contrast in software.

embedded emulation module (EEM)

All MSP430F471x3, MSP430F471x6, and MSP430F471x7 devices have an EEM that supports real-time in-system debugging. The implemented L version of the EEM has the following features:

- Eight hardware triggers on memory address or data bus
- Two hardware triggers on write accesses to CPU register
- Eight combinational triggers to combine any of the 10 above hardware triggers
- Trigger sequencer
- CPU break reaction on combinational triggers for breakpoints
- State storage to trace internal buses
- Clock control on module level

peripheral file map

PERIPHERALS WITH WORD ACCESS			
Watchdog	Watchdog timer control	WDTCTL	0120h
Flash_A	Flash control 4	FCTL4	01BEh
	Flash control 3	FCTL3	012Ch
	Flash control 2	FCTL2	012Ah
	Flash control 1	FCTL1	0128h
Timer_B3	Capture/compare register 2	TBCCR2	0196h
	Capture/compare register 1	TBCCR1	0194h
	Capture/compare register 0	TBCCR0	0192h
	Timer_B register	TBR	0190h
	Capture/compare control 2	TBCCTL2	0186h
	Capture/compare control 1	TBCCTL1	0184h
	Capture/compare control 0	TBCCTL0	0182h
	Timer_B control	TBCTL	0180h
	Timer_B interrupt vector	TBIV	011Eh
Timer_A3	Capture/compare register 2	TACCR2	0176h
	Capture/compare register 1	TACCR1	0174h
	Capture/compare register 0	TACCR0	0172h
	Timer_A register	TAR	0170h
	Capture/compare control 2	TACCTL2	0166h
	Capture/compare control 1	TACCTL1	0164h
	Capture/compare control 0	TACCTL0	0162h
	Timer_A control	TACTL	0160h
	Timer_A interrupt vector	TAIV	012Eh
32-bit Hardware Multiplier	MPY32 control 0	MPY32CTL0	015Ch
	64-bit result 3 – most significant word	RES3	015Ah
	64-bit result 2	RES2	0158h
	64-bit result 1	RES1	0156h
	64-bit result 0 – least significant word	RES0	0154h
	Second 32-bit operand, high word	OP2H	0152h
	Second 32-bit operand, low word	OP2L	0150h
	Multiply signed + accumulate/ 32-bit operand1, high word	MACS32H	014Eh
	Multiply signed + accumulate/ 32-bit operand1, low word	MACS32L	014Ch
	Multiply + accumulate/ 32-bit operand1, high word	MAC32H	014Ah
	Multiply + accumulate/ 32-bit operand1, low word	MAC32L	0148h
	Multiply signed/32-bit operand1, high word	MPYS32H	0146h
	Multiply signed/32-bit operand1, low word	MPYS32L	0144h
	Multiply unsigned/32-bit operand1, high word	MPY32H	0142h
	Multiply unsigned/32-bit operand1, low word	MPY32L	0140h

peripheral file map (continued)

PERIPHERALS WITH WORD ACCESS (CONTINUED)			
32-bit Hardware Multiplier	Sum extend	SUMEXT	013Eh
	Result high word	RESHI	013Ch
	Result low word	RESLO	013Ah
	Second operand	OP2	0138h
	Multiply signed + accumulate/operand1	MACS	0136h
	Multiply + accumulate/operand1	MAC	0134h
	Multiply signed/operand1	MPYS	0132h
	Multiply unsigned/operand1	MPY	0130h
USCI_B0 (see also: Peripherals with Byte Access)	USCI_B0 I2C own address	UCB0I2COA	016Ch
	USCI_B0 I2C slave address	UCB0I2CSA	016Eh
USCI_B1 (see also: Peripherals with Byte Access)	USCI_B1 I2C own address	UCB1I2COA	017Ch
	USCI_B1 I2C slave address	UCB1I2CSA	017Eh
SD16_A (see also: Peripherals with Byte Access)	General Control	SD16CTL	0100h
	Channel 0 Control	SD16CCTL0	0102h
	Channel 1 Control	SD16CCTL1	0104h
	Channel 2 Control	SD16CCTL2	0106h
	Channel 3 Control	SD16CCTL3	0108h
	Channel 4 Control	SD16CCTL4	010Ah
	Channel 5 Control	SD16CCTL5	010Ch
	Channel 6 Control	SD16CCTL6	010Eh
	Channel 0 conversion memory	SD16MEM0	0110h
	Channel 1 conversion memory	SD16MEM1	0112h
	Channel 2 conversion memory	SD16MEM2	0114h
	Channel 3 conversion memory	SD16MEM3	0116h
	Channel 4 conversion memory	SD16MEM4	0118h
	Channel 5 conversion memory	SD16MEM5	011Ah
	Channel 6 conversion memory	SD16MEM6	011Ch
	SD16 Interrupt vector word register	SD16IV	01AEh
Port PA	Port PA resistor enable	PAREN	014h
	Port PA selection	PASEL	03Eh
	Port PA direction	PADIR	03Ch
	Port PA output	PAOUT	03Ah
	Port PA input	PAIN	038h
Port PB	Port PB resistor enable	PBREN	016h
	Port PB selection	PBSEL	00Eh
	Port PB direction	PBDIR	00Ch
	Port PB output	PBOUT	00Ah
	Port PB input	PBIN	008h

peripheral file map (continued)

PERIPHERALS WITH WORD ACCESS (CONTINUED)			
DMA	DMA module control 0	DMACTL0	0122h
	DMA module control 1	DMACTL1	0124h
	DMA interrupt vector	DMAIV	0126h
DMA Channel 0	DMA channel 0 control	DMA0CTL	01D0h
	DMA channel 0 source address	DMA0SA	01D2h
	DMA channel 0 destination address	DMA0DA	01D6h
	DMA channel 0 transfer size	DMA0SZ	01DAh
DMA Channel 1	DMA channel 1 control	DMA1CTL	01DCh
	DMA channel 1 source address	DMA1SA	01DEh
	DMA channel 1 destination address	DMA1DA	01E2h
	DMA channel 1 transfer size	DMA1SZ	01E6h
DMA Channel 2	DMA channel 2 control	DMA2CTL	01E8h
	DMA channel 2 source address	DMA2SA	01EAh
	DMA channel 2 destination address	DMA2DA	01EEh
	DMA channel 2 transfer size	DMA2SZ	01F2h

peripheral file map (continued)

PERIPHERALS WITH BYTE ACCESS			
SD16_A (see also: Peripherals with Word Access)	Channel 0 Input Control	SD16INCTL0	0B0h
	Channel 1 Input Control	SD16INCTL1	0B1h
	Channel 2 Input Control	SD16INCTL2	0B2h
	Channel 3 Input Control	SD16INCTL3	0B3h
	Channel 4 Input Control	SD16INCTL4	0B4h
	Channel 5 Input Control	SD16INCTL5	0B5h
	Channel 6 Input Control	SD16INCTL6	0B6h
	Reserved		0B7h
	Channel 0 preload	SD16PRE0	0B8h
	Channel 1 preload	SD16PRE1	0B9h
	Channel 2 preload	SD16PRE2	0BAh
	Channel 3 preload	SD16PRE3	0BBh
	Channel 4 preload	SD16PRE4	0BCh
	Channel 5 preload	SD16PRE5	0BDh
	Channel 6 preload	SD16PRE6	0BEh
	Reserved	SD16CONF1	0BFh
LCD_A	LCD Voltage Control 1	LCDAVCTL1	0AFh
	LCD Voltage Control 0	LCDAVCTL0	0AEh
	LCD Voltage Port Control 1	LCDAPCTL1	0ADh
	LCD Voltage Port Control 0	LCDAPCTL0	0ACh
	LCD memory 20	LCDM20	0A4h
	:	:	:
	LCD memory 16	LCDM16	0A0h
	LCD memory 15	LCDM15	09Fh
	:	:	:
	LCD memory 1	LCDM1	091h
	LCD control and mode	LCDACTL	090h

peripheral file map (continued)

PERIPHERALS WITH BYTE ACCESS (CONTINUED)			
USCI_A0	USCI_A0 transmit buffer	UCA0TXBUF	067h
	USCI_A0 receive buffer	UCA0RXBUF	066h
	USCI_A0 status	UCA0STAT	065h
	USCI_A0 modulation control	UCA0MCTL	064h
	USCI_A0 baud rate control 1	UCA0BR1	063h
	USCI_A0 baud rate control 0	UCA0BR0	062h
	USCI_A0 control 1	UCA0CTL1	061h
	USCI_A0 control 0	UCA0CTL0	060h
	USCI_A0 IrDA receive control	UCA0IRRCTL	05Fh
	USCI_A0 IrDA transmit control	UCA0IRTCTL	05Eh
	USCI_A0 auto baud rate control	UCA0ABCTL	05Dh
USCI_B0	USCI_B0 transmit buffer	UCB0TXBUF	06Fh
	USCI_B0 receive buffer	UCB0RXBUF	06Eh
	USCI_B0 status	UCB0STAT	06Dh
	USCI_B1 I2C interrupt enable	UCB0I2CIE	06Ch
	USCI_B0 bit rate control 1	UCB0BR1	06Bh
	USCI_B0 bit rate control 0	UCB0BR0	06Ah
	USCI_B0 control 1	UCB0CTL1	069h
	USCI_B0 control 0	UCB0CTL0	068h
USCI_A1	USCI_A1 transmit buffer	UCA1TXBUF	0D7h
	USCI_A1 receive buffer	UCA1RXBUF	0D6h
	USCI_A1 status	UCA1STAT	0D5h
	USCI_A1 modulation control	UCA1MCTL	0D4h
	USCI_A1 baud rate control 1	UCA1BR1	0D3h
	USCI_A1 baud rate control 0	UCA1BR0	0D2h
	USCI_A1 control 1	UCA1CTL1	0D1h
	USCI_A1 control 0	UCA1CTL0	0D0h
	USCI_A1 IrDA receive control	UCA1IRRCTL	0CFh
	USCI_A1 IrDA transmit control	UCA1IRTCTL	0CEh
	USCI_A1 auto baud rate control	UCA1ABCTL	0CDh
	USCI_A1 interrupt flag	UC1IFG	007h
	USCI_A1 interrupt enable	UC1IE	006h
USCI_B1	USCI_B1 transmit buffer	UCB1TXBUF	0DFh
	USCI_B1 receive buffer	UCB1RXBUF	0DEh
	USCI_B1 status	UCB1STAT	0DDh
	USCI_B1 I2C interrupt enable	UCB1I2CIE	0DCh
	USCI_B1 bit rate control 1	UCB1BR1	0DBh
	USCI_B1 bit rate control 0	UCB1BR0	0DAh
	USCI_B1 control 1	UCB1CTL1	0D9h
	USCI_B1 control 0	UCB1CTL0	0D8h
	USCI_A1 interrupt flag	UC1IFG	007h
	USCI_A1 interrupt enable	UC1IE	006h
Comparator_A	Comparator_A port disable	CAPD	05Bh
	Comparator_A control2	CACTL2	05Ah
	Comparator_A control1	CACTL1	059h
BrownOUT, SVS	SVS control register (Reset by brownout signal)	SVSCTL	056h

peripheral file map (continued)

PERIPHERALS WITH BYTE ACCESS (CONTINUED)			
FLL+ Clock	FLL+ Control2	FLL_CTL2	055h
	FLL+ Control1	FLL_CTL1	054h
	FLL+ Control0	FLL_CTL0	053h
	System clock frequency control	SCFQCTL	052h
	System clock frequency integrator	SCFI1	051h
	System clock frequency integrator	SCFI0	050h
RTC (Basic Timer 1)	Real Time Clock Year High Byte	RTCYEARH	04Fh
	Real Time Clock Year Low Byte	RTCYEARL	04Eh
	Real Time Clock Month	RTCMON	04Dh
	Real Time Clock Day of Month	RTCDAY	04Ch
	Basic Timer1 Counter 2	BTCNT2	047h
	Basic Timer1 Counter 1	BTCNT1	046h
	Real Time Counter 4	RTCNT4	045h
	(Real Time Clock Day of Week)	(RTCDOW)	
	Real Time Counter 3	RTCNT3	044h
	(Real Time Clock Hour)	(RTCHOUR)	
	Real Time Counter 2	RTCNT2	043h
	(Real Time Clock Minute)	(RTCMIN)	
	Real Time Counter 1	RTCNT1	042h
	(Real Time Clock Second)	(RTCSEC)	
	Real Time Clock Control	RTCCTL	041h
	Basic Timer1 Control	BTCTL	040h
Port P10	Port P10 resistor enable	P10REN	017h
	Port P10 selection	P10SEL	00Fh
	Port P10 direction	P10DIR	00Dh
	Port P10 output	P10OUT	00Bh
	Port P10 input	P10IN	009h
Port P9	Port P9 resistor enable	P9REN	016h
	Port P9 selection	P9SEL	00Eh
	Port P9 direction	P9DIR	00Ch
	Port P9 output	P9OUT	00Ah
	Port P9 input	P9IN	008h
Port P8	Port P8 resistor enable	P8REN	015h
	Port P8 selection	P8SEL	03Fh
	Port P8 direction	P8DIR	03Dh
	Port P8 output	P8OUT	03Bh
	Port P8 input	P8IN	039h
Port P7	Port P7 resistor enable	P7REN	014h
	Port P7 selection	P7SEL	03Eh
	Port P7 direction	P7DIR	03Ch
	Port P7 output	P7OUT	03Ah
	Port P7 input	P7IN	038h

peripheral file map (continued)

PERIPHERALS WITH BYTE ACCESS (CONTINUED)			
Port P5	Port P5 resistor enable	P5REN	012h
	Port P5 selection	P5SEL	033h
	Port P5 direction	P5DIR	032h
	Port P5 output	P5OUT	031h
	Port P5 input	P5IN	030h
Port P4	Port P4 resistor enable	P4REN	011h
	Port P4 selection	P4SEL	01Fh
	Port P4 direction	P4DIR	01Eh
	Port P4 output	P4OUT	01Dh
	Port P4 input	P4IN	01Ch
Port P3	Port P3 resistor enable	P3REN	010h
	Port P3 selection	P3SEL	01Bh
	Port P3 direction	P3DIR	01Ah
	Port P3 output	P3OUT	019h
	Port P3 input	P3IN	018h
Port P2	Port P2 resistor enable	P2REN	02Fh
	Port P2 selection	P2SEL	02Eh
	Port P2 interrupt enable	P2IE	02Dh
	Port P2 interrupt-edge select	P2IES	02Ch
	Port P2 interrupt flag	P2IFG	02Bh
	Port P2 direction	P2DIR	02Ah
	Port P2 output	P2OUT	029h
	Port P2 input	P2IN	028h
Port P1	Port P1 resistor enable	P1REN	027h
	Port P1 selection	P1SEL	026h
	Port P1 interrupt enable	P1IE	025h
	Port P1 interrupt-edge select	P1IES	024h
	Port P1 interrupt flag	P1IFG	023h
	Port P1 direction	P1DIR	022h
	Port P1 output	P1OUT	021h
	Port P1 input	P1IN	020h
Special Functions	SFR interrupt flag2	IFG2	003h
	SFR interrupt flag1	IFG1	002h
	SFR interrupt enable2	IE2	001h
	SFR interrupt enable1	IE1	000h

absolute maximum ratings (see Note 1)

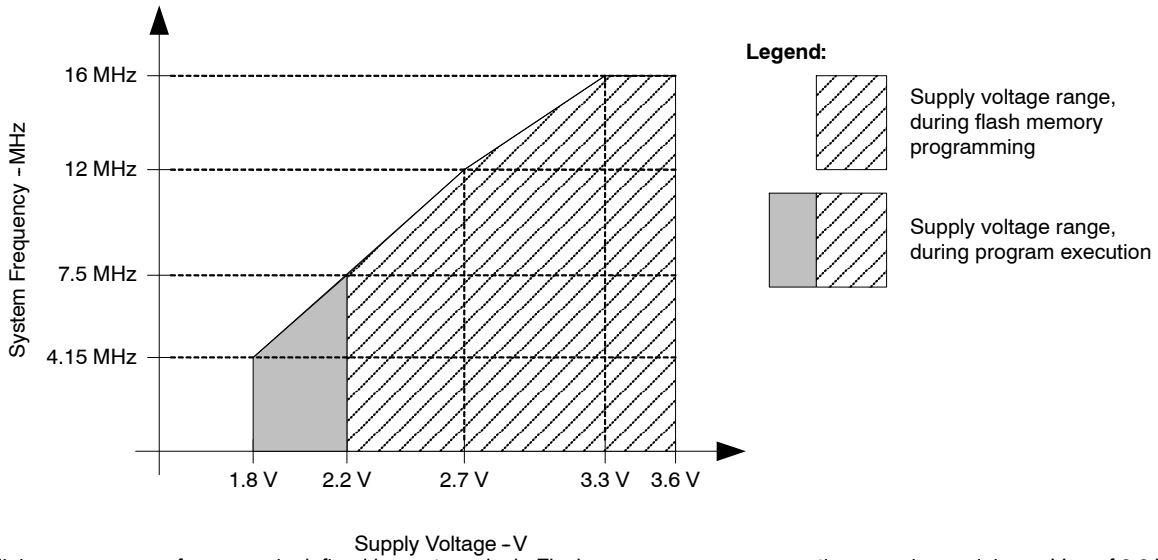
Voltage applied at V_{CC} to V_{SS} . . . . . –0.3 V to 4.1 V
Voltage applied to any pin (see Note 2) . . . . . –0.3 V to V_{CC} + 0.3 V
Diode current at any device terminal . . . . . ±2 mA
Storage temperature, T_{stg}: Unprogrammed device (see Note 3) . . . . . –55°C to 150°C
Programmed device (see Note 3) . . . . . –40°C to 85°C

NOTES:
1. Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. All voltages referenced to V_{SS}. The JTAG fuse-blow voltage, V_{FB}, is allowed to exceed the absolute maximum rating. The voltage is applied to the TDI/TCLK pin when blowing the JTAG fuse.
3. Higher temperature may be applied during board soldering process according to the current JEDEC J-STD-020 specification with peak reflow temperatures not higher than classified on the device label on the shipping boxes or reels.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage during program execution, V_{CC} (AV_{CC} = DV_{CC} = V_{CC}) (see Note 1)		1.8		3.6	V
Supply voltage during program execution, SVS enabled, PORON = 1, V_{CC} (AV_{CC} = DV_{CC} = V_{CC}) (see Notes 1, 2)		2.0		3.6	V
Supply voltage during program/erase flash memory, V_{CC} (AV_{CC} = DV_{CC} = V_{CC}) (see Note 1)		2.2		3.6	V
Supply voltage, V_{SS}			0		V
Operating free-air temperature range, T_A		–40		85	°C
Processor frequency f_{SYSTEM} (Maximum MCLK frequency) (see Notes 3, 4 and Figure 1)	V_{CC} = 1.8 V, Duty cycle = 50% ±10%	dc		4.15	MHz
	V_{CC} = 2.2 V, Duty cycle = 50% ±10%	dc		7.5	MHz
	V_{CC} = 2.7 V, Duty cycle = 50% ±10%	dc		12	MHz
	V_{CC} ≥ 3.3 V, Duty cycle = 50% ±10%	dc		16	

NOTES: 1. It is recommended to power AV_{CC} and DV_{CC} from the same source. A maximum difference of 0.3 V between AV_{CC} and DV_{CC} can be tolerated during power up and operation.
2. The minimum operating supply voltage is defined according to the trip point where POR is going active by decreasing supply voltage. POR is going inactive when the supply voltage is raised above minimum supply voltage plus the hysteresis of the SVS circuitry.
3. The MSP430 CPU is clocked directly with MCLK.
Both the high and low phase of MCLK must not exceed the pulse width of the specified maximum frequency.
4. Modules might have a different maximum input clock specification. Refer to the specification of the respective module in this data sheet.



NOTE: Minimum processor frequency is defined by system clock. Flash program or erase operations require a minimum V_{CC} of 2.2 V.

Figure 1. Operating Area

electrical characteristics over recommended operating free-air temperature (unless otherwise noted)

supply current into AV_{CC} + DV_{CC} excluding external current

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
$I_{(AM)}$	Active mode, (see Note 1) $f_{(MCLK)} = f_{(SMCLK)}$ = 1 MHz, $f_{(ACLK)}$ = 32768 Hz XTS = 0, SELM = (0,1) (Program executes from flash)	T_A = –40°C to 85°C	2.2 V		350	400	µA
			3 V		500	560	
$I_{(LPM0)}$	Low-power mode, (LPM0) (see Notes 1, 4)	T_A = –40°C to 85°C	2.2 V		45	70	µA
			3 V		75	110	
$I_{(LPM2)}$	Low-power mode, (LPM2), f(MCLK) = f (SMCLK) = 0 MHz, f(ACLK) = 32768 Hz, SCG0 = 0 (see Notes 2, 4)	T_A = –40°C to 85°C	2.2 V		11	14	µA
			3 V		17	22	
$I_{(LPM3)}$	Low-power mode, (LPM3) $f_{(MCLK)} = f_{(SMCLK)}$ = 0 MHz, $f_{(ACLK)}$ = 32768 Hz, SCG0 = 1 Basic Timer1 and RTC enabled , ACLK selected LCD_A enabled, LCDCPEN = 0: (static mode , $f_{LCD} = f_{(ACLK)}/32$) (see Notes 2, 3, and 4)	T_A = –40°C	2.2 V		0.7	2.0	µA
		T_A = 25°C			0.8	2.0	
		T_A = 60°C			2.0	3.5	
		T_A = 85°C			5.0	9.5	
		T_A = –40°C	3 V		1.1	3.0	µA
		T_A = 25°C			1.2	3.0	
		T_A = 60°C			2.5	4.0	
		T_A = 85°C			6.0	10.0	
$I_{(LPM3)}$	Low-power mode, (LPM3) $f_{(MCLK)} = f_{(SMCLK)}$ = 0 MHz, $f_{(ACLK)}$ = 32768 Hz, SCG0 = 1 Basic Timer1 and RTC enabled , ACLK selected LCD_A enabled, LCDCPEN = 0: (4-mux mode, $f_{LCD} = f_{(ACLK)}/32$) (see Notes 2, 3, and 4)	T_A = –40°C	2.2 V		3.5	5.5	µA
		T_A = 25°C			3.5	5.5	
		T_A = 60°C			5.5	7.0	
		T_A = 85°C			11.0	17.0	
		T_A = –40°C	3 V		4.0	6.5	µA
		T_A = 25°C			4.0	6.5	
		T_A = 60°C			6.0	8.0	
		T_A = 85°C			13.0	20.0	
$I_{(LPM4)}$	Low-power mode, (LPM4) $f_{(MCLK)}$ = 0 MHz, $f_{(SMCLK)}$ = 0 MHz, $f_{(ACLK)}$ = 0 Hz, SCG0 = 1 (see Notes 2 and 4)	T_A = –40°C	2.2 V		0.1	1.0	µA
		T_A = 25°C			0.2	1.0	
		T_A = 60°C			1.0	2.5	
		T_A = 85°C			4.5	8.5	
		T_A = –40°C	3 V		0.1	2.0	µA
		T_A = 25°C			0.2	2.0	
		T_A = 60°C			1.5	3.0	
		T_A = 85°C			5.0	9.0	

NOTES: 1. Timer_A is clocked by $f_{(DCOCLK)} = f_{(DCO)}$ = 1 MHz. All inputs are tied to 0 V or to V_{CC}. Outputs do not source or sink any current.
2. All inputs are tied to 0 V or to V_{CC}. Outputs do not source or sink any current.
3. The LPM3 currents are characterized with a Micro Crystal CC4V–T1A (9 pF) crystal and OSCCAPx = 01h.
4. Current for brownout included.

typical characteristics – active mode supply current (into V_{CC})

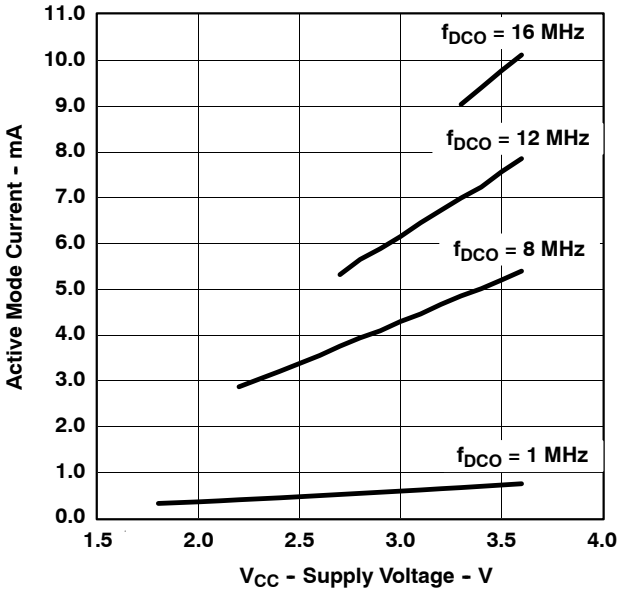


Figure 2. Active Mode Current vs V_{CC}, T_A = 25°C

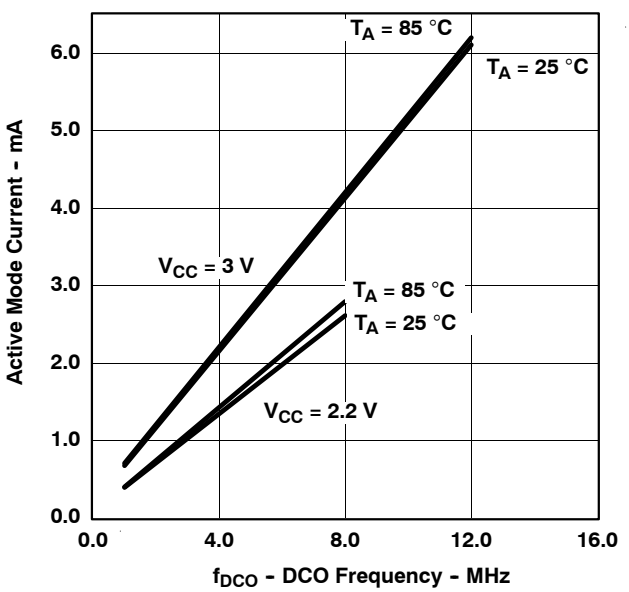


Figure 3. Active Mode Current vs DCO Frequency

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (continued)

Schmitt-trigger inputs – Ports P1 to P5, P7 to P10, RST/NMI, JTAG (TCK, TMS, TDI/TCLK, TDO/TDI)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
V_{IT+}	Positive-going input threshold voltage			0.45		0.75	V_{CC}
			2.2 V	1.00		1.65	V
			3 V	1.35		2.25	
V_{IT-}	Negative-going input threshold voltage			0.25		0.55	V_{CC}
			2.2 V	0.55		1.20	V
			3 V	0.75		1.65	
V_{hys}	Input voltage hysteresis (V_{IT+} - V_{IT-})		2.2 V	0.2		1.0	V
			3 V	0.3		1.0	
R_{Pull}	Pullup/pulldown resistor (not RST/NMI and JTAG pins)	For pullup: $V_{IN} = V_{SS}$, For pulldown: $V_{IN} = V_{CC}$		20	35	50	kΩ
C_I	Input capacitance	$V_{IN} = V_{SS}$ or V_{CC}			5		pF

inputs – Ports P1, P2

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
$t_{(int)}$	External interrupt timing	Port P1, P2: P1.x to P2.x, external trigger puls width to set interrupt flag (see Note 1)	2.2 V/3 V	20		ns

NOTES: 1. An external signal sets the interrupt flag every time the minimum interrupt puls width $t_{(int)}$ is met. It may be set even with trigger signals shorter than $t_{(int)}$.

leakage current – Ports P1 to P5, P7 to P10

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
$I_{lkg(Px.x)}$	High-impedance leakage current	See Notes 1 and 2	2.2 V/3 V		±50	nA

NOTES: 1. The leakage current is measured with V_{SS} or V_{CC} applied to the corresponding pin(s), unless otherwise noted.
2. The leakage of the digital port pins is measured individually. The port pin is selected for input and the pullup/pulldown resistor is disabled.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (continued)

outputs – Ports P1 to P5, P7 to P10

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
V_{OH}	High-level output voltage	$I_{(OHmax)}$ = –1.5 mA (see Note 1)	2.2 V	V_{CC}–0.25	V_{CC}	V
		$I_{(OHmax)}$ = –6 mA (see Note 2)	2.2 V	V_{CC}–0.6	V_{CC}	
		$I_{(OHmax)}$ = –1.5 mA (see Note 1)	3 V	V_{CC}–0.25	V_{CC}	
		$I_{(OHmax)}$ = –6 mA (see Note 2)	3 V	V_{CC}–0.6	V_{CC}	
V_{OL}	Low-level output voltage	$I_{(OLmax)}$ = 1.5 mA (see Note 1)	2.2 V	V_{SS}	V_{SS}+0.25	V
		$I_{(OLmax)}$ = 6 mA (see Note 2)	2.2 V	V_{SS}	V_{SS}+0.6	
		$I_{(OLmax)}$ = 1.5 mA (see Note 1)	3 V	V_{SS}	V_{SS}+0.25	
		$I_{(OLmax)}$ = 6 mA (see Note 2)	3 V	V_{SS}	V_{SS}+0.6	

NOTES: 1. The maximum total current, I_{OHmax} and I_{OLmax}, for all outputs combined, should not exceed ±12 mA to hold the maximum voltage drop specified.
2. The maximum total current, I_{OHmax} and I_{OLmax}, for all outputs combined, should not exceed ±48 mA to hold the maximum voltage drop specified.

output frequency – Ports P1 to P5, P7 to P10

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
$f_{Px.y}$	Port output frequency (with load)	P1.4/TBCLK/SMCLK, C_L = 20 pF, R_L = 1 kΩ against V_{CC}/2 (see Notes 1 and 2)	2.2 V		10	MHz
			3 V		12	MHz
f_{Port_CLK}	Clock output frequency	P1.1/TA0/MCLK, P1.5/TACLK/ACLK, P1.4/TBCLK/SMCLK, C_L = 20 pF (see Note 2)	2.2 V		12	MHz
			3 V		16	MHz

NOTES: 1. Alternatively a resistive divider with 2 times 2 kΩ between V_{CC} and V_{SS} is used as load. The output is connected to the center tap of the divider.
2. The output voltage reaches at least 10% and 90% V_{CC} at the specified toggle frequency.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (continued)

typical characteristics – outputs

TYPICAL LOW-LEVEL OUTPUT CURRENT vs LOW-LEVEL OUTPUT VOLTAGE

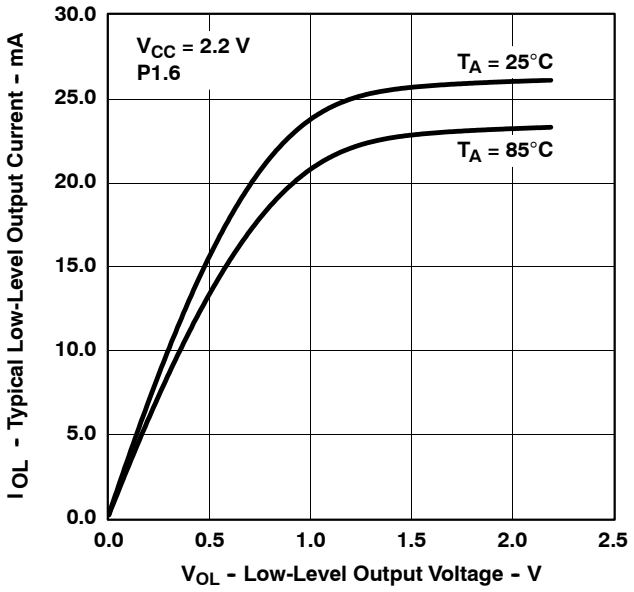


Figure 4

TYPICAL LOW-LEVEL OUTPUT CURRENT vs LOW-LEVEL OUTPUT VOLTAGE

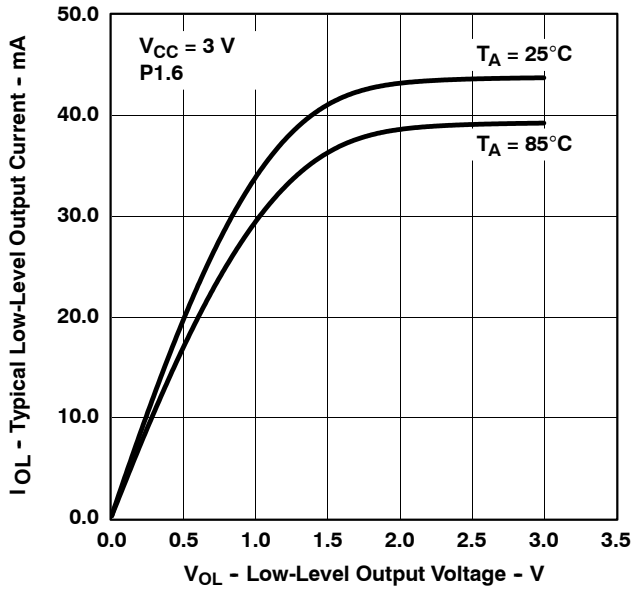


Figure 5

TYPICAL HIGH-LEVEL OUTPUT CURRENT vs HIGH-LEVEL OUTPUT VOLTAGE

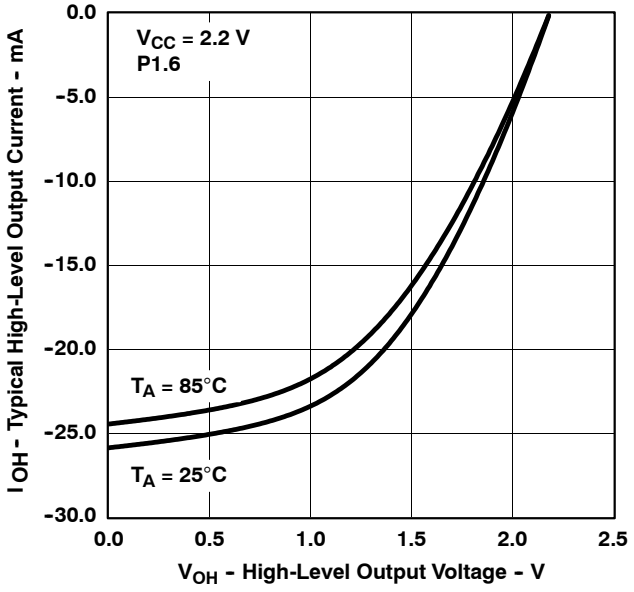


Figure 6

TYPICAL HIGH-LEVEL OUTPUT CURRENT vs HIGH-LEVEL OUTPUT VOLTAGE

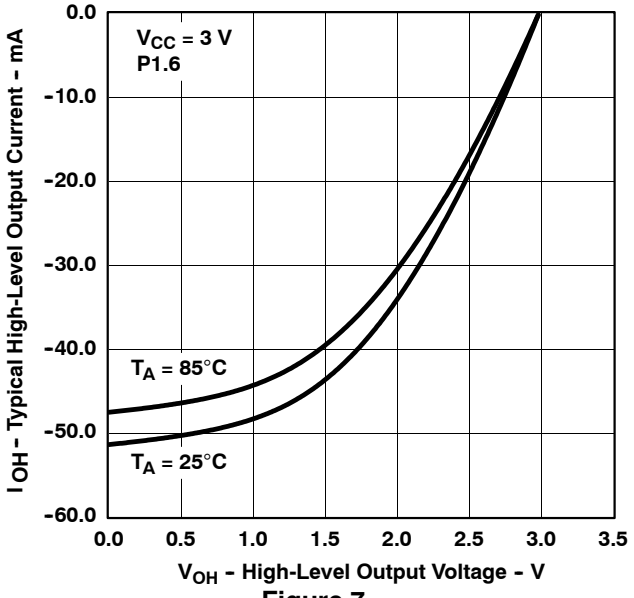


Figure 7

NOTE: One output loaded at a time.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (continued)

POR/brownout reset (BOR) (see Notes 1 and 2)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
$V_{CC(start)}$	(See Figure 8)	$dV_{CC}/dt \le 3$ V/s			$0.7 \times V_{(B\_IT-)}$		V
$V_{(B\_IT-)}$	(See Figure 8 through Figure 10)	$dV_{CC}/dt \le 3$ V/s				1.71	V
$V_{hys(B\_IT-)}$	(See Figure 8)	$dV_{CC}/dt \le 3$ V/s		70	130	180	mV
$t_{d(BOR)}$	(See Figure 8)					2000	μs
$t_{(reset)}$	Pulse length needed at $\overline{RST}$/NMI pin to accepted reset internally		2.2 V/3 V	2			μs

NOTES: 1. The current consumption of the brownout module is already included in the I_{CC} current consumption data. The voltage level $V_{(B\_IT-)} + V_{hys(B\_IT-)}$ is ≤ 1.8 V.

2. During power up, the CPU begins code execution following a period of $t_{d(BOR)}$ after $V_{CC} = V_{(B\_IT-)} + V_{hys(B\_IT-)}$. The default FLL+ settings must not be changed until $V_{CC} \ge V_{CC(min)}$, where $V_{CC(min)}$ is the minimum supply voltage for the desired operating frequency. See the *MSP430x4xx Family User's Guide (SLAU056)* for more information on the brownout/SVS circuit.

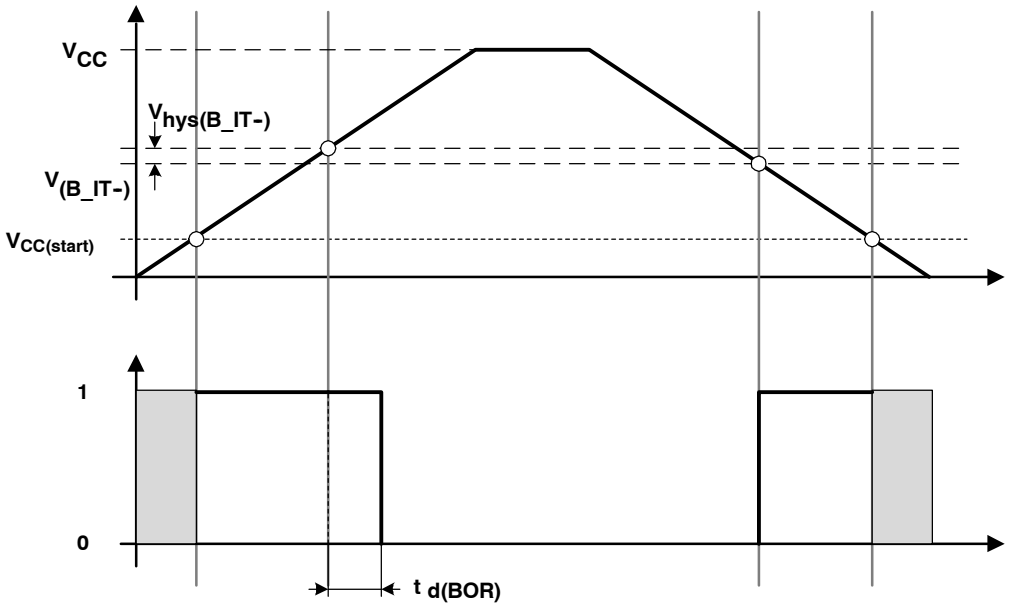


Figure 8. POR/Brownout Reset (BOR) vs Supply Voltage

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (continued)

typical characteristics – POR/brownout reset (BOR)

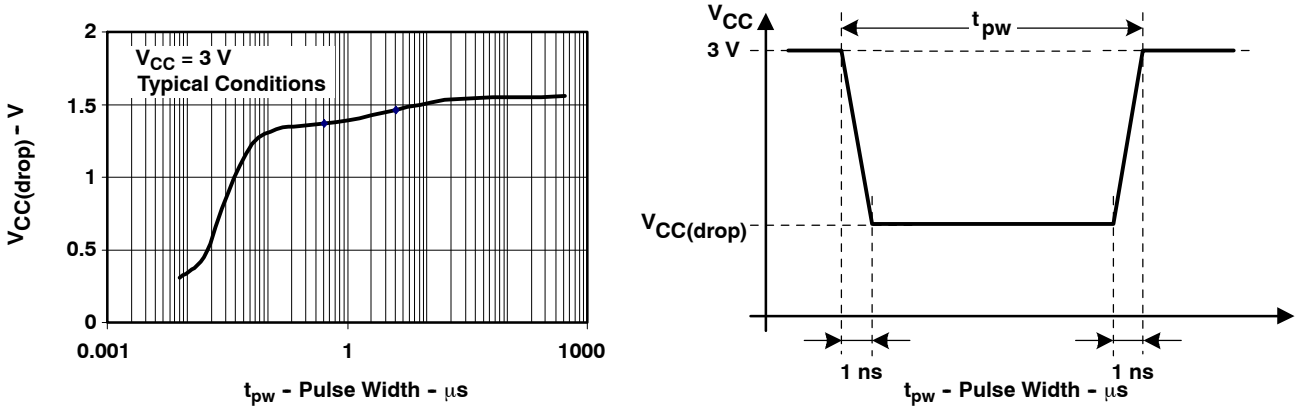


Figure 9. $V_{CC(drop)}$ Level With a Square Voltage Drop to Generate a POR/Brownout Signal

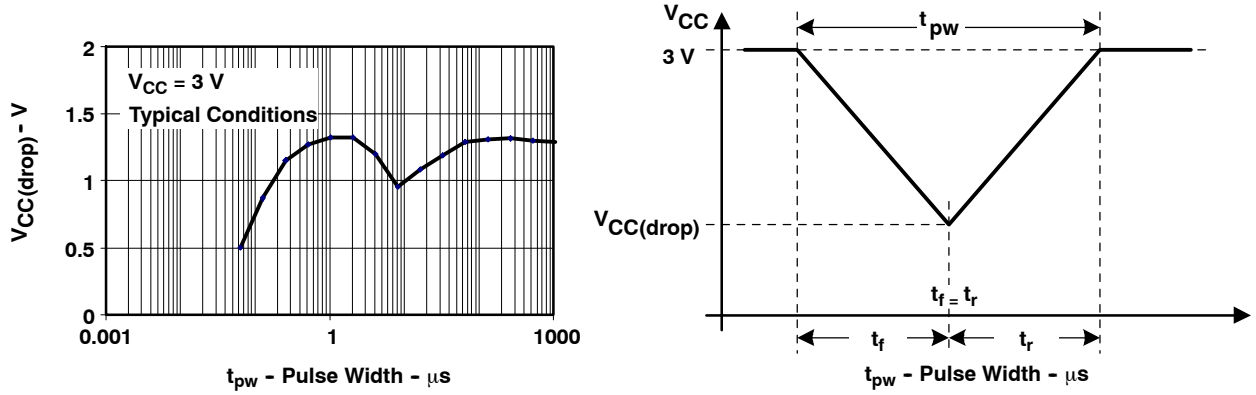


Figure 10. $V_{CC(drop)}$ Level With a Triangle Voltage Drop to Generate a POR/Brownout Signal

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (continued)

SVS (supply voltage supervisor/monitor) (see Note 1)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
$t_{(SVSR)}$	dV_{CC}/dt > 30 V/ms (see Figure 11)		5		150	µs
	dV_{CC}/dt ≤ 30 V/ms				2000	µs
$t_{d(SVSon)}$	SVSon, switch from VLD = 0 to VLD ≠ 0, V_{CC} = 3 V			150	300	µs
t_{settle}	VLD ≠ 0 (see Note 2)				12	µs
$V_{(SVSstart)}$	VLD ≠ 0, V_{CC}/dt ≤ 3 V/s (see Figure 11)			1.55	1.7	V
$V_{hys(SVS\_IT-)}$	V_{CC}/dt ≤ 3 V/s (see Figure 11)	VLD = 1	70	120	155	mV
		VLD = 2 to 14	$V_{(SVS\_IT-)}$ × 0.001		$V_{(SVS\_IT-)}$ × 0.016	
	V_{CC}/dt ≤ 3 V/s (see Figure 11), External voltage applied on A7	VLD = 15	4.4		10.4	mV
$V_{(SVS\_IT-)}$	V_{CC}/dt ≤ 3 V/s (see Figure 11)	VLD = 1	1.8	1.9	2.05	V
		VLD = 2	1.94	2.1	2.25	
		VLD = 3	2.05	2.2	2.37	
		VLD = 4	2.14	2.3	2.48	
		VLD = 5	2.24	2.4	2.6	
		VLD = 6	2.33	2.5	2.71	
		VLD = 7	2.46	2.65	2.86	
		VLD = 8	2.58	2.8	3	
		VLD = 9	2.69	2.9	3.13	
		VLD = 10	2.83	3.05	3.29	
		VLD = 11	2.94	3.2	3.42	
		VLD = 12	3.11	3.35	3.61†	
		VLD = 13	3.24	3.5	3.76†	
		VLD = 14	3.43	3.7†	3.99†	
	V_{CC}/dt ≤ 3 V/s (see Figure 11), External voltage applied on A7	VLD = 15	1.1	1.2	1.3	
$I_{CC(SVS)}$ (see Note 1)	VLD ≠ 0, V_{CC} = 2.2 V/3 V			10	15	µA

† The recommended operating voltage range is limited to 3.6 V.

NOTES: 1. The current consumption of the SVS module is not included in the I_{CC} current consumption data.
2. t_{settle} is the settling time that the comparator output needs to have a stable level after VLD is switched VLD ≠ 0 to a different VLD value somewhere between 2 and 15. The overdrive is assumed to be > 50 mV.

typical characteristics

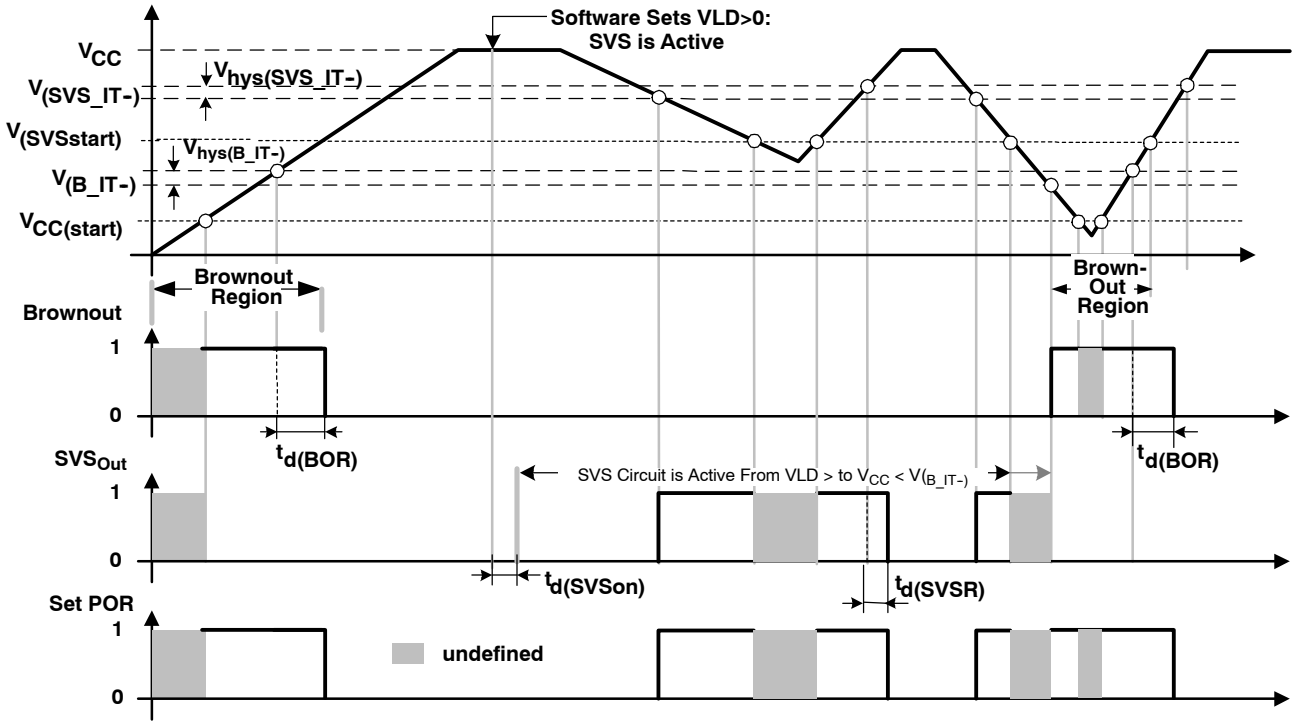


Figure 11. SVS Reset (SVSR) vs Supply Voltage

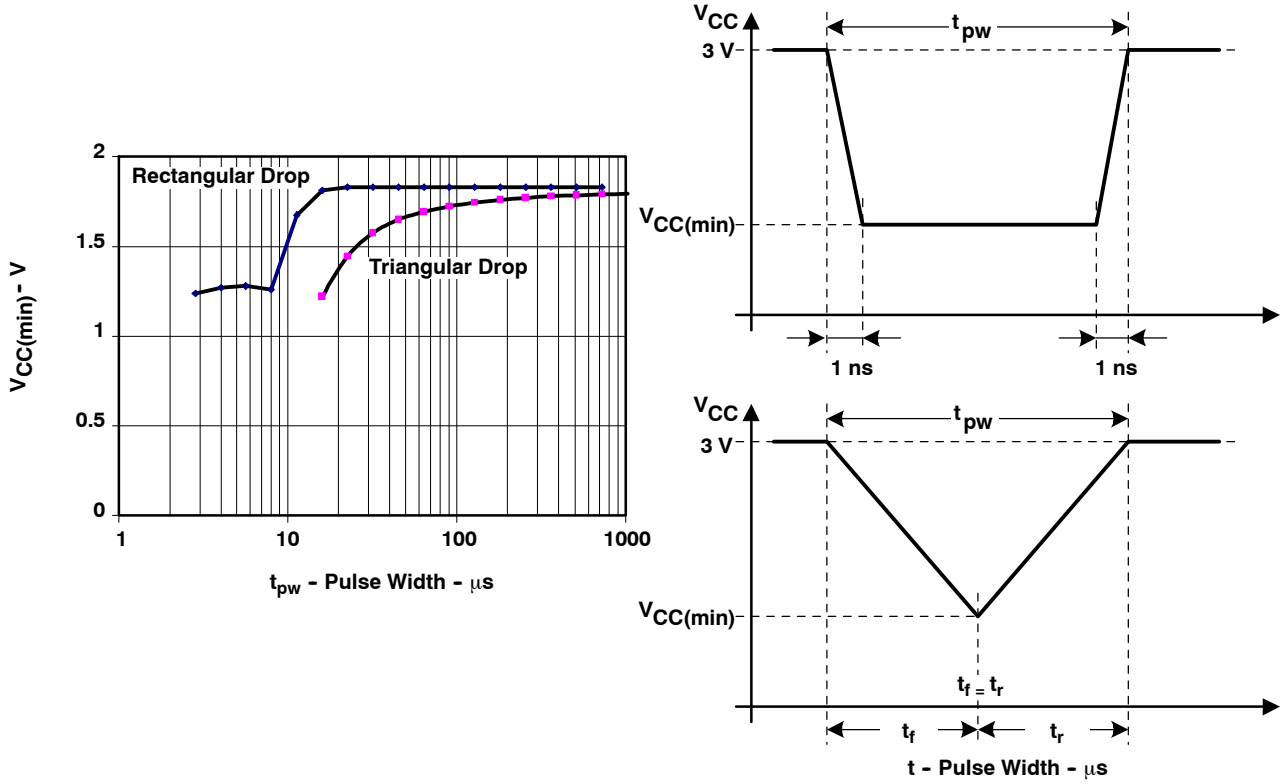


Figure 12. $V_{CC(min)}$ With a Square Voltage Drop and a Triangle Voltage Drop to Generate an SVS Signal

electrical characteristics over recommended operating free-air temperature (unless otherwise noted)

DCO

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
$f_{(DCOCLK)}$	$N_{(DCO)}$ = 01Eh, FN_8 = FN_4 = FN_3 = FN_2 = 0, D = 2, DCOPLUS = 0	V_{CC} = 2.2 V/3 V		1		MHz
$f_{(DCO = 2)}$	FN_8 = FN_4 = FN_3 = FN_2 = 0, DCOPLUS = 1	V_{CC} = 2.2 V	0.3	0.65	1.25	MHz
		V_{CC} = 3 V	0.3	0.7	1.3	
$f_{(DCO = 27)}$	FN_8 = FN_4 = FN_3 = FN_2 = 0, DCOPLUS = 1	V_{CC} = 2.2 V	2.5	5.6	10.5	MHz
		V_{CC} = 3 V	2.7	6.1	11.3	
$f_{(DCO = 2)}$	FN_8 = FN_4 = FN_3 = 0, FN_2 = 1, DCOPLUS = 1	V_{CC} = 2.2 V	0.7	1.3	2.3	MHz
		V_{CC} = 3 V	0.8	1.5	2.5	
$f_{(DCO = 27)}$	FN_8 = FN_4 = FN_3 = 0, FN_2 = 1, DOPLUS = 1	V_{CC} = 2.2 V	5.7	10.8	18	MHz
		V_{CC} = 3 V	6.5	12.1	20	
$f_{(DCO = 2)}$	FN_8 = FN_4 = 0, FN_3 = 1, FN_2 = x, DCOPLUS = 1	V_{CC} = 2.2 V	1.2	2	3	MHz
		V_{CC} = 3 V	1.3	2.2	3.5	
$f_{(DCO = 27)}$	FN_8 = FN_4 = 0, FN_3 = 1, FN_2 = x, DCOPLUS = 1	V_{CC} = 2.2 V	9	15.5	25	MHz
		V_{CC} = 3 V	10.3	17.9	28.5	
$f_{(DCO = 2)}$	FN_8 = 0, FN_4 = 1, FN_3 = FN_2 = x, DCOPLUS = 1	V_{CC} = 2.2 V	1.8	2.8	4.2	MHz
		V_{CC} = 3 V	2.1	3.4	5.2	
$f_{(DCO = 27)}$	FN_8 = 0, FN_4 = 1, FN_3 = FN_2 = x, DCOPLUS = 1	V_{CC} = 2.2 V	13.5	21.5	33	MHz
		V_{CC} = 3 V	16	26.6	41	
$f_{(DCO = 2)}$	FN_8 = 1, FN_4 = FN_3 = FN_2 = x, DCOPLUS = 1	V_{CC} = 2.2 V	2.8	4.2	6.2	MHz
		V_{CC} = 3 V	4.2	6.3	9.2	
$f_{(DCO = 27)}$	FN_8 = 1,FN_4 = FN_3 = FN_2 = x, DCOPLUS = 1	V_{CC} = 2.2 V	21	32	46	MHz
		V_{CC} = 3 V	30	46	70	
S_n	Step size between adjacent DCO taps: $S_n = f_{DCO(Tap\ n+1)} / f_{DCO(Tap\ n)}$, (see Figure 14 for taps 21 to 27)	1 < TAP ≤ 20	1.06		1.11	
		TAP = 27	1.07		1.17	
D_t	Temperature drift, $N_{(DCO)}$ = 01Eh, FN_8 = FN_4 = FN_3 = FN_2 = 0 D = 2, DCOPLUS = 0	V_{CC} = 2.2 V	–0.2	–0.4	–0.6	%/°C
		V_{CC} = 3 V	–0.2	–0.4	–0.6	
D_V	Drift with V_{CC} variation, $N_{(DCO)}$ = 01Eh, FN_8 = FN_4 = FN_3 = FN_2 = 0, D = 2, DCOPLUS = 0	V_{CC} = 2.2 V/3 V	0	5	15	%/V

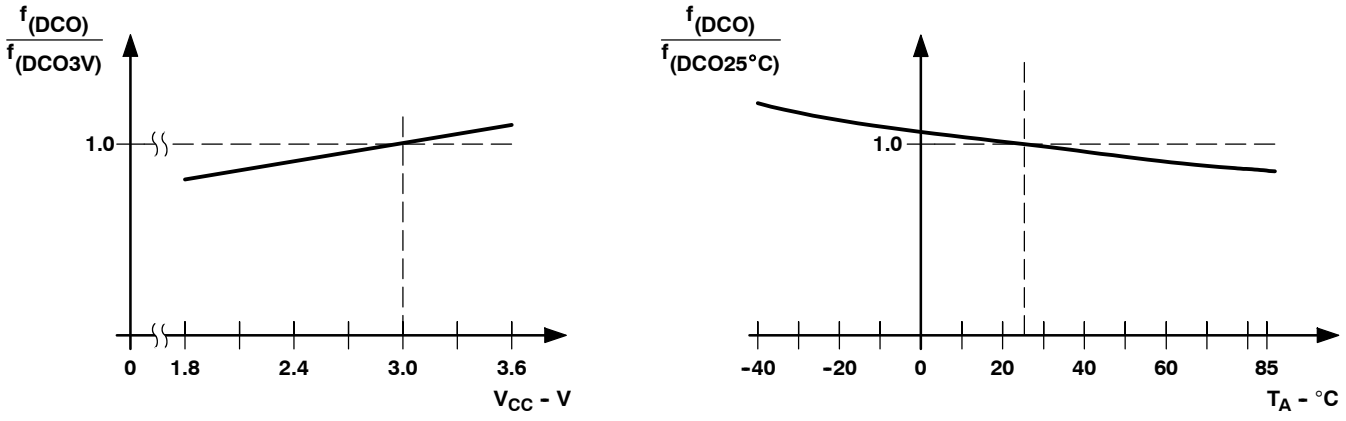


Figure 13. DCO Frequency vs Supply Voltage V_{CC} and vs Ambient Temperature

electrical characteristics over recommended operating free-air temperature (unless otherwise noted)

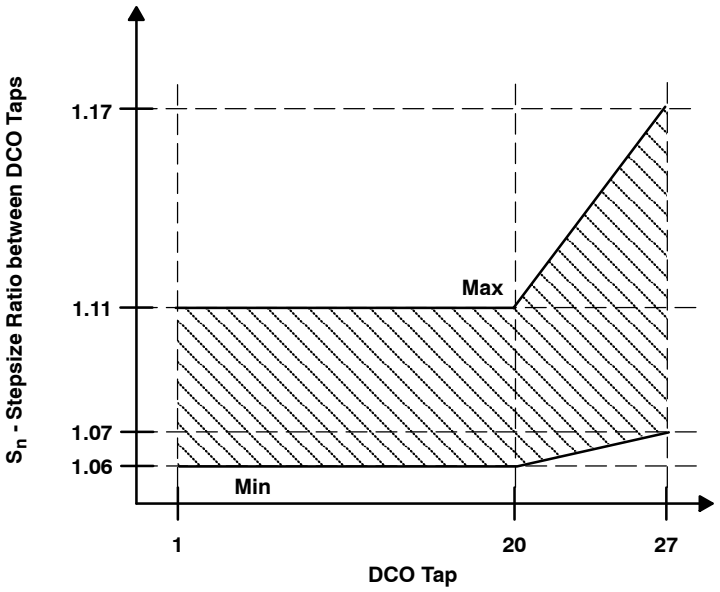


Figure 14. DCO Tap Step Size

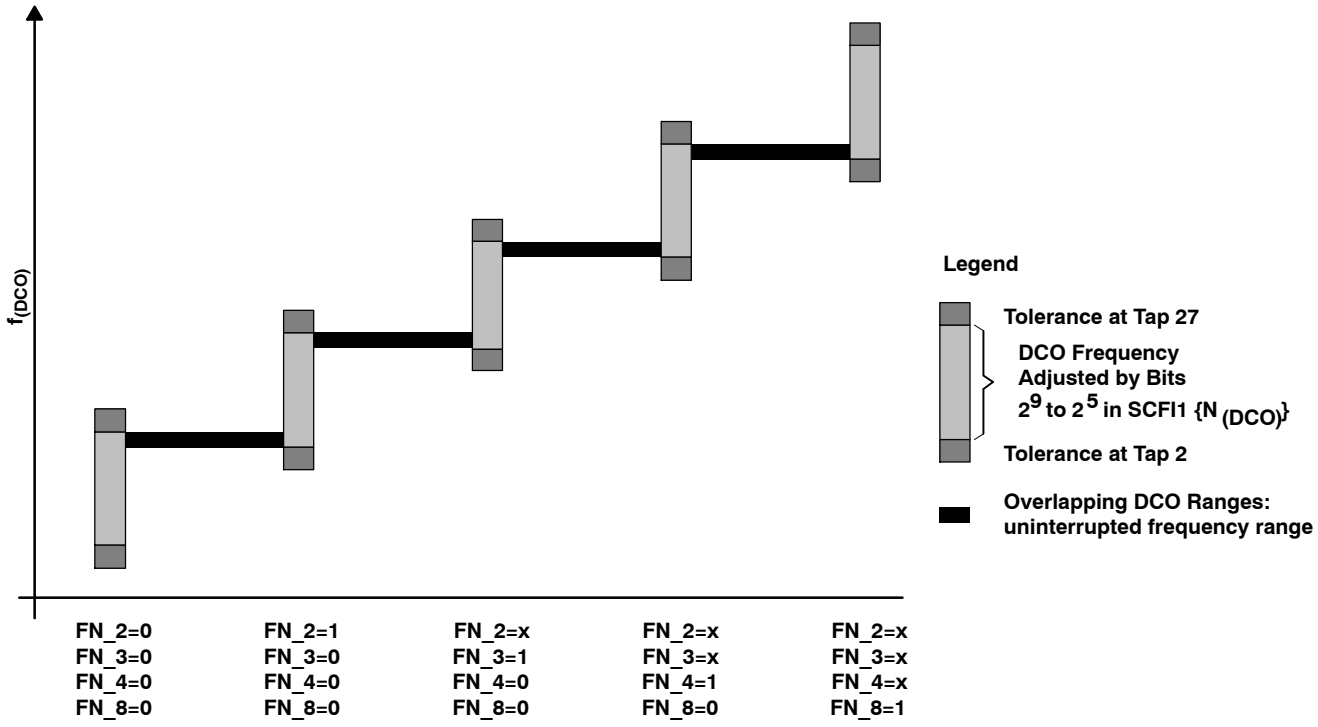


Figure 15. Five Overlapping DCO Ranges Controlled by FN_x Bits

electrical characteristics over recommended operating free-air temperature (unless otherwise noted) (continued)

crystal oscillator, LFXT1, low-frequency mode (see Note 4)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
$f_{LFXT1,LF}$	LFXT1 oscillator crystal frequency, LF mode	XTS = 0	1.8 V to 3.6 V		32768		Hz
OA_{LF}	Oscillation allowance for LF crystals	XTS = 0, LFXT1Sx = 0, $f_{LFXT1,LF}$ = 32768 Hz, $C_{L,eff}$ = 6 pF			500		kΩ
		XTS = 0, LFXT1Sx = 0, $f_{LFXT1,LF}$ = 32768 Hz, $C_{L,eff}$ = 12 pF			200		kΩ
$C_{L,eff}$	Integrated effective load capacitance, LF mode (see Note 1)	XTS = 0, XCAPxPF = 0			1		pF
		XTS = 0, XCAPxPF = 1			5.5		pF
		XTS = 0, XCAPxPF = 2			8.5		pF
		XTS = 0, XCAPxPF = 3			11		pF
Duty Cycle	LF mode	XTS = 0, $f_{LFXT1,LF}$ = 32768 Hz Measured at P1.5/TACLK/ACLK	2.2 V/3 V	30	50	70	%
$f_{Fault,LF}$	Oscillator fault frequency, LF mode (see Note 3)	XTS = 0 (see Note 2)	2.2 V/3 V	10		10,000	Hz

NOTES: 1. Includes parasitic bond and package capacitance (approximately 2 pF per pin).
Since the PCB adds additional capacitance it is recommended to verify the correct load by measuring the ACLK frequency. For a correct setup the effective load capacitance should always match the specification of the used crystal.
2. Measured with logic level input frequency but also applies to operation with crystals.
3. Frequencies below the MIN specification will set the fault flag, frequencies above the MAX specification will not set the fault flag. Frequencies in between might set the flag.
4. To improve EMI on the LFXT1 oscillator the following guidelines should be observed.
   - Keep the trace between the device and the crystal as short as possible.
   - Design a good ground plane around the oscillator pins.
   - Prevent crosstalk from other clock or data lines into oscillator pins XIN and XOUT.
   - Avoid running PCB traces underneath or adjacent to the XIN and XOUT pins.
   - Use assembly materials and praxis to avoid any parasitic load on the oscillator XIN and XOUT pins.
   - If conformal coating is used, ensure that it does not induce capacitive/resistive leakage between the oscillator pins.
   - Do not route the XOUT line to the JTAG header to support the serial programming adapter as shown in other documentation. This signal is no longer required for the serial programming adapter.

crystal oscillator, LFXT1, high-frequency mode

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
f_{XT1}	XT1 oscillator crystal frequency	XTS = 1, Ceramic resonator	1.8 V to 3.6 V	0.45		6	MHz
f_{XT1}	XT1 oscillator crystal frequency	XTS = 1, Crystal	1.8 V to 3.6 V	1		6	MHz
$C_{L,eff}$	Integrated effective load capacitance (see Note 1)	(see Note 2)			1		pF
Duty Cycle		Measured at P1.5/TACLK/ACLK	2.2 V/3 V	40	50	60	%

NOTES: 1. Includes parasitic bond and package capacitance (approximately 2pF per pin).
Since the PCB adds additional capacitance it is recommended to verify the correct load by measuring the ACLK frequency. For a correct setup the effective load capacitance should always match the specification of the used crystal.
2. Requires external capacitors at both terminals. Values are specified by crystal manufacturers.

electrical characteristics over recommended operating free-air temperature (unless otherwise noted) (continued)

crystal oscillator, XT2 oscillator (see Note 5)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
$f_{XT2,0}$	XT2 oscillator crystal frequency, mode 0	XT2Sx = 0	1.8 V to 3.6 V	0.4		1	MHz
$f_{XT2,1}$	XT2 oscillator crystal frequency, mode 1	XT2Sx = 1	1.8 V to 3.6 V	1		4	MHz
$f_{XT2,2}$	XT2 oscillator crystal frequency, mode 2	XT2Sx = 2	1.8 V to 3.6 V	2		10	MHz
			2.2 V to 3.6 V	2		12	MHz
			3.0 V to 3.6 V	2		16	MHz
$f_{XT2,logic}$	XT2 oscillator logic level square wave input frequency	XT2Sx = 3	1.8 V to 3.6 V	0.4		10	MHz
			2.2 V to 3.6 V	0.4		12	MHz
			3.0 V to 3.6 V	0.4		16	MHz
OA_{XT2}	Oscillation allowance for HF crystals (see Figure 16)	XT2Sx = 0, f_{XT2} = 1 MHz, $C_{L,eff}$ = 15 pF			2700		Ω
		XT2Sx = 1 f_{XT2} = 4 MHz, $C_{L,eff}$ = 15 pF			800		Ω
		XT2Sx = 2 f_{XT2} = 16 MHz, $C_{L,eff}$ = 15 pF			300		Ω
$C_{L,eff}$	Integrated effective load capacitance (see Note 1)	(see Note 2)			1		pF
Duty cycle		Measured at P1.5/TACLK/ACLK, f_{XT2} = 10 MHz	2.2 V/3 V	40	50	60	%
		Measured at P1.5/TACLK/ACLK, f_{XT2} = 16 MHz	2.2 V/3 V	40	50	60	%
$f_{Fault,XT2}$	Oscillator fault frequency (see Note 4)	XT2Sx = 3 (see Notes 3)	2.2 V/3 V	30		300	kHz

NOTES: 1. Includes parasitic bond and package capacitance (approximately 2pF per pin).
Since the PCB adds additional capacitance it is recommended to verify the correct load by measuring the frequency. For a correct setup the effective load capacitance should always match the specification of the used crystal.
2. Requires external capacitors at both terminals. Values are specified by crystal manufacturers.
3. Measured with logic level input frequency but also applies to operation with crystals.
4. Frequencies below the MIN specification will set the fault flag, frequencies above the MAX specification will not set the fault flag. Frequencies in between might set the flag.
5. To improve EMI on the XT2 oscillator the following guidelines should be observed.
   - Keep the trace between the device and the crystal as short as possible.
   - Design a good ground plane around the oscillator pins.
   - Prevent crosstalk from other clock or data lines into oscillator pins XT2IN and XT2OUT.
   - Avoid running PCB traces underneath or adjacent to the XT2IN and XT2OUT pins.
   - Use assembly materials and praxis to avoid any parasitic load on the oscillator XT2IN and XT2OUT pins.
   - If conformal coating is used, ensure that it does not induce capacitive/resistive leakage between the oscillator pins.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (continued)

typical characteristics – XT2 oscillator

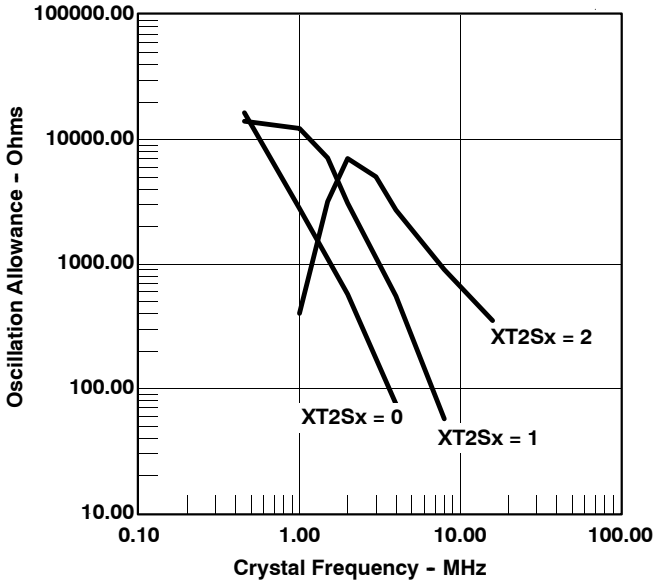


Figure 16. Oscillation Allowance vs Crystal Frequency, $C_{L,eff}$ = 15 pF, T_A = 25°C

electrical characteristics over recommended operating free-air temperature (unless otherwise noted) (continued)

wake-up LPM3

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
$t_{d(LPM3)}$	Delay time	f = 1 MHz	2.2 V/3 V		6	µs
		f = 2 MHz			6	
		f = 3 MHz			6	

LCD_A

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
$V_{CC(LCD)}$	Supply voltage range	Charge pump enabled (LCDCPEN = 1, VLCDx > 0000)		2.2		3.6	V
C_{LCD}	Capacitor on LCDCAP (see Note 1)	Charge pump enabled (LCDCPEN = 1, VLCDx > 0000)		4.7			µF
$I_{CC(LCD)}$	Supply current	$V_{LCD(typ)}$ = 3 V, LCDCPEN = 1, VLCDx = 1000, all segments on, $f_{LCD} = f_{ACLK}/32$ no LCD connected (see Note 2), T_A = 25°C	2.2 V		3.8		µA
f_{LCD}	LCD frequency					1.1	kHz
V_{LCD}	LCD voltage	VLCDx = 0000			V_{CC}		V
V_{LCD}	LCD voltage	VLCDx = 0001			2.60		V
V_{LCD}	LCD voltage	VLCDx = 0010			2.66		V
V_{LCD}	LCD voltage	VLCDx = 0011			2.72		V
V_{LCD}	LCD voltage	VLCDx = 0100			2.78		V
V_{LCD}	LCD voltage	VLCDx = 0101			2.84		V
V_{LCD}	LCD voltage	VLCDx = 0110			2.90		V
V_{LCD}	LCD voltage	VLCDx = 0111			2.96		V
V_{LCD}	LCD voltage	VLCDx = 1000			3.02		V
V_{LCD}	LCD voltage	VLCDx = 1001			3.08		V
V_{LCD}	LCD voltage	VLCDx = 1010			3.14		V
V_{LCD}	LCD voltage	VLCDx = 1011			3.20		V
V_{LCD}	LCD voltage	VLCDx = 1100			3.26		V
V_{LCD}	LCD voltage	VLCDx = 1101			3.32		V
V_{LCD}	LCD voltage	VLCDx = 1110			3.38		V
V_{LCD}	LCD voltage	VLCDx = 1111			3.44	3.60	V
R_{LCD}	LCD driver output impedance	V_{LCD} = 3 V, LCDCPEN = 1, VLCDx = 1000, I_{LOAD} = ±10 µA	2.2 V			10	kΩ

NOTES: 1. Enabling the internal charge pump with an external capacitor smaller than the minimum specified might damage the device.
2. Connecting an actual display will increase the current consumption depending on the size of the LCD.

electrical characteristics over recommended operating free-air temperature (unless otherwise noted) (continued)

Comparator_A (see Note 1)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
$I_{(CC)}$		CAON = 1, CARSEL = 0, CAREF = 0	2.2 V		25	40	μA
			3 V		45	60	
$I_{(Refladder/RefDiode)}$		CAON = 1, CARSEL = 0, CAREF = 1/2/3, No load at P2.6/CA0 and P2.7/CA1	2.2 V		30	50	μA
			3 V		45	80	
$V_{(Ref025)}$	$\frac{\text{Voltage @ 0.25 } V_{CC} \text{ node}}{V_{CC}}$	PCA0 = 1, CARSEL = 1, CAREF = 1, No load at P2.6/CA0 and P2.7/CA1	2.2 V / 3 V	0.23	0.24	0.25	
$V_{(Ref050)}$	$\frac{\text{Voltage @ 0.5 } V_{CC} \text{ node}}{V_{CC}}$	PCA0 = 1, CARSEL = 1, CAREF = 2, No load at P2.6/CA0 and P2.7/CA1	2.2V / 3 V	0.47	0.48	0.5	
$V_{(RefVT)}$	See Figure 17 and Figure 18	PCA0 = 1, CARSEL = 1, CAREF = 3, No load at P2.6/CA0 and P2.7/CA1, $T_{A\ =}$ 85°C	2.2 V	390	480	540	mV
			3 V	400	490	550	
V_{IC}	Common-mode input voltage range	CAON = 1	2.2 V / 3 V	0		V_{CC}–1	V
V_p–V_S	Offset voltage	See Note 2	2.2 V / 3 V	–30		30	mV
V_{hys}	Input hysteresis	CAON = 1	2.2 V / 3 V	0	0.7	1.4	mV
$t_{(response\ LH\ and\ HL)}$ (See Note 3)		T_A = 25°C, Overdrive 10 mV, without filter: CAF = 0	2.2 V	80	165	300	ns
			3 V	70	120	240	
		T_A = 25°C Overdrive 10 mV, with filter: CAF = 1	2.2 V	1.4	1.9	2.8	μs
			3 V	0.9	1.5	2.2	

NOTES: 1. The leakage current for the Comparator_A terminals is identical to $I_{lkg(Px.x)}$ specification.
2. The input offset voltage can be cancelled by using the CAEX bit to invert the Comparator_A inputs on successive measurements. The two successive measurements are then summed together.
3. The response time is measured at P2.6/CA0 with an input voltage step and the Comparator_A already enabled (CAON = 1). If CAON is set at the same time, a settling time of up to 300 ns is added to the response time.

electrical characteristics over recommended operating free-air temperature (unless otherwise noted) (continued)

typical characteristics

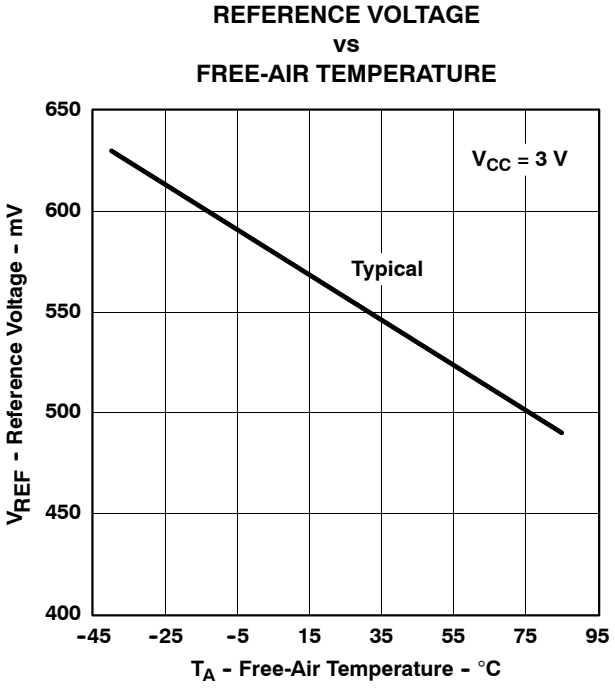


Figure 17. $V_{(RefVT)}$ vs Temperature

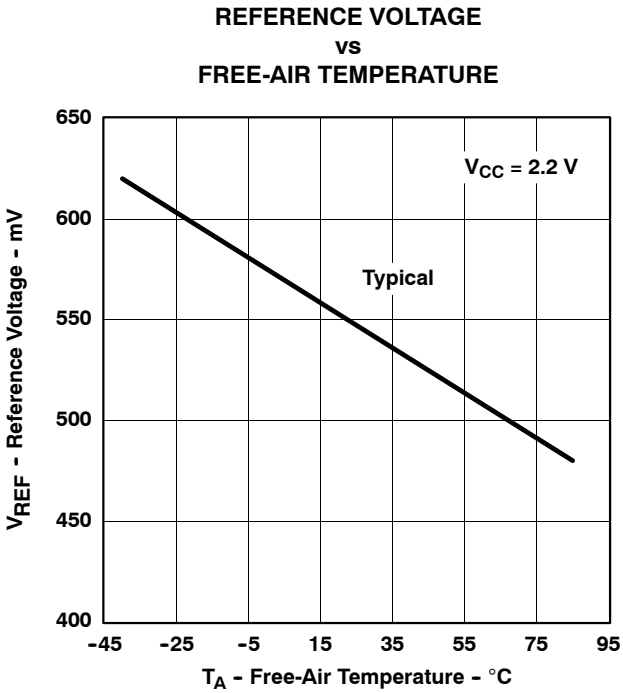


Figure 18. $V_{(RefVT)}$ vs Temperature

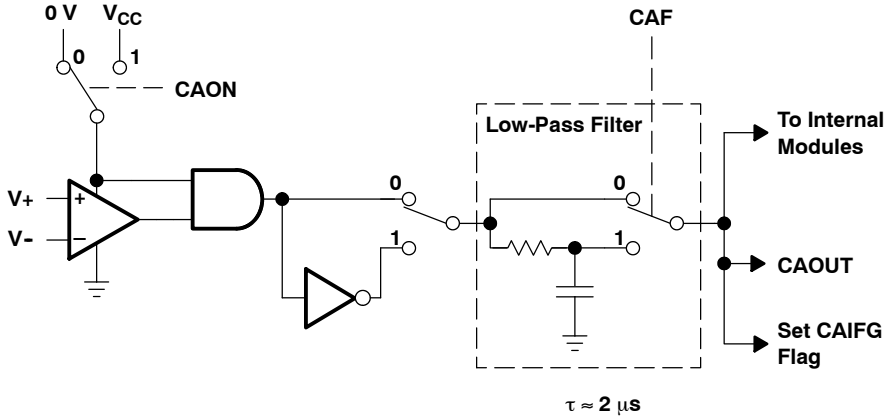


Figure 19. Block Diagram of Comparator_A Module

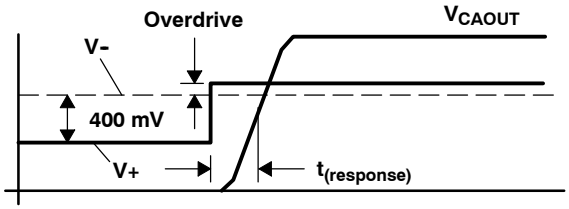


Figure 20. Overdrive Definition

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (continued)

Timer_A

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
f_{TA}	Timer_A clock frequency	Internal: SMCLK, ACLK, External: TACLK, INCLK, Duty cycle = 50% ±10%	2.2 V		10	MHz
			3 V		16	
$t_{TA,cap}$	Timer_A, capture timing	TA0, TA1, TA2	2.2 V/3 V	20		ns

Timer_B

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
f_{TB}	Timer_B clock frequency	Internal: SMCLK, ACLK, External: TBCLK, Duty cycle = 50% ±10%	2.2 V		10	MHz
			3 V		16	
$t_{TB,cap}$	Timer_B, capture timing	TB0, TB1, TB2	2.2 V/3 V	20		ns

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (continued)

USCI (UART mode) – recommended operating conditions

PARAMETER		CONDITIONS	MIN	MAX	UNIT
f_{USCI}	USCI input clock frequency	Internal: SMCLK, ACLK External: UCLK Duty cycle = 50% ± 10%		f_{SYSTEM}	MHz
f_{BITCLK}	BITCLK clock frequency (equals baud rate in MBaud)			1	MHz

USCI (UART mode)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
t_τ	UART receive deglitch time (see Note 1)		2.2 V	50	150	600	ns
			3 V	50	100	600	ns

NOTES: 1. Pulses on the UART receive input (UCxRX) shorter than the UART receive deglitch time are suppressed. To ensure that pulses are correctly recognized their width should exceed the maximum specification of the deglitch time.

USCI (SPI master mode) – recommended operating conditions

PARAMETER		CONDITIONS	MIN	MAX	UNIT
f_{USCI}	USCI input clock frequency	SMCLK, ACLK Duty cycle = 50% ± 10%		f_{SYSTEM}	MHz

USCI (SPI master mode) (see Note 1, Figure 21, and Figure 22)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	MAX	UNIT
f_{USCI}	USCI input clock frequency	SMCLK, ACLK Duty cycle = 50% ± 10%			f_{SYSTEM}	MHz
$t_{SU,MI}$	SOMI input data setup time		2.2 V	110		ns
			3 V	75		ns
$t_{HD,MI}$	SOMI input data hold time		2.2 V	0		ns
			3 V	0		ns
$t_{VALID,MO}$	SIMO output data valid time (Note 2)	UCLK edge to SIMO valid, C_L = 20 pF	2.2 V		30	ns
			3 V		20	ns
$t_{HD,MO}$	SIMO output data hold time (Note 3)	C_L = 20 pF	2.2 V	0		ns
			3 V	0		ns

NOTES: 1. $f_{UCxCLK} = \frac{1}{2t_{LO/HI}}$ with $t_{LO/HI} \geq \max(t_{VALID,MO(USCI)} + t_{SU,SI(Slave)}, t_{SU,MI(USCI)} + t_{VALID,SO(Slave)})$.
For the slave's parameters $t_{SU,SI(Slave)}$ and $t_{VALID,SO(Slave)}$ refer to the SPI parameters of the attached slave.
2. Specifies the time to drive the next valid data to the SIMO output after the output changing UCLK clock edge. Refer to the timing diagrams in Figure 21 and Figure 22.
3. Specifies how long data on the SIMO output is valid after the output changing UCLK clock edge. Negative values indicate that the data on the SIMO output can become invalid before the output changing clock edge observed on UCLK. Refer to the timing diagrams in Figure 21 and Figure 22.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (continued)

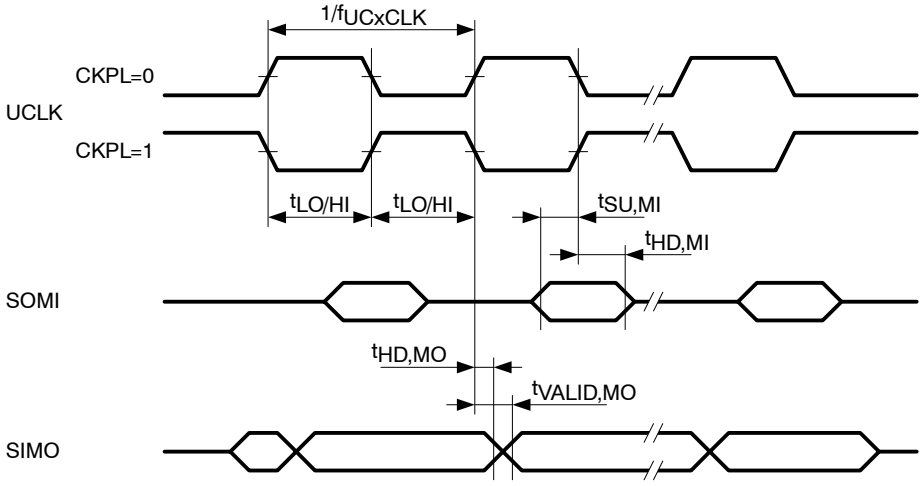


Figure 21. SPI Master Mode, CKPH = 0

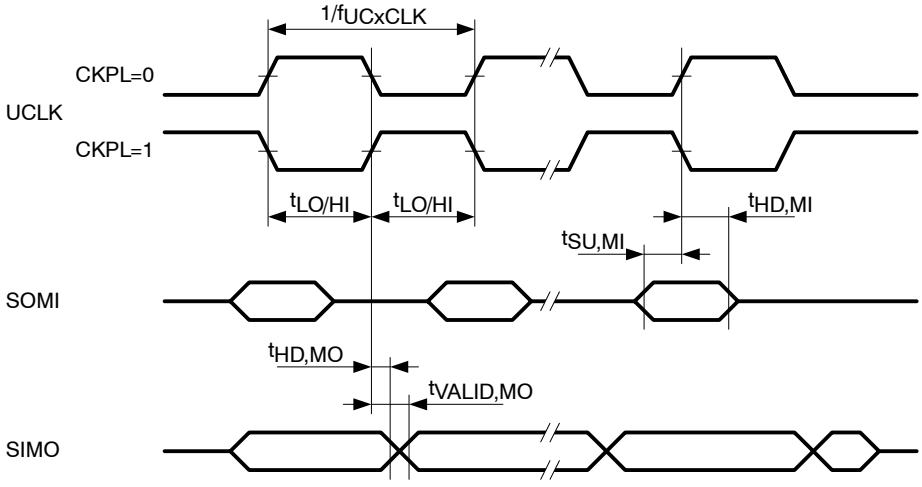


Figure 22. SPI Master Mode, CKPH = 1

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (continued)

USCI (SPI slave mode) (see Note 1, Figure 23, and Figure 24)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
$t_{STE,LEAD}$	STE lead time STE low to clock		2.2 V/3 V		50		ns
$t_{STE,LAG}$	STE lag time Last clock to STE high		2.2 V/3 V	10			ns
$t_{STE,ACC}$	STE access time STE low to SOMI data out		2.2 V/3 V		50		ns
$t_{STE,DIS}$	STE disable time STE high to SOMI high impedance		2.2 V/3 V		50		ns
$t_{SU,SI}$	SIMO input data setup time		2.2 V	20			ns
			3 V	15			ns
$t_{HD,SI}$	SIMO input data hold time		2.2 V	10			ns
			3 V	10			ns
$t_{VALID,SO}$	SOMI output data valid time (Note 2)	UCLK edge to SOMI valid, C_L = 20 pF	2.2 V		75	110	ns
			3 V		50	75	ns
$t_{HD,MO}$	SOMI output data hold time (Note 3)	C_L = 20 pF	2.2 V	0			ns
			3 V	0			ns

NOTES: 1. $f_{UCxCLK} = \frac{1}{2t_{LO/HI}}$ with $t_{LO/HI} \geq \max(t_{VALID,MO(Master)} + t_{SU,SI(USCI)}, t_{SU,MI(Master)} + t_{VALID,SO(USCI)})$.
For the master's parameters $t_{SU,MI(Master)}$ and $t_{VALID,MO(Master)}$ refer to the SPI parameters of the attached master.
2. Specifies the time to drive the next valid data to the SOMI output after the output changing UCLK clock edge. Refer to the timing diagrams in Figure 23 and Figure 24.
3. Specifies how long data on the SOMI output is valid after the output changing UCLK clock edge. Negative values indicate that the data on the SOMI output can become invalid before the output changing clock edge observed on UCLK. Refer to the timing diagrams in Figure 23 and Figure 24.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (continued)

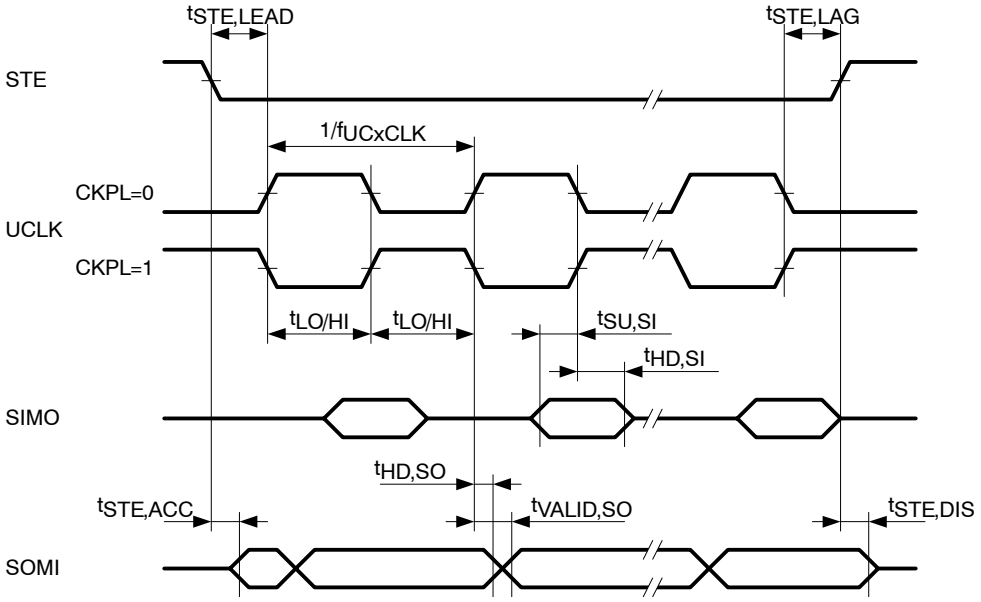


Figure 23. SPI Slave Mode, CKPH = 0

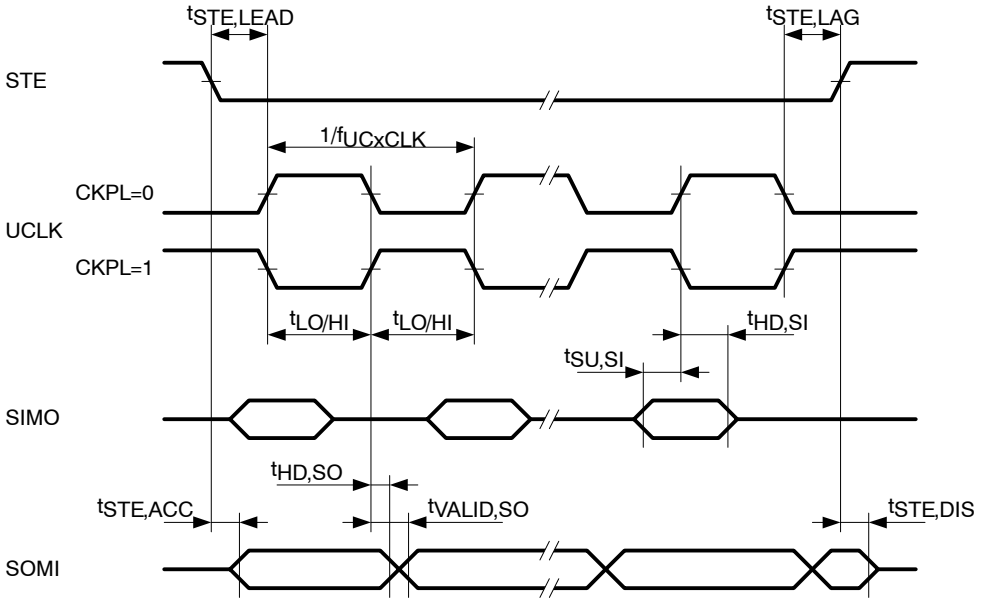


Figure 24. SPI Slave Mode, CKPH = 1

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (continued)

USCI (I2C mode) (see Figure 25)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
f_{USCI}	USCI input clock frequency	Internal: SMCLK, ACLK External: UCLK Duty cycle = 50% ± 10%				f_{SYSTEM}	MHz
f_{SCL}	SCL clock frequency		2.2 V/3 V	0		400	kHz
$t_{HD,STA}$	Hold time (repeated) START	f_{SCL} ≤ 100kHz (standard mode)	2.2 V/3 V	4.0			µs
		f_{SCL} > 100kHz (fast mode)	2.2 V/3 V	0.6			µs
$t_{SU,STA}$	Setup time for a repeated START	f_{SCL} ≤ 100kHz (standard mode)	2.2 V/3 V	4.7			µs
		f_{SCL} > 100kHz (fast mode)	2.2 V/3 V	0.6			µs
$t_{HD,DAT}$	Data hold time		2.2 V/3 V	0			ns
$t_{SU,DAT}$	Data setup time		2.2 V/3 V	250			ns
$t_{SU,STO}$	Setup time for STOP	f_{SCL} ≤ 100kHz (standard mode)	2.2 V/3 V	4.0			µs
		f_{SCL} > 100kHz (fast mode)	2.2 V/3 V	0.6			µs
t_{SP}	Pulse width of spikes suppressed by input filter		2.2 V	50	150	600	ns
			3 V	50	100	600	ns

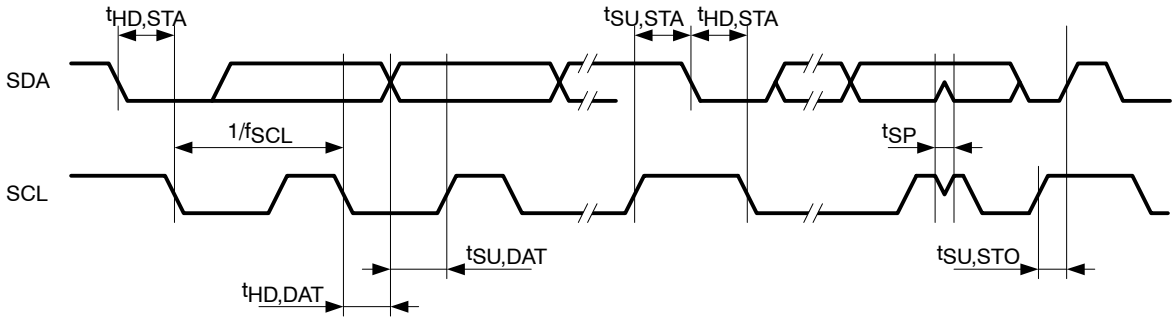


Figure 25. I2C Mode Timing

electrical characteristics over recommended operating free-air temperature (unless otherwise noted) (continued)

SD16_A, power supply and recommended operating conditions

PARAMETER		TEST CONDITIONS		V_{CC}	MIN	TYP	MAX	UNIT
AV_{CC}	Analog supply voltage	$AV_{CC} = DV_{CC}$ $AV_{SS} = DV_{SS} = 0V$			2.5		3.6	V
I_{SD16}	Analog supply current: 1 active SD16_A channel including internal reference	SD16LP = 0, f_{SD16} = 1 MHz, SD16OSR = 256	GAIN: 1,2	3 V		800	1100	µA
			GAIN: 4,8,16	3 V		900	1200	
			GAIN: 32	3 V		1200	1700	
		SD16LP = 1, f_{SD16} = 0.5 MHz, SD16OSR = 256	GAIN: 1	3 V		800	1100	
			GAIN: 32	3 V		900	1200	
f_{SD16}	Analog front-end input clock frequency	SD16LP = 0 (low-power mode disabled)		3 V	0.03	1	1.1	MHz
		SD16LP = 1 (low-power mode enabled)		3 V	0.03	0.5		

SD16_A, input range (see Note 1)

PARAMETER		TEST CONDITIONS		V_{CC}	MIN	TYP	MAX	UNIT
$V_{ID,FSR}$	Differential full scale input voltage range	Bipolar mode, SD16UNI = 0			$-V_{REF}/2GAIN$		$+V_{REF}/2GAIN$	mV
		Unipolar mode, SD16UNI = 1			0		$+V_{REF}/2GAIN$	mV
V_{ID}	Differential input voltage range for specified performance (see Note 2)	SD16REFON = 1	SD16GAINx = 1			±500		mV
			SD16GAINx = 2			±250		
			SD16GAINx = 4			±125		
			SD16GAINx = 8			±62		
			SD16GAINx = 16			±31		
			SD16GAINx = 32			±15		
Z_I	Input impedance (one input pin to AV_{SS})	f_{SD16} = 1 MHz	SD16GAINx = 1	3 V		200		kΩ
			SD16GAINx = 32	3 V		75		
Z_{ID}	Differential input impedance (IN+ to IN–)	f_{SD16} = 1 MHz	SD16GAINx = 1	3 V	300	400		kΩ
			SD16GAINx = 32	3 V	100	150		
V_I	Absolute input voltage range				AV_{SS} -1V		AV_{CC}	V
V_{IC}	Common-mode input voltage range				AV_{SS} -1V		AV_{CC}	V

NOTES: 1. All parameters pertain to each SD16_A channel.
2. The full-scale range is defined by $V_{FSR+} = +(V_{REF}/2)/GAIN$ and $V_{FSR-} = -(V_{REF}/2)/GAIN$.
If V_{REF} is sourced externally, the analog input range should not exceed 80% of V_{FSR+} or V_{FSR-}; i.e., V_{ID} = 0.8 V_{FSR-} to 0.8 V_{FSR+}.
If V_{REF} is sourced internally, the given V_{ID} ranges apply.

electrical characteristics over recommended operating free-air temperature (unless otherwise noted) (continued)

SD16_A, performance (f_{SD16} = 1 MHz, SD16OSRx = 256, SD16REFON = 1)

PARAMETER		TEST CONDITIONS		V_{CC}	MIN	TYP	MAX	UNIT
SINAD	Signal-to-noise + distortion ratio	SD16GAINx = 1, Signal amplitude V_{PP} = 500 mV	f_{IN} = 50 Hz, 100 Hz (see Note 1)	3 V	83	85		dB
		SD16GAINx = 2, Signal amplitude V_{PP} = 250 mV		3 V	81	84		
		SD16GAINx = 4, Signal amplitude V_{PP} = 125 mV		3 V	76	79		
		SD16GAINx = 8, Signal amplitude V_{PP} = 62 mV		3 V	73	76		
		SD16GAINx = 16, Signal amplitude V_{PP} = 31 mV		3 V	69	73		
		SD16GAINx = 32, Signal amplitude V_{PP} = 15 mV		3 V	62	69		
G	Nominal gain	SD16GAINx = 1		3 V	0.97	1.00	1.02	
		SD16GAINx = 2		3 V	1.90	1.96	2.02	
		SD16GAINx = 4		3 V	3.76	3.86	3.96	
		SD16GAINx = 8		3 V	7.36	7.62	7.84	
		SD16GAINx = 16		3 V	14.56	15.04	15.52	
		SD16GAINx = 32		3 V	27.20	28.35	29.76	
E_{OS}	Offset error	SD16GAINx = 1		3 V			±0.2	%FSR
		SD16GAINx = 32		3 V			±1.5	
dE_{OS}/dT	Offset error temperature coefficient	SD16GAINx = 1		3 V		±4	±20	ppm FSR/°C
		SD16GAINx = 32		3 V		±20	±100	
CMRR	Common-mode rejection ratio	SD16GAINx = 1, Common-mode input signal: V_{ID} = 500 mV, f_{IN} = 50 Hz, 100 Hz		3 V		>90		dB
		SD16GAINx = 32, Common-mode input signal: V_{ID} = 16 mV, f_{IN} = 50 Hz, 100 Hz		3 V		>75		
AC PSRR	AC power supply rejection ratio	SD16GAINx = 1, V_{CC} = 3 V ± 100 mV, f_{VCC} = 50 Hz		3 V		>80		dB
X_T	Crosstalk	SD16GAINx = 1, V_{ID} = 500 mV, f_{IN} = 50 Hz, 100 Hz		3 V		<–100		dB

NOTE 1: The following voltages were applied to the SD16_A inputs:
$V_{IN,A+}(t) = 0V + V_{PP}/2 \times \sin(2\pi \times f_{IN} \times t)$
$V_{IN,A-}(t) = 0V - V_{PP}/2 \times \sin(2\pi \times f_{IN} \times t)$
resulting in a differential voltage of $V_{diff} = V_{IN,A+}(t) - V_{IN,A-}(t) = V_{PP} \times \sin(2\pi \times f_{IN} \times t)$

electrical characteristics over recommended operating free-air temperature (unless otherwise noted) (continued)

typical characteristics – SD16_A SINAD performance over OSR

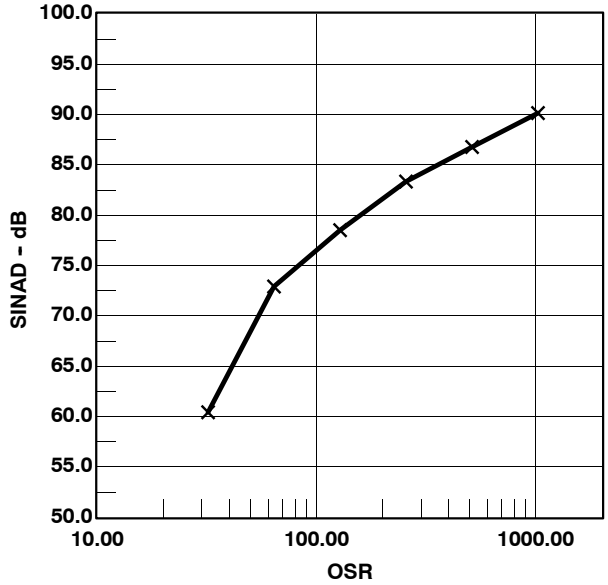


Figure 26. SINAD performance over OSR, f_{SD16} = 1 MHz, SD16REFON = 1, SD16GAINx = 1

SD16_A, temperature sensor and built-in V_{CC} sense

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
TC_{Sensor}	Sensor temperature coefficient			1.18	1.32	1.46	mV/K
$V_{Offset,sensor}$	Sensor offset voltage			–100		100	mV
V_{Sensor}	Sensor output voltage (see Note 2)	Temperature sensor voltage at T_A = 85°C	3 V	435	475	515	mV
		Temperature sensor voltage at T_A = 25°C	3 V	355	395	435	
		Temperature sensor voltage at T_A = 0°C	3 V	320	360	400	
$V_{CC,Sense}$	V_{CC} divider at input 5	f_{SD16} = 1 MHz, SD16OSRx = 256, SD16REFON = 1		0.08	1/11	0.1	V_{CC}
$R_{Source,VCC}$	Source resistance of V_{CC} divider at input 5				20		kΩ

NOTES: 1. The following formula can be used to calculate the temperature sensor output voltage:
$V_{Sensor,typ} = TC_{Sensor}$ (273 + T [°C]) + $V_{Offset,sensor}$ [mV]
2. Results based on characterization and/or production test, not TC_{Sensor} or $V_{Offset,sensor}$. Measured with f_{SD16} = 1 MHz, SD16OSRx = 256, SD16REFON = 1.

electrical characteristics over recommended operating free-air temperature (unless otherwise noted) (continued)

SD16_A, built-in voltage reference

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
V_{REF}	Internal reference voltage	SD16REFON = 1, SD16VMIDON = 0	3 V	1.14	1.20	1.26	V
I_{REF}	Reference supply current	SD16REFON = 1, SD16VMIDON = 0	3 V		175	260	μA
TC	Temperature coefficient	SD16REFON = 1, SD16VMIDON = 0 (see Note 1)	3 V		18	50	ppm/°C
C_{REF}	V_{REF} load capacitance	SD16REFON = 1, SD16VMIDON = 0 (see Note 2)			100		nF
I_{LOAD}	$V_{REF(I)}$ maximum load current	SD16REFON = 1, SD16VMIDON = 0	3 V			±200	nA
t_{ON}	Turn-on time	SD16REFON = 0->1, SD16VMIDON = 0, C_{REF} = 100nF	3 V		5		ms
DC PSR	DC power supply rejection $\Delta V_{REF}/\Delta V_{CC}$	SD16REFON = 1, SD16VMIDON = 0, V_{CC} = 2.5 V to 3.6 V			100		uV/V

NOTES: 1. Calculated using the box method: (MAX(-40...85°C) – MIN(-40...85°C)) / MIN(–40...85°C) / (85°C – (-40°C))
2. There is no capacitance required on V_{REF}. However, a capacitance of at least 100 nF is recommended to reduce any reference voltage noise.

SD16_A, reference output buffer

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
$V_{REF,BUF}$	Reference buffer output voltage	SD16REFON = 1, SD16VMIDON = 1	3 V		1.2		V
$I_{REF,BUF}$	Reference supply + reference output buffer quiescent current	SD16REFON = 1, SD16VMIDON = 1	3 V		385	600	μA
$C_{REF(O)}$	Required load capacitance on V_{REF}	SD16REFON = 1, SD16VMIDON = 1		470			nF
$I_{LOAD,Max}$	Maximum load current on V_{REF}	SD16REFON = 1, SD16VMIDON = 1	3 V			±1	mA
	Maximum voltage variation vs load current	$\|I_{LOAD}\|$ = 0 to 1mA	3 V	–15		+15	mV
t_{ON}	Turn-on time	SD16REFON = 0->1, SD16VMIDON = 0->1, C_{REF} = 470nF	3 V		100		μs

SD16_A, external reference input

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
$V_{REF(I)}$	Input voltage range	SD16REFON = 0	3 V	1.0	1.25	1.5	V
$I_{REF(I)}$	Input current	SD16REFON = 0	3 V			50	nA

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (continued)

flash memory

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
$V_{CC(PGM/ERASE)}$	Program and erase supply voltage			2.2		3.6	V
f_{FTG}	Flash timing generator frequency			257		476	kHz
I_{PGM}	Supply current from V_{CC} during program		2.2 V/3.6 V		3	5	mA
I_{ERASE}	Supply current from V_{CC} during erase		2.2 V/3.6 V		3	7	mA
t_{CPT}	Cumulative program time (see Note 1)		2.2 V/3.6 V			10	ms
$t_{CMErase}$	Cumulative mass erase time		2.2 V/3.6 V	20			ms
	Program/Erase endurance			10^4	10^5		cycles
$t_{Retention}$	Data retention duration	T_J = 25°C		100			years
t_{Word}	Word or byte program time	see Note 2			30		t_{FTG}
$t_{Block, 0}$	Block program time for 1st byte or word				25		t_{FTG}
$t_{Block, 1-63}$	Block program time for each additional byte or word				18		t_{FTG}
$t_{Block, End}$	Block program end-sequence wait time				6		t_{FTG}
$t_{Mass Erase}$	Mass erase time				10593		t_{FTG}
$t_{Seg Erase}$	Segment erase time				4819		t_{FTG}
$f_{MCLK,MGR}$	MCLK frequency in marginal read mode (FCTL4.MGR0 = 1 or FCTL4.MGR1 = 1)			0		1	MHz

NOTES: 1. The cumulative program time must not be exceeded when writing to a 64-byte flash block. This parameter applies to all programming methods: individual word/byte write and block write modes.
2. These values are hardwired into the Flash Controller's state machine ($t_{FTG} = 1/f_{FTG}$).

RAM

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
$V_{(RAMh)}$	RAM retention supply voltage (see Note 1)	CPU halted	1.6		V

NOTE 1: This parameter defines the minimum supply voltage V_{CC} when the data in RAM remains unchanged. No program execution should happen during this supply voltage condition.

JTAG interface

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
f_{TCK}	TCK input frequency	See Note 1	2.2 V	0		5	MHz
			3 V	0		10	MHz
$R_{Internal}$	Internal pullup resistance on TMS, TCK, TDI/TCLK	See Note 2	2.2 V/ 3 V	25	40	90	kΩ

NOTES: 1. f_{TCK} may be restricted to meet the timing requirements of the module selected.
2. TMS, TDI/TCLK, and TCK pull-up resistors are implemented in all versions.

JTAG fuse (see Note 1)

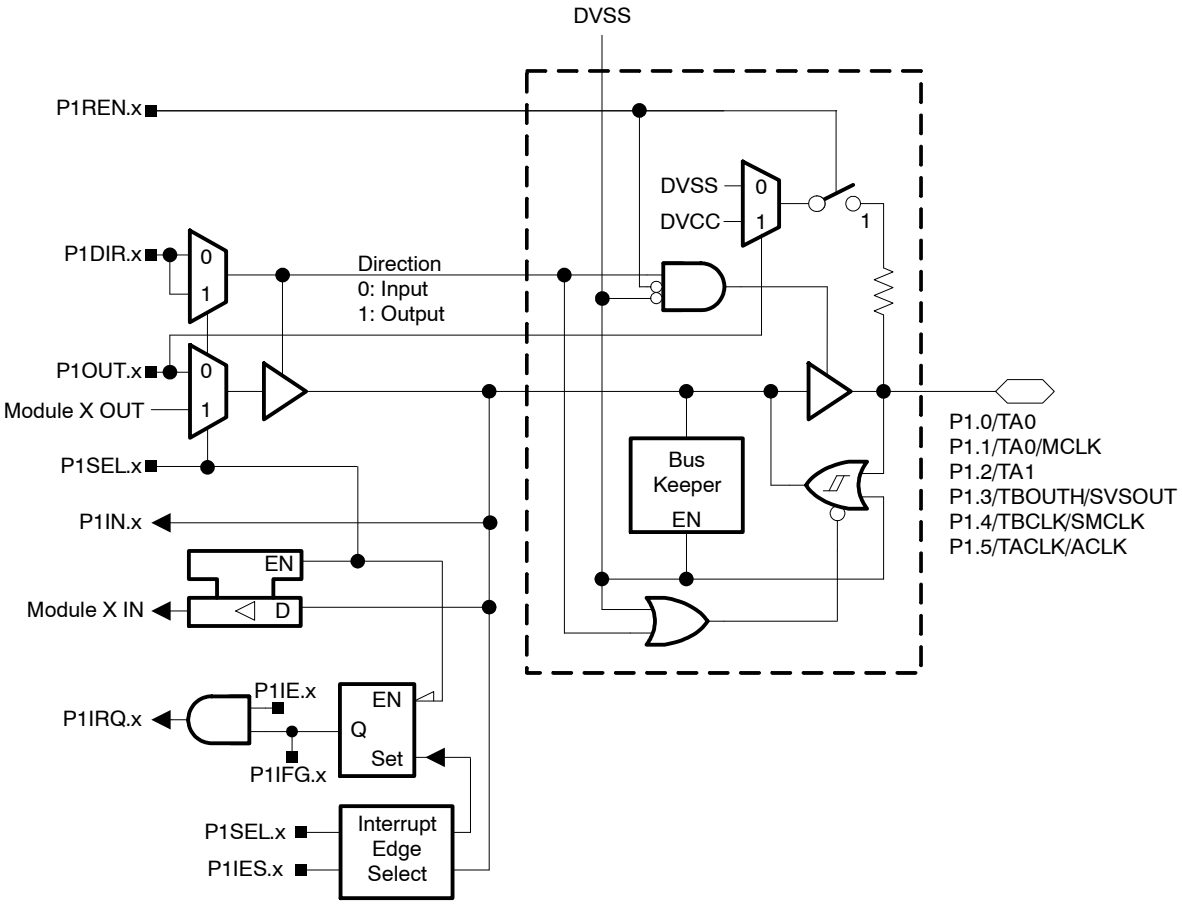
PARAMETER		TEST CONDITIONS	V_{CC}	MIN	NOM	MAX	UNIT
$V_{CC(FB)}$	Supply voltage during fuse-blow condition	T_A = 25°C		2.5			V
V_{FB}	Voltage level on TDI/TCLK for fuse-blow: F versions			6		7	V
I_{FB}	Supply current into TDI/TCLK during fuse blow					100	mA
t_{FB}	Time to blow fuse					1	ms

NOTES: 1. Once the fuse is blown, no further access to the MSP430 JTAG/test and emulation features is possible. The JTAG block is switched to bypass mode.

APPLICATION INFORMATION

input/output schematics

Port P1, P1.0 to P1.5, input/output with Schmitt trigger

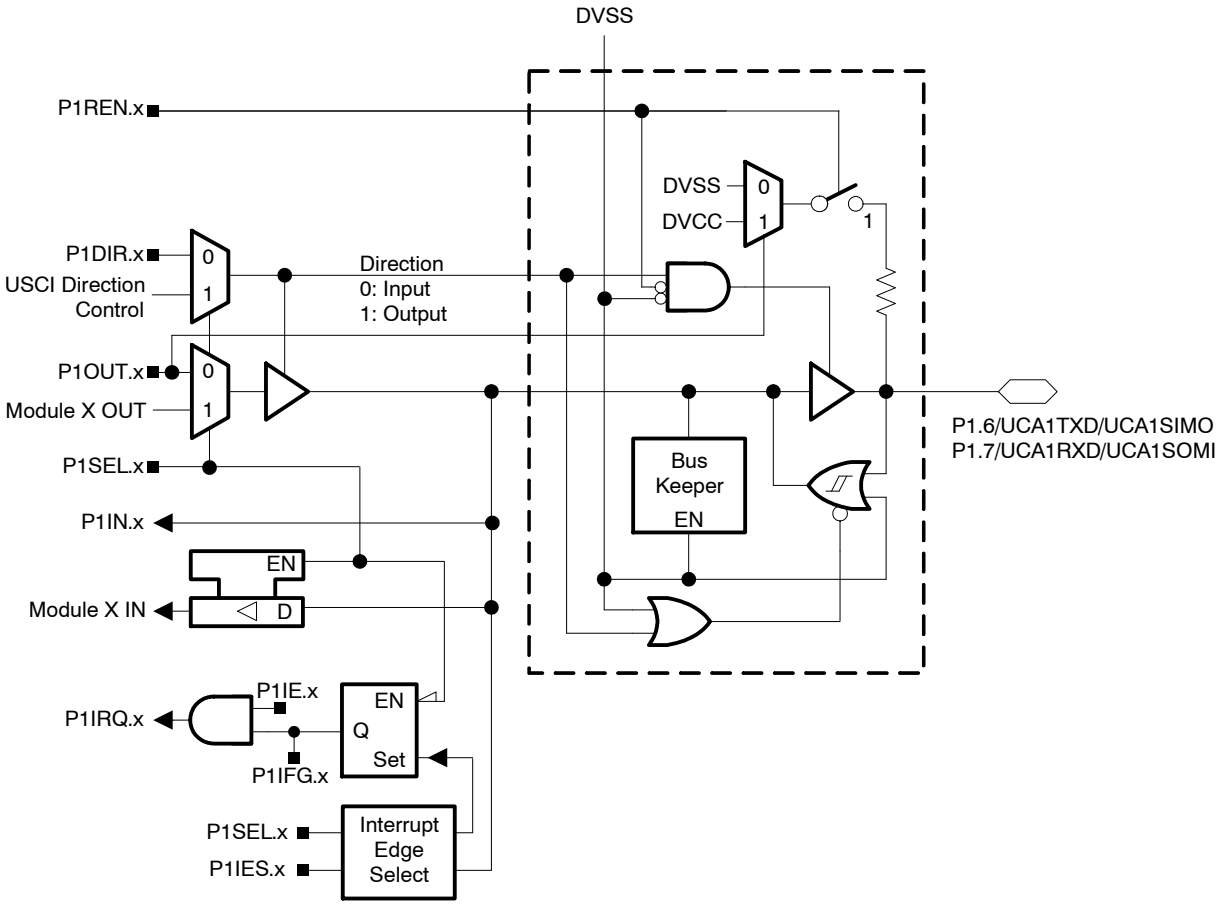


Port P1 (P1.0 to P1.5) pin functions

PIN NAME (P1.X)	X	FUNCTION	CONTROL BITS / SIGNALS	
			P1DIR.x	P1SEL.x
P1.0/TA0	0	P1.0 (I/O)	I: 0, O: 1	0
		Timer_A3.CCI0A	0	1
		Timer_A3.TA0	1	1
P1.1/TA0/MCLK	1	P1.1 (I/O)	I: 0, O: 1	0
		Timer_A3.CCI0B	0	1
		MCLK	1	1
P1.2/TA1	2	P1.2 (I/O)	I: 0, O: 1	0
		Timer_A3.CCI1A	0	1
		Timer_A3.TA1	1	1
P1.3/ TBOUTH/SVSOUT	3	P1.3 (I/O)	I: 0, O: 1	0
		Timer_B7.TBOUTH	0	1
		SVSOUT	1	1
P1.4/TBCLK/SMCLK	4	P1.4 (I/O)	I: 0, O: 1	0
		Timer_B7.TBCLK	0	1
		SMCLK	1	1
P1.5/TACLK/ACLK	5	P1.5 (I/O)	I: 0, O: 1	0
		Timer_A3.TACLK	0	1
		ACLK	1	1

NOTES: 1. X: Don’t care

Port P1, P1.6 and P1.7, input/output with Schmitt trigger

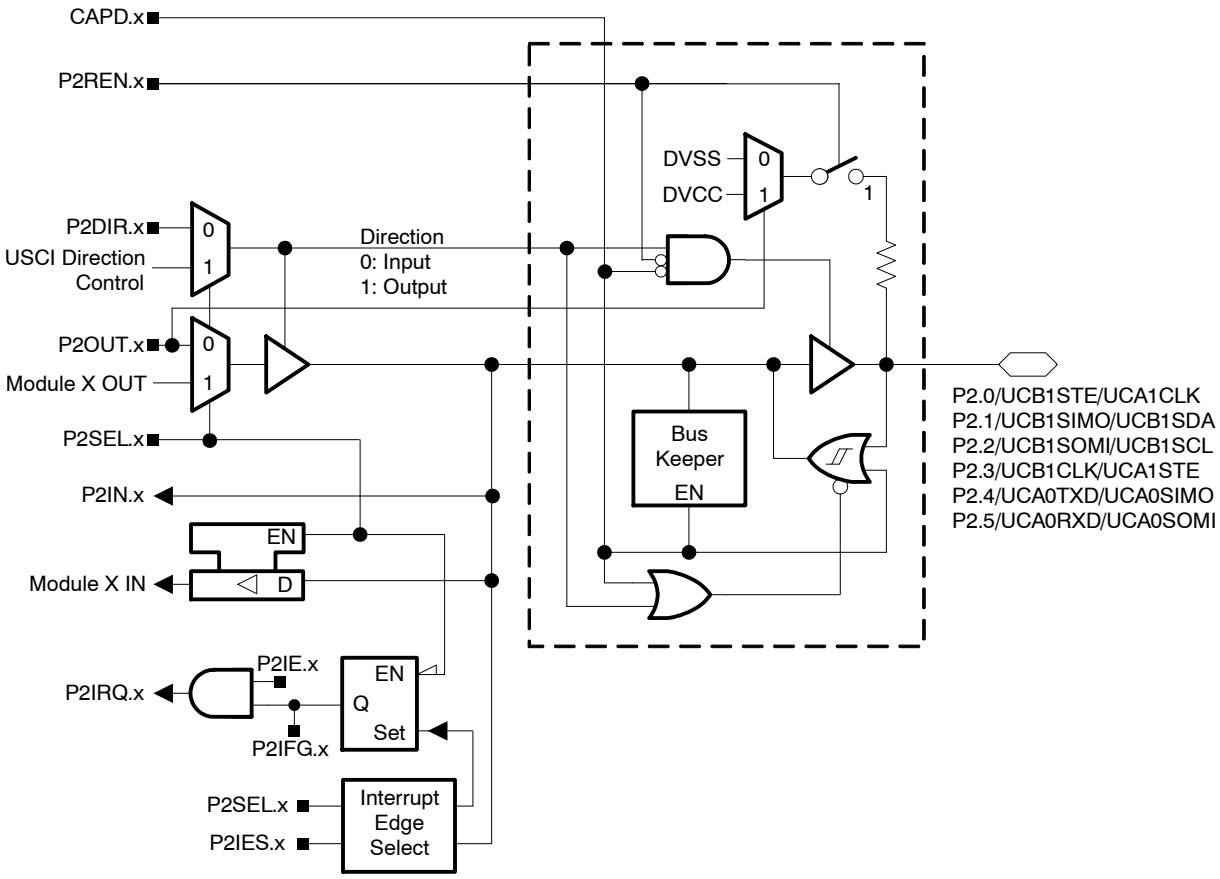


Port P1 (P1.6 and P1.7) pin functions

PIN NAME (P1.X)	X	FUNCTION	CONTROL BITS / SIGNALS	
			P1DIR.x	P1SEL.x
P1.6/ UCA1TXD/UCA1SIMO	4	P1.6 (I/O)	I: 0, O: 1	0
		UCA1TXD/UCA1SIMO (see Note 1, 2)	X	1
P1.7/ UCA1RXD/UCA1SOMI	5	P1.7 (I/O)	I: 0, O: 1	0
		UCA1RXD/UCA1SOMI (see Note 1, 2)	X	1

NOTES: 1. X: Don't care
2. The pin direction is controlled by the USCI module.

Port P2, P2.0 to P2.5, input/output with Schmitt trigger

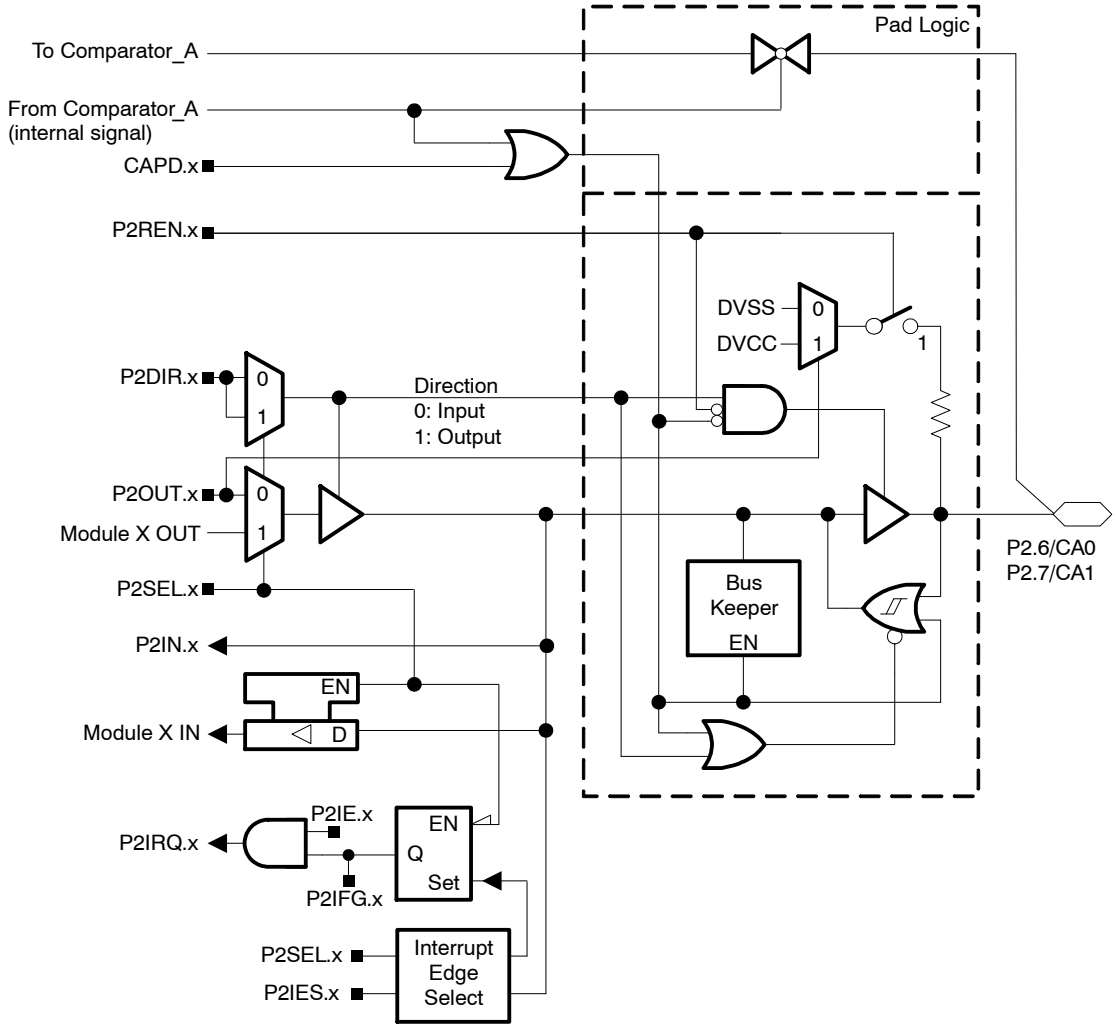


Port P2 (P2.0 to P2.5) pin functions

PIN NAME (P2.X)	X	FUNCTION	CONTROL BITS / SIGNALS		
			P2DIR.x	P2SEL.x	CAPD.x
P2.0/ UCB1STE/UCA1CLK	4	P2.0 (I/O)	I: 0, O: 1	0	0
		UCB1STE/UCA1CLK (see Note 1, 2, 3)	X	1	0
		Input buffer disabled (see Note 6)	X	X	1
P2.1/ UCB1SIMO/UCB1SDA	4	P2.1 (I/O)	I: 0, O: 1	0	0
		UCB1SIMO/UCB1SDA (see Note 1, 2, 4)	X	1	0
		Input buffer disabled (see Note 6)	X	X	1
P2.2/ UCB1SOMI/UCB1SCL	4	P2.2 (I/O)	I: 0, O: 1	0	0
		UCB1SOMI/UCB1SCL (see Note 1, 2, 4)	X	1	0
		Input buffer disabled (see Note 6)	X	X	1
P2.3/ UCB1CLK/UCA1STE	4	P2.3 (I/O)	I: 0, O: 1	0	0
		UCB1CLK/UCA1STE (see Note 1, 2, 5)	X	1	0
		Input buffer disabled (see Note 6)	X	X	1
P2.4/ UCA0TXD/UCA0SIMO	4	P2.4 (I/O)	I: 0, O: 1	0	0
		UCA0TXD/UCA0SIMO (see Note 1, 2)	X	1	0
		Input buffer disabled (see Note 6)	X	X	1
P2.5/ UCA0RXD/UCA0SOMI	5	P2.5 (I/O)	I: 0, O: 1	0	0
		UCA0RXD/UCA0SOMI (see Note 1, 2)	X	1	0
		Input buffer disabled (see Note 6)	X	X	1

NOTES:
1. X: Don't care
2. The pin direction is controlled by the USCI module.
3. UCA1CLK function takes precedence over UCB1STE function. If the pin is required as UCA1CLK input or output USCI_B1 will be forced to 3-wire SPI mode even if 4-wire SPI mode is selected.
4. In case the I2C functionality is selected the output drives only the logical 0 to V_{SS} level.
5. UCB1CLK function takes precedence over UCA1STE function. If the pin is required as UCB1CLK input or output USCI_A1 will be forced to 3-wire SPI mode even if 4-wire SPI mode is selected.
6. Setting the CAPD.x bit disables the output driver as well as the input schmitt trigger to prevent parasitic cross currents when applying analog signals.

Port P2, P2.6 and P2.7, input/output with Schmitt trigger

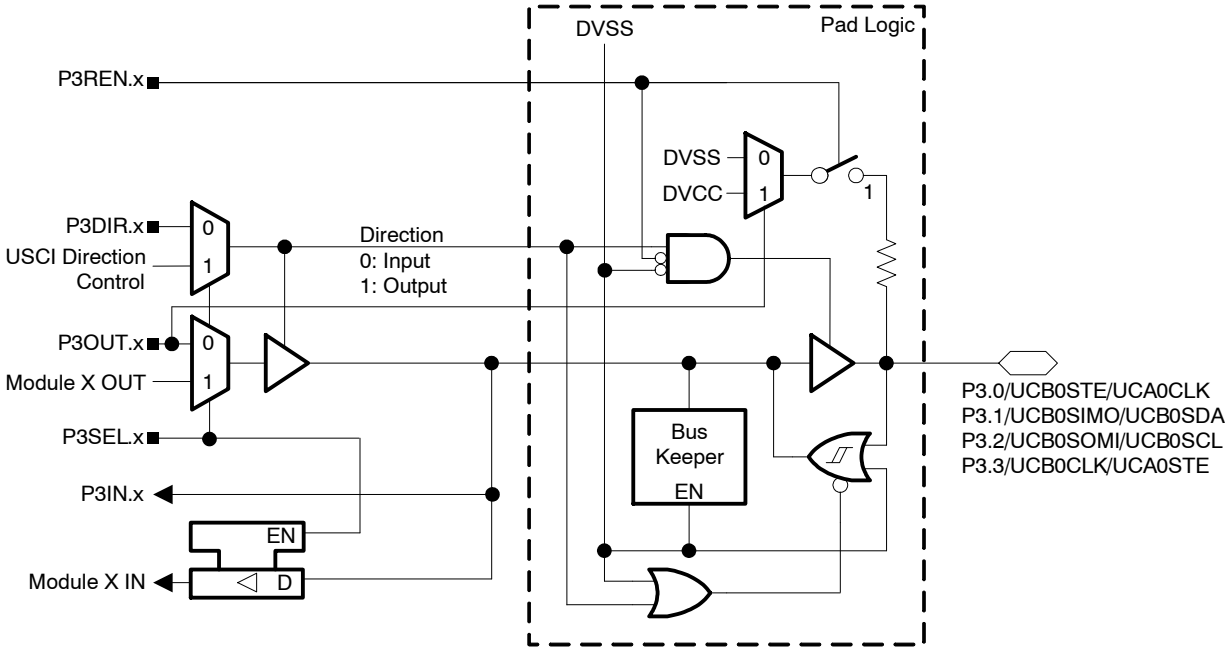


Port P2 (P2.6 and P2.7) pin functions

PIN NAME (P2.X)	X	FUNCTION	CONTROL BITS / SIGNALS		
			P2DIR.x	P2SEL.x	CAPD.x
P2.6/CA0	6	P2.6 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		CA0 (see Note 3)	X	X	1
P2.7/CA1	7	P2.7 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		CA1 (see Note 3)	X	X	1

NOTES: 1. X: Don't care
2. N/A: Not available or not applicable.
3. Setting the CAPD.x bit disables the output driver as well as the input schmitt trigger to prevent parasitic cross currents when applying analog signals.

Port P3, P3.0 to P3.3, input/output with Schmitt trigger

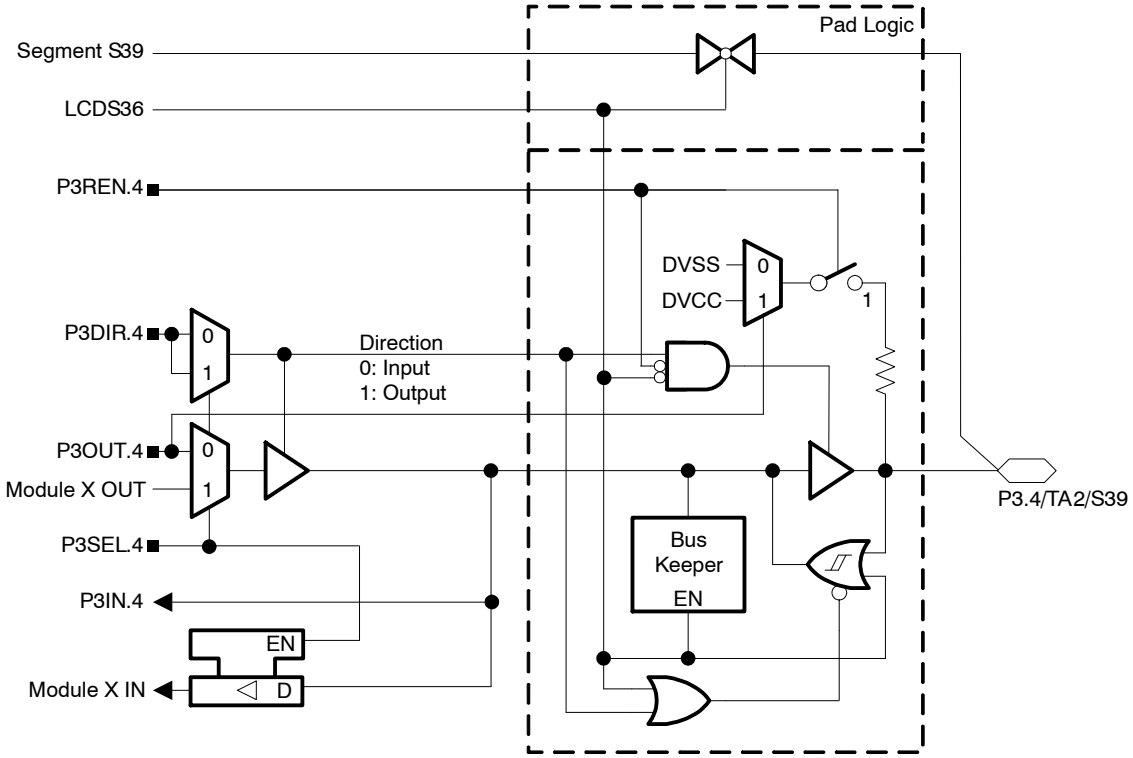


Port P3 (P3.0 to P3.3) pin functions

PIN NAME (P3.X)	X	FUNCTION	CONTROL BITS / SIGNALS	
			P3DIR.x	P3SEL.x
P3.0/ UCA0CLK/UCB0STE	0	P3.0 (I/O)	I: 0, O: 1	0
		UCA0CLK/UCB0STE (see Notes 1, 2, 3)	X	1
P3.1/ UCB0SIMO/ UCB0SDA	1	P3.1 (I/O)	I: 0, O: 1	0
		UCB0SIMO/UCB0SDA (see Notes 1, 2, 4)	X	1
P3.2/ UCB0SOMI/ UCB0SCL	2	P3.2 (I/O)	I: 0, O: 1	0
		UCB0SOMI/UCB0SCL (see Notes 1, 2, 4)	X	1
P3.3/ UCB0CLK/UCA0STE	3	P3.3 (I/O)	I: 0, O: 1	0
		UCB0CLK/UCA0STE (see Notes 1, 2, 5)	X	1

NOTES: 1. X: Don't care
2. The pin direction is controlled by the USCI module.
3. UCA0CLK function takes precedence over UCB0STE function. If the pin is required as UCA0CLK input or output USCI_B0 will be forced to 3-wire SPI mode even if 4-wire SPI mode is selected.
4. In case the I2C functionality is selected the output drives only the logical 0 to V_{SS} level.
5. UCB0CLK function takes precedence over UCA0STE function. If the pin is required as UCB0CLK input or output USCI_A0 will be forced to 3-wire SPI mode even if 4-wire SPI mode is selected.

Port P3, P3.4, input/output with Schmitt trigger

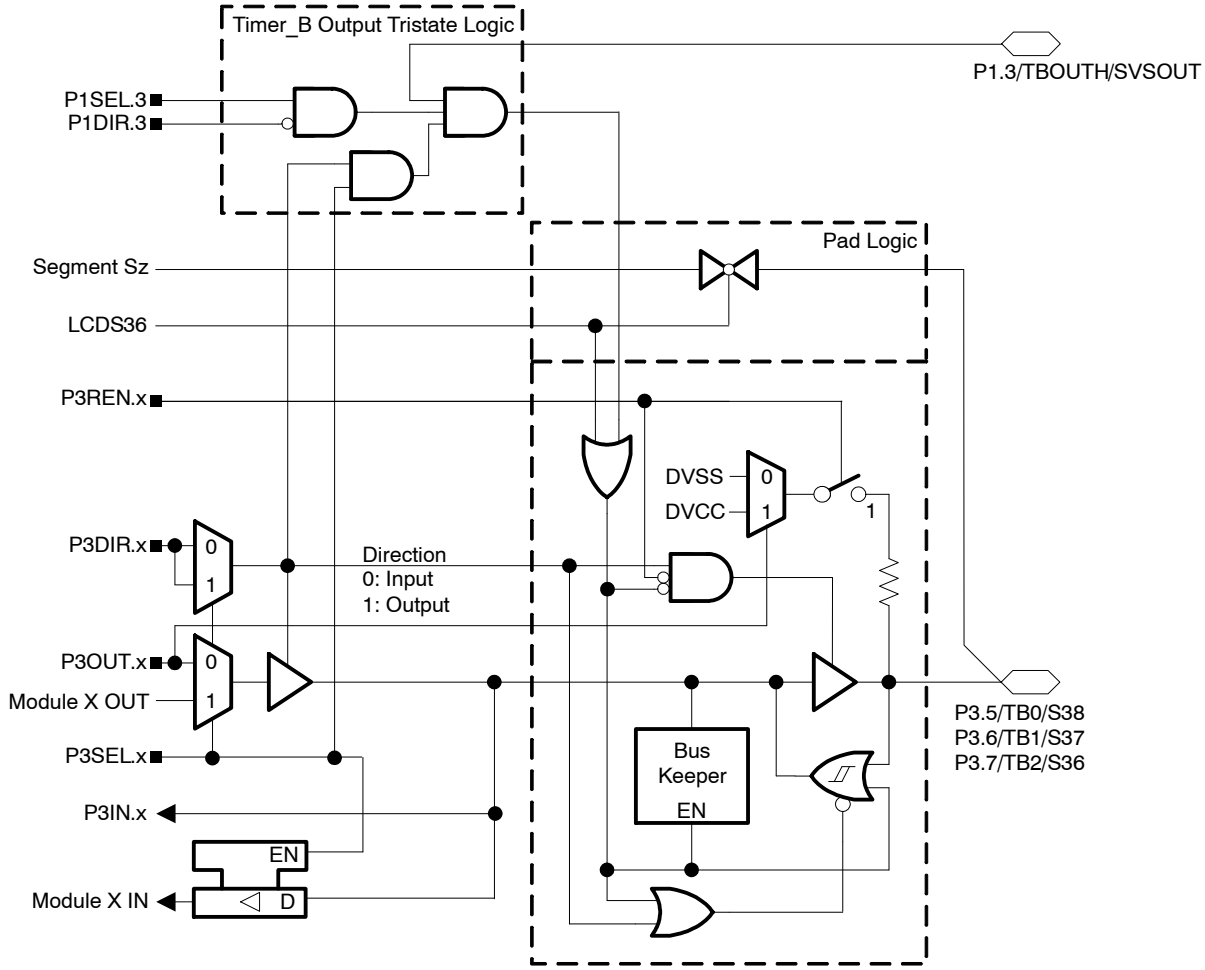


Port P3 (P3.4) pin functions

PIN NAME (P3.X)	X	FUNCTION	CONTROL BITS / SIGNALS		
			P3DIR.x	P3SEL.x	LCDS36
P3.4/TA2/S39	4	P3.4 (I/O)	I: 0, O: 1	0	0
		Timer_A3.CCI2A	0	1	0
		Timer_A3.TA2	1	1	0
		S39	X	X	1

NOTES: 1. X: Don't care

Port P3, P3.5 to P3.7, input/output with Schmitt trigger

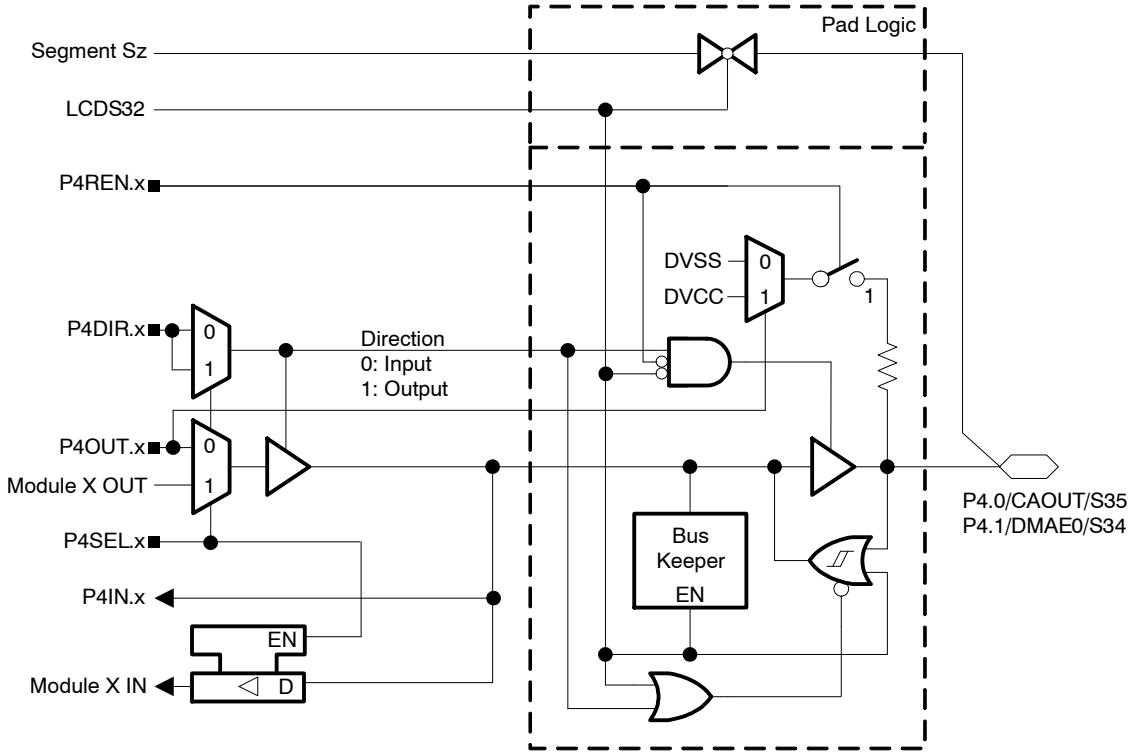


Port P3 (P3.5 to P3.7) pin functions

PIN NAME (P3.X)	X	FUNCTION	CONTROL BITS / SIGNALS		
			P3DIR.x	P3SEL.x	LCDS36
P3.5/TB0/S38	5	P3.5 (I/O)	I: 0, O: 1	0	0
		Timer_B3.CCI0A and Timer_B3.CCI0B	0	1	0
		Timer_B3.TB0 (see Note 2)	1	1	0
		S38	X	X	1
P3.6/TB1/S37	6	P3.6 (I/O)	I: 0, O: 1	0	0
		Timer_B3.CCI1A and Timer_B3.CCI1B	0	1	0
		Timer_B3.TB1 (see Note 2)	1	1	0
		S37	X	X	1
P3.7/TB2/S36	7	P3.7 (I/O)	I: 0, O: 1	0	0
		Timer_B3.CCI2A and Timer_B3.CCI2B	0	1	0
		Timer_B3.TB3 (see Note 2)	1	1	0
		S36	X	X	1

NOTES: 1. X: Don't care
2. Setting TBOUTH causes all Timer_B outputs to be set to high impedance.

Port P4, P4.0 and P4.1, input/output with Schmitt trigger

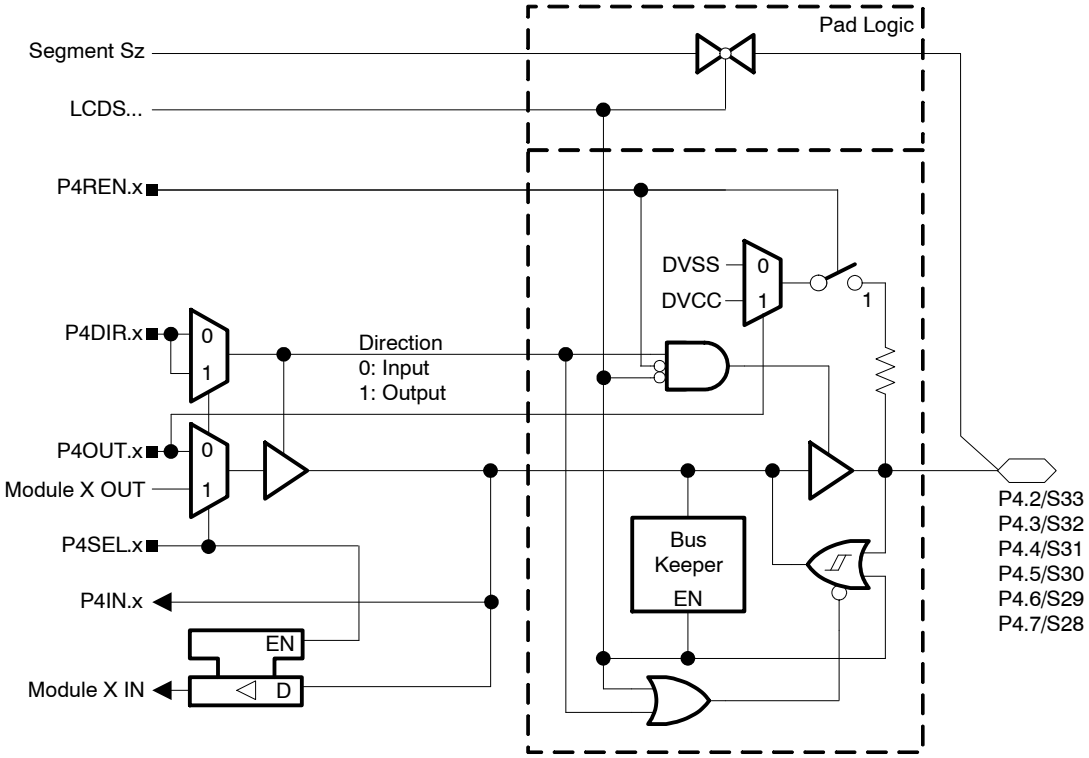


Port P4 (P4.0 and P4.1) pin functions

PIN NAME (P4.X)	X	FUNCTION	CONTROL BITS / SIGNALS		
			P4DIR.x	P4SEL.x	LCDS32
P4.0/CAOUT/S35	0	P4.0 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		CAOUT	1	1	0
		S35	X	X	1
P4.1/DMAE0/S34	1	P4.1 (I/O)	I: 0, O: 1	0	0
		DMAE0	0	1	0
		DVSS	1	1	0
		S34	X	X	1

NOTES: 1. X: Don't care
2. N/A: Not available or not applicable.

Port P4, P4.2 to P4.7, input/output with Schmitt trigger



Port P4 (P4.2 and P4.3) pin functions

PIN NAME (P4.X)	X	FUNCTION	CONTROL BITS / SIGNALS		
			P4DIR.x	P4SEL.x	LCDS32
P4.2/S33	2	P4.2 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S33	X	X	1
P4.3/S32	3	P4.3 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S32	X	X	1

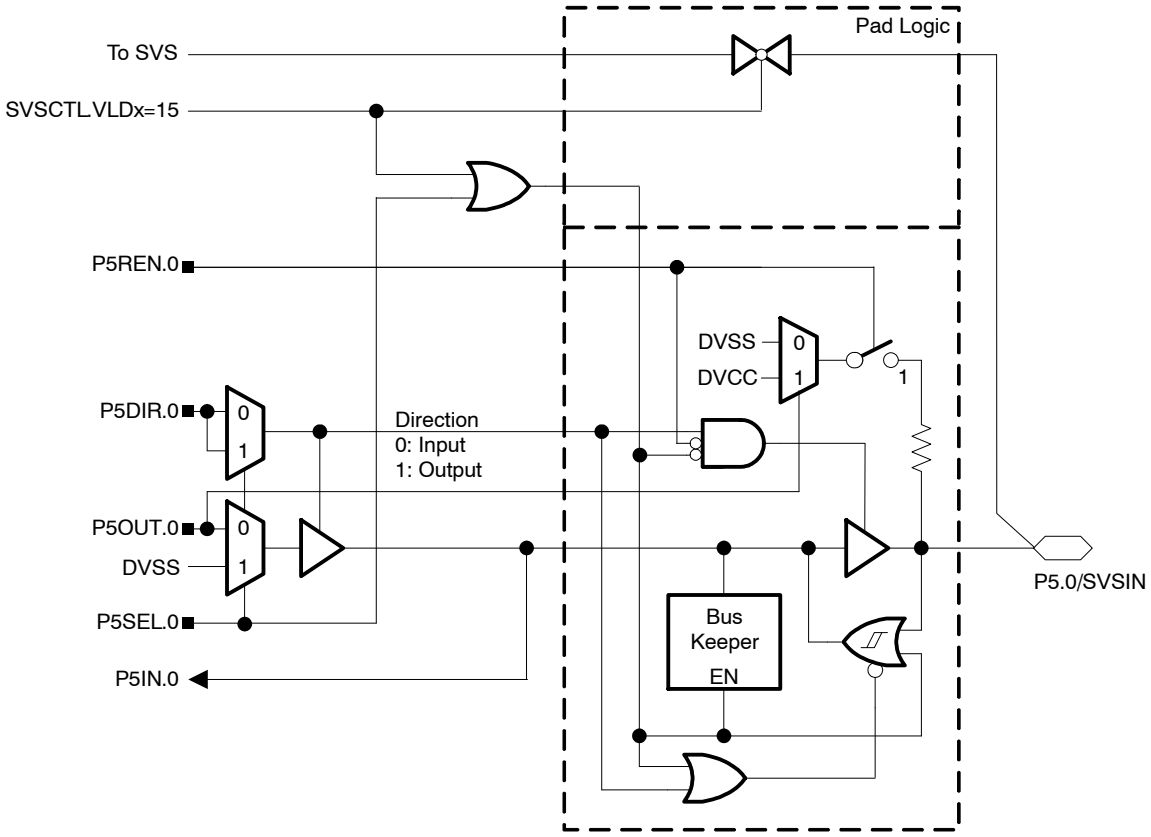
NOTES: 1. X: Don't care
2. N/A: Not available or not applicable.

Port P4 (P4.4 to P4.7) pin functions

PIN NAME (P4.X)	X	FUNCTION	CONTROL BITS / SIGNALS		
			P4DIR.x	P4SEL.x	LCDS28
P4.4/S31	4	P4.4 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S31	X	X	1
P4.5/S30	5	P4.5 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S30	X	X	1
P4.6/S29	5	P4.6 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S29	X	X	1
P4.7/S28	5	P4.7 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S28	X	X	1

NOTES: 1. X: Don't care
2. N/A: Not available or not applicable.

Port P5, P5.0, input/output with Schmitt trigger

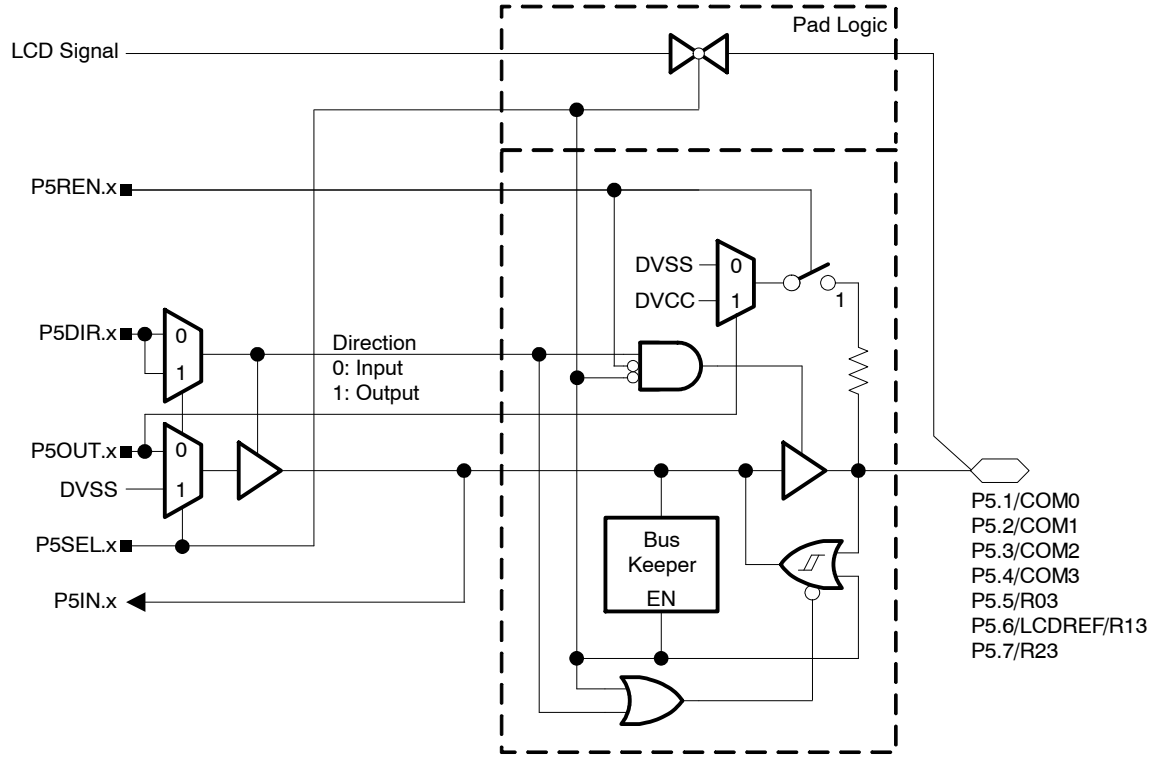


Port P5 (P5.0) pin functions

PIN NAME (P5.X)	X	FUNCTION	CONTROL BITS / SIGNALS	
			P5DIR.x	P5SEL.x
P5.0/SVSIN	0	P5.0 (I/O) (see Note 1)	I: 0, O: 1	0
		SVSIN (see Notes 1 and 3)	X	1

NOTES: 1. X: Don't care
2. N/A: Not available or not applicable.
3. Setting the P5SEL.x bit disables the output driver as well as the input Schmitt trigger to prevent parasitic cross currents when applying analog signals. To enable the SVSIN function the SVS input also needs to be selected in the SVS module by setting the VLDx bits to 15.

Port P5, P5.1 to P5.7, input/output with Schmitt trigger

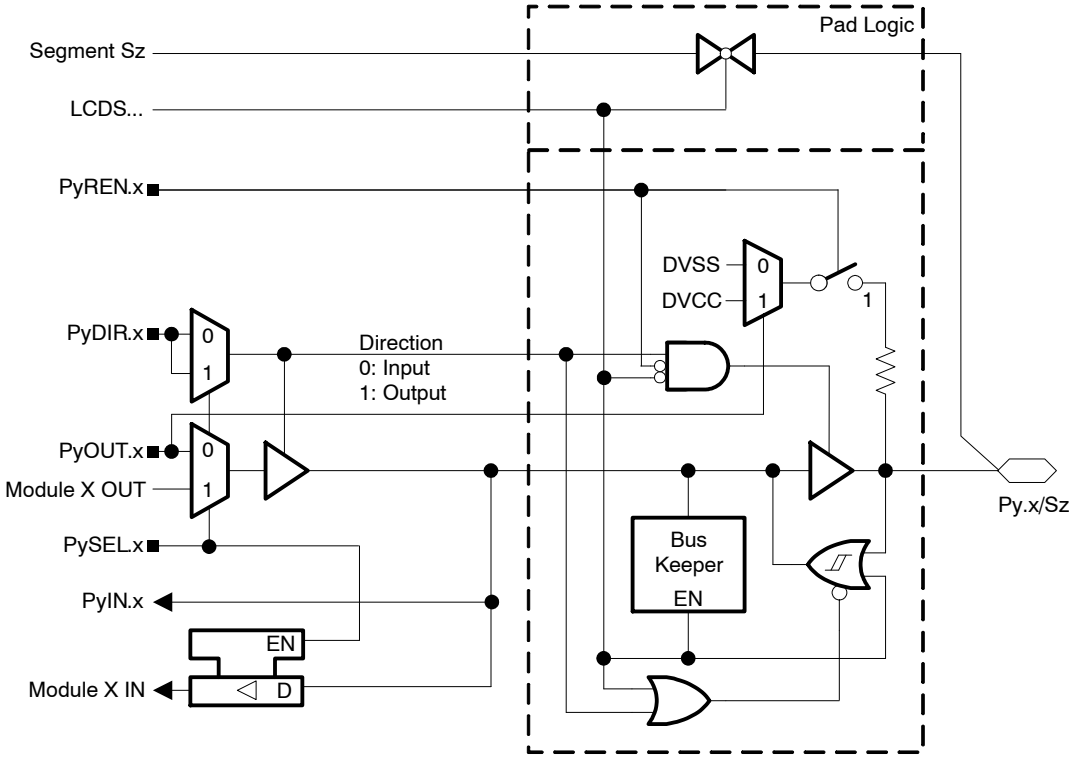


Port P5 (P5.1 to P5.7) pin functions

PIN NAME (P5.X)	X	FUNCTION	CONTROL BITS / SIGNALS	
			P5DIR.x	P5SEL.x
P5.1/COM0	2	P5.1 (I/O)	I: 0, O: 1	0
		COM0 (see Note 2)	X	1
P5.2/COM1	2	P5.2 (I/O)	I: 0, O: 1	0
		COM1 (see Note 2)	X	1
P5.3/COM2	3	P5.3 (I/O)	I: 0, O: 1	0
		COM2 (see Note 2)	X	1
P5.4/COM3	4	P5.4 (I/O)	I: 0, O: 1	0
		COM3 (see Note 2)	X	1
P5.5/R03	5	P5.5 (I/O)	I: 0, O: 1	0
		R03 (see Note 2)	X	1
P5.6/LCDREF/R13	6	P5.6 (I/O)	I: 0, O: 1	0
		R13 or LCDREF (see Notes 2 and 3)	X	1
P5.7/R23	7	P5.7 (I/O)	I: 0, O: 1	0
		R23 (see Note 2)	X	1

NOTES: 1. X: Don't care
2. Setting the P5SEL.x bit disables the output driver as well as the input Schmitt trigger to prevent parasitic cross currents when applying analog signals.
3. External reference for the LCD_A charge pump is applied when VLCDREFx = 01. Otherwise R13 is selected.

Port P7 to port P10, input/output with Schmitt trigger



Port P7 (P7.0 to P7.3) pin functions

PIN NAME (P7.X)	X	FUNCTION	CONTROL BITS / SIGNALS		
			P7DIR.x	P7SEL.x	LCDS24
P7.0/S27	0	P7.0 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S27	X	X	1
P7.1/S26	1	P7.1 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S26	X	X	1
P7.2/S25	2	P7.2 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S25	X	X	1
P7.3/S24	3	P7.3 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S24	X	X	1

NOTES: 1. X: Don't care
2. N/A: Not available or not applicable.

Port P7 (P7.4 to P7.7) pin functions

PIN NAME (P7.X)	X	FUNCTION	CONTROL BITS / SIGNALS		
			P7DIR.x	P7SEL.x	LCDS20
P7.4/S23	4	P7.4 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S23	X	X	1
P7.5/S22	5	P7.5 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S22	X	X	1
P7.6/S21	6	P7.6 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S21	X	X	1
P7.7/S20	7	P7.7 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S20	X	X	1

NOTES: 1. X: Don't care
2. N/A: Not available or not applicable.

Port P8 (P8.0 to P8.3) pin functions

PIN NAME (P8.X)	X	FUNCTION	CONTROL BITS / SIGNALS		
			P8DIR.x	P8SEL.x	LCDS16
P8.0/S19	0	P8.0 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S19	X	X	1
P8.1/S18	1	P8.0 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S18	X	X	1
P8.2/S17	2	P8.2 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S17	X	X	1
P8.3/S16	3	P8.3 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S16	X	X	1

NOTES: 1. X: Don't care
2. N/A: Not available or not applicable.

Port P8 (P8.4 to P8.7) pin functions

PIN NAME (P8.X)	X	FUNCTION	CONTROL BITS / SIGNALS		
			P8DIR.x	P8SEL.x	LCDS12
P8.4/S15	4	P8.4 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S15	X	X	1
P8.5/S14	5	P8.5 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S14	X	X	1
P8.6/S13	6	P8.6 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S13	X	X	1
P8.7/S12	7	P8.7 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S12	X	X	1

NOTES: 1. X: Don't care
2. N/A: Not available or not applicable.

Port P9 (P9.0 to P9.3) pin functions

PIN NAME (P9.X)	X	FUNCTION	CONTROL BITS / SIGNALS		
			P9DIR.x	P9SEL.x	LCDS8
P9.0/S11	0	P9.0 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S11	X	X	1
P9.1/S10	1	P9.1 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S10	X	X	1
P9.2/S9	2	P9.2 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S9	X	X	1
P9.3/S8	3	P9.3 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S8	X	X	1

NOTES: 1. X: Don't care
2. N/A: Not available or not applicable.

Port P9 (P9.4 to P9.7) pin functions

PIN NAME (P9.X)	X	FUNCTION	CONTROL BITS / SIGNALS		
			P9DIR.x	P9SEL.x	LCDS4
P9.4/S7	4	P9.4 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S7	X	X	1
P9.5/S6	5	P9.5 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S6	X	X	1
P9.6/S5	6	P9.6 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S5	X	X	1
P9.7/S4	7	P9.7 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S4	X	X	1

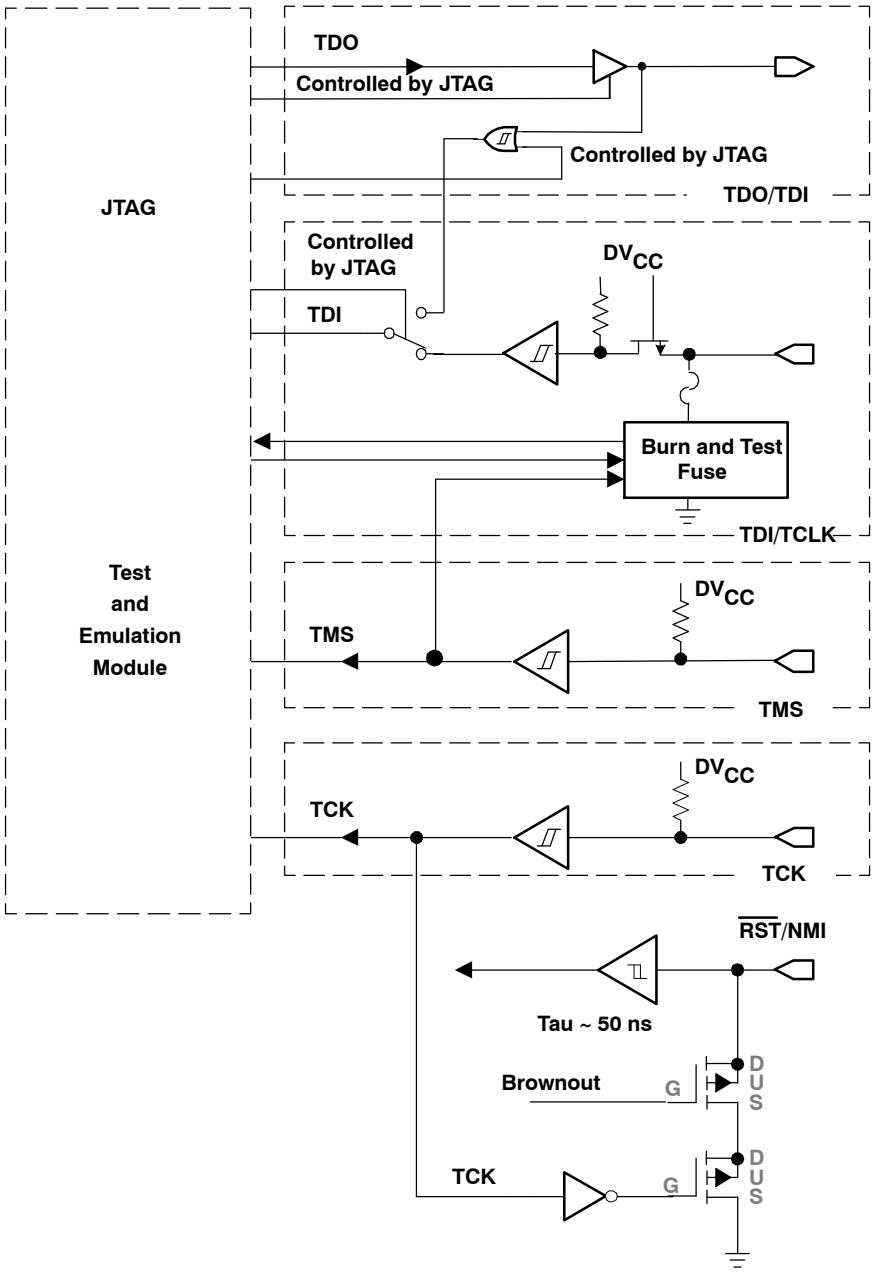
NOTES: 1. X: Don't care
2. N/A: Not available or not applicable.

Port P10 (P10.0 to P10.3) pin functions

PIN NAME (P10.X)	X	FUNCTION	CONTROL BITS / SIGNALS		
			P10DIR.x	P10SEL.x	LCDS0
P10.0/S3	0	P10.0 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S3	X	X	1
P10.1/S2	1	P10.1 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S2	X	X	1
P10.2/S1	2	P10.2 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S1	X	X	1
P10.3/S0	3	P10.3 (I/O)	I: 0, O: 1	0	0
		N/A	0	1	0
		DVSS	1	1	0
		S0	X	X	1

NOTES: 1. X: Don't care
2. N/A: Not available or not applicable.

JTAG pins (TMS, TCK, TDI/TCLK, TDO/TDI), input/output with Schmitt trigger or output



JTAG fuse check mode

MSP430 devices that have the fuse on the TDI/TCLK terminal have a fuse check mode that tests the continuity of the fuse the first time the JTAG port is accessed after a power-on reset (POR). When activated, a fuse check current ($I_{(TF)}$) of 1 mA at 3 V can flow from the TDI/TCLK pin to ground if the fuse is not burned. Care must be taken to avoid accidentally activating the fuse check mode and increasing overall system power consumption.

Activation of the fuse check mode occurs with the first negative edge on the TMS pin after power up or if the TMS is being held low during power up. The second positive edge on the TMS pin deactivates the fuse check mode. After deactivation, the fuse check mode remains inactive until another POR occurs. After each POR the fuse check mode has the potential to be activated.

The fuse check current only flows when the fuse check mode is active and the TMS pin is in a low state (see Figure 27). Therefore, the additional current flow can be prevented by holding the TMS pin high (default condition). The JTAG pins are terminated internally and therefore do not require external termination.

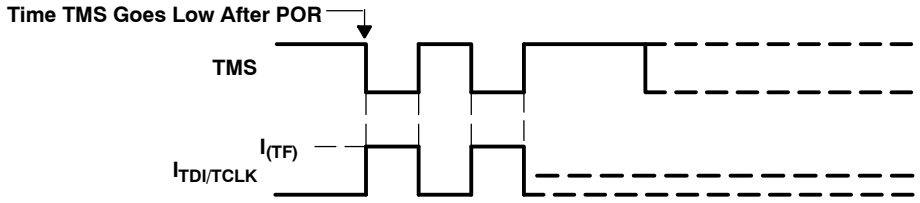


Figure 27. Fuse Check Mode Current MSP430F471x3/6/7

Data Sheet Revision History

LITERATURE NUMBER	SUMMARY
SLAS626	Product Preview release
SLAS626A	Production Data release
SLAS626B	Added MSP430F471x3, MSP430F47126, and MSP430F47127 devices
SLAS626C	Corrected pin numbers in BSL function table (page 16) Changed limits on $t_{d(SVSon)}$ parameter (page 38)

NOTE: Page and figure numbers refer to the respective document revision and may differ in other revisions.

TEXAS INSTRUMENTS
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
MSP430F47126IPZ	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47126
MSP430F47126IPZ.B	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47126
MSP430F47126IPZR	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47126
MSP430F47126IPZR.B	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47126
MSP430F47127IPZ	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47127
MSP430F47127IPZ.B	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47127
MSP430F47127IPZR	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47127
MSP430F47127IPZR.B	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47127
MSP430F47163IPZ	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47163
MSP430F47163IPZ.B	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47163
MSP430F47163IPZR	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47163
MSP430F47163IPZR.B	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47163
MSP430F47166IPZ	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47166 REV #
MSP430F47166IPZ.B	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47166 REV #
MSP430F47166IPZR	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47166 REV #
MSP430F47166IPZR.B	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47166 REV #
MSP430F47167IPZ	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47167 REV #
MSP430F47167IPZ.B	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47167 REV #
MSP430F47167IPZR	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47167 REV #

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
MSP430F47167IPZR.B	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47167 REV #
MSP430F47173IPZ	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47173
MSP430F47173IPZ.B	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47173
MSP430F47173IPZR	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47173
MSP430F47173IPZR.B	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47173
MSP430F47176IPZ	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47176 REV #
MSP430F47176IPZ.B	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47176 REV #
MSP430F47176IPZR	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47176 REV #
MSP430F47176IPZR.B	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47176 REV #
MSP430F47177IPZ	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47177 REV #
MSP430F47177IPZ.B	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47177 REV #
MSP430F47177IPZR	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47177 REV #
MSP430F47177IPZR.B	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47177 REV #
MSP430F47183IPZ	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47183
MSP430F47183IPZ.B	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47183
MSP430F47183IPZR	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47183
MSP430F47183IPZR.B	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47183
MSP430F47186IPZ	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47186 REV #
MSP430F47186IPZ.B	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47186 REV #

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
MSP430F47186IPZR	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47186 REV #
MSP430F47186IPZR.B	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47186 REV #
MSP430F47187IPZ	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47187 REV #
MSP430F47187IPZ.B	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47187 REV #
MSP430F47187IPZR	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47187 REV #
MSP430F47187IPZR.B	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47187 REV #
MSP430F47187IPZRG4	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47187 REV #
MSP430F47187IPZRG4.B	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47187 REV #
MSP430F47193IPZ	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47193
MSP430F47193IPZ.B	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47193
MSP430F47193IPZR	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47193
MSP430F47193IPZR.B	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47193
MSP430F47196IPZ	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47196 REV #
MSP430F47196IPZ.B	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47196 REV #
MSP430F47196IPZR	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47196 REV #
MSP430F47196IPZR.B	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47196 REV #
MSP430F47197IPZ	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47197 REV #
MSP430F47197IPZ.B	Active	Production	LQFP (PZ) | 100	90 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47197 REV #

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
MSP430F47197IPZR	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47197 REV #
MSP430F47197IPZR.B	Active	Production	LQFP (PZ) | 100	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	M430F47197 REV #

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

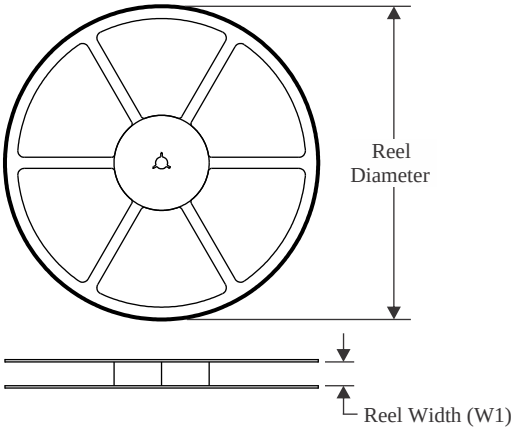
(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

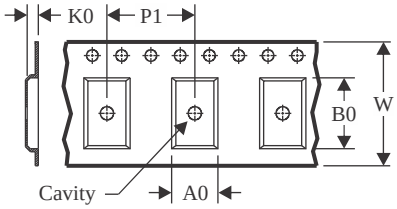
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

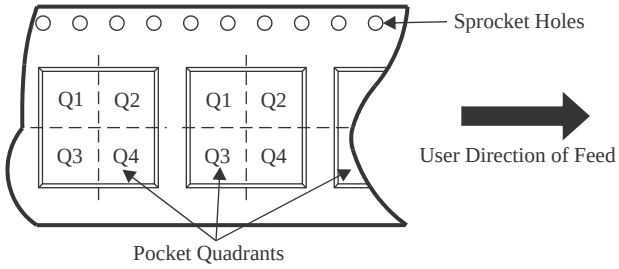


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

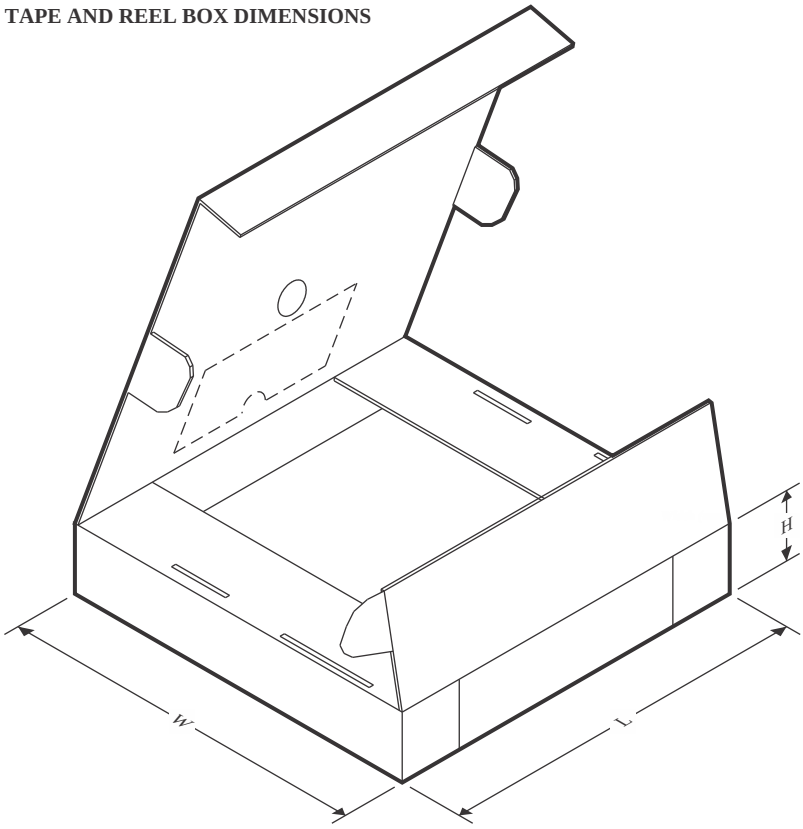
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MSP430F47163IPZR	LQFP	PZ	100	1000	330.0	24.4	17.0	17.0	2.1	20.0	24.0	Q2
MSP430F47173IPZR	LQFP	PZ	100	1000	330.0	24.4	17.0	17.0	2.1	20.0	24.0	Q2
MSP430F47183IPZR	LQFP	PZ	100	1000	330.0	24.4	17.0	17.0	2.1	20.0	24.0	Q2
MSP430F47193IPZR	LQFP	PZ	100	1000	330.0	24.4	17.0	17.0	2.1	20.0	24.0	Q2

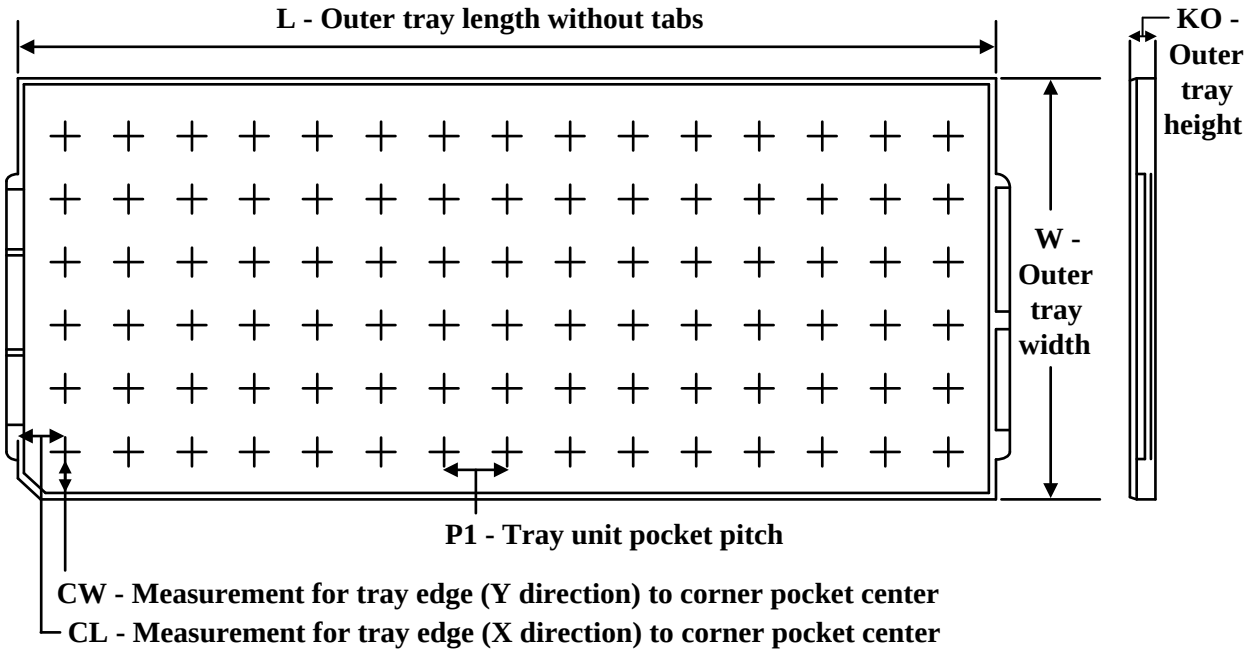
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MSP430F47163IPZR	LQFP	PZ	100	1000	350.0	350.0	43.0
MSP430F47173IPZR	LQFP	PZ	100	1000	350.0	350.0	43.0
MSP430F47183IPZR	LQFP	PZ	100	1000	350.0	350.0	43.0
MSP430F47193IPZR	LQFP	PZ	100	1000	350.0	350.0	43.0

TRAY



Chamfer on Tray corner indicates Pin 1 orientation of packed units.

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	Unit array matrix	Max temperature (°C)	L (mm)	W (mm)	K0 (µm)	P1 (mm)	CL (mm)	CW (mm)
MSP430F47126IPZ	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47126IPZ.B	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47127IPZ	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47127IPZ.B	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47163IPZ	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47163IPZ.B	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47166IPZ	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47166IPZ.B	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47167IPZ	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47167IPZ.B	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47173IPZ	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47173IPZ.B	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47177IPZ	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47177IPZ.B	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47183IPZ	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47183IPZ.B	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47187IPZ	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45

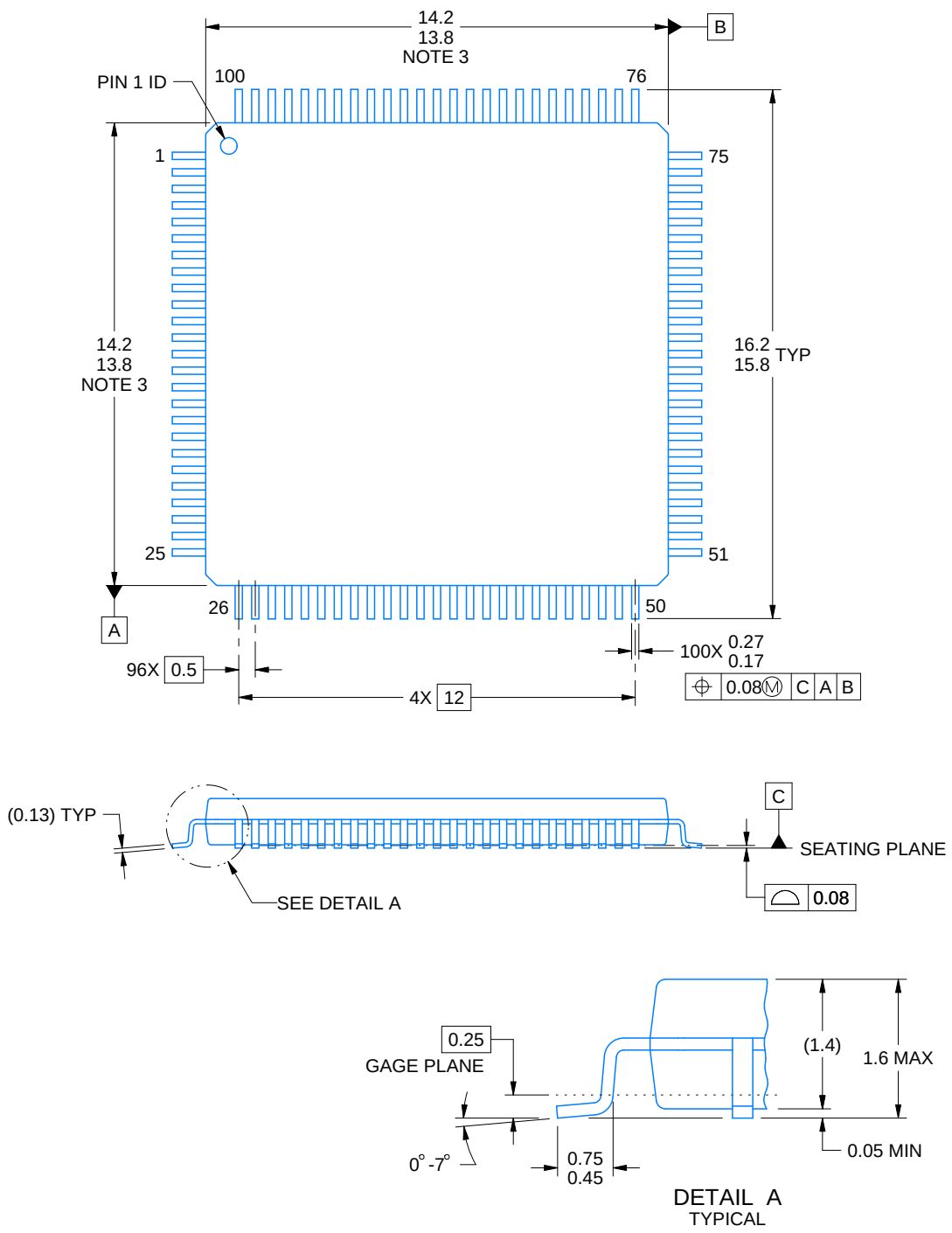
Device	Package Name	Package Type	Pins	SPQ	Unit array matrix	Max temperature (°C)	L (mm)	W (mm)	K0 (µm)	P1 (mm)	CL (mm)	CW (mm)
MSP430F47187IPZ.B	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47193IPZ	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47193IPZ.B	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47197IPZ	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45
MSP430F47197IPZ.B	PZ	LQFP	100	90	6 x 15	150	315	135.9	7620	20.3	15.4	15.45

PACKAGE OUTLINE

PZ0100A

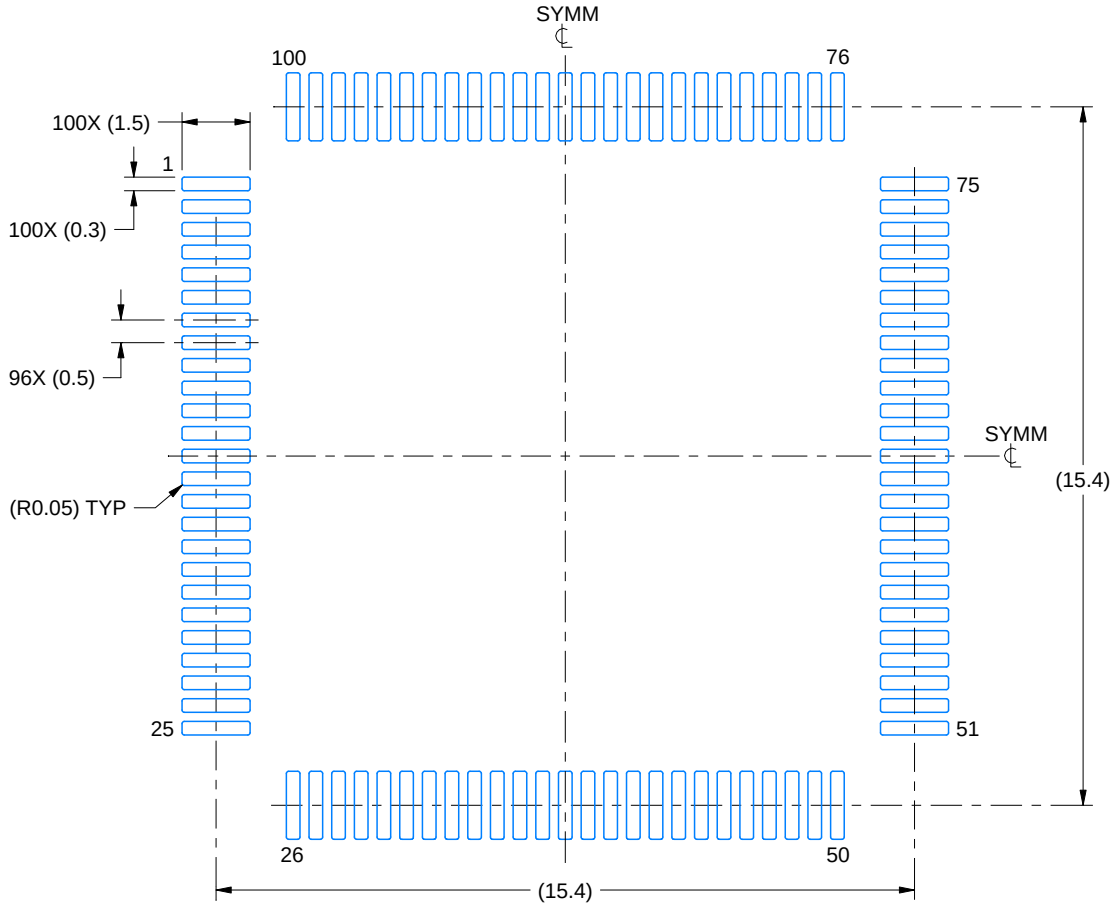
LQFP - 1.6 mm max height

PLASTIC QUAD FLATPACK

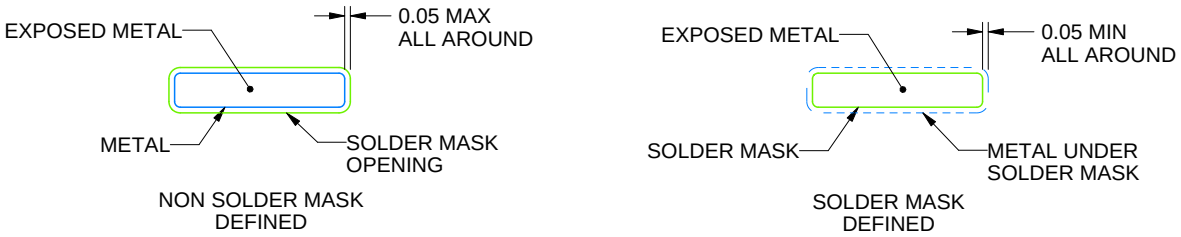


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MS-026.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:6X

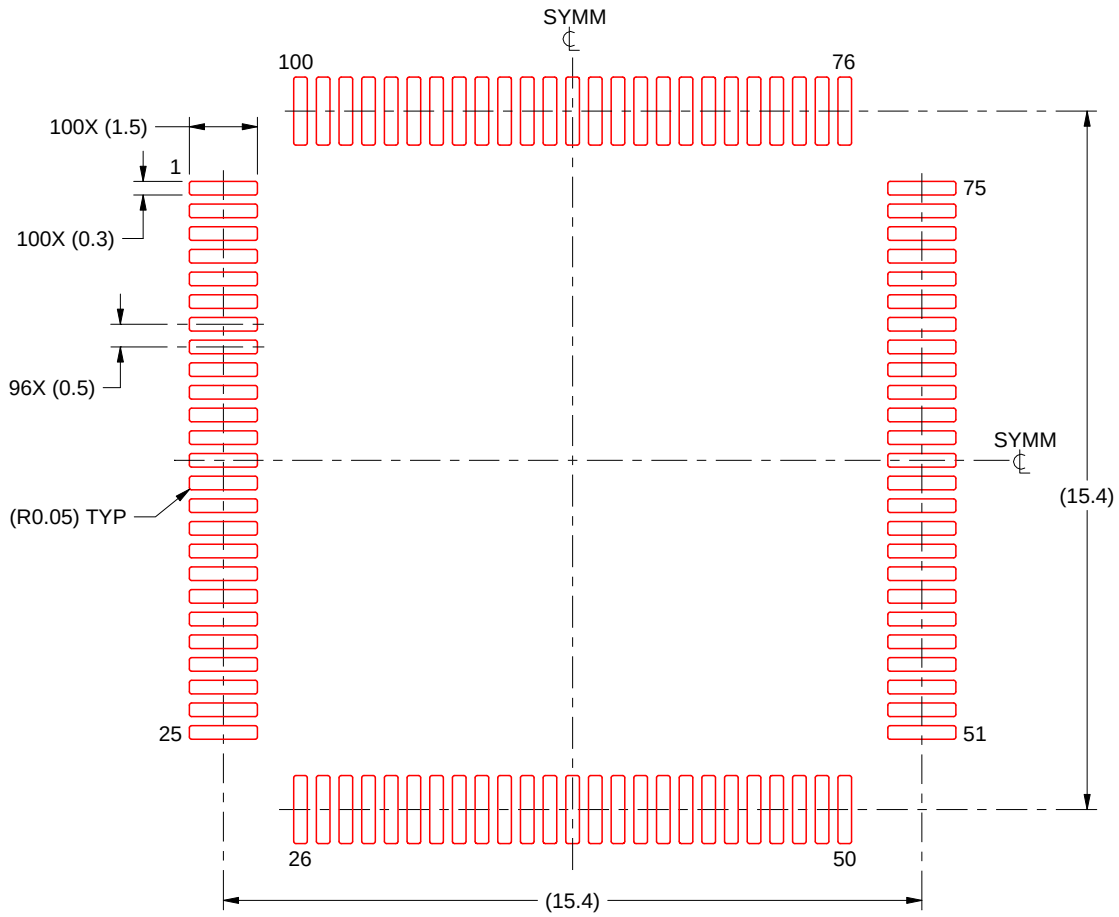


SOLDER MASK DETAILS

4215169/A 03/2017

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
7. For more information, see Texas Instruments literature number SLMA004 (www.ti.com/lit/slma004).



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4215169/A 03/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale, TI’s General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Last updated 10/2025